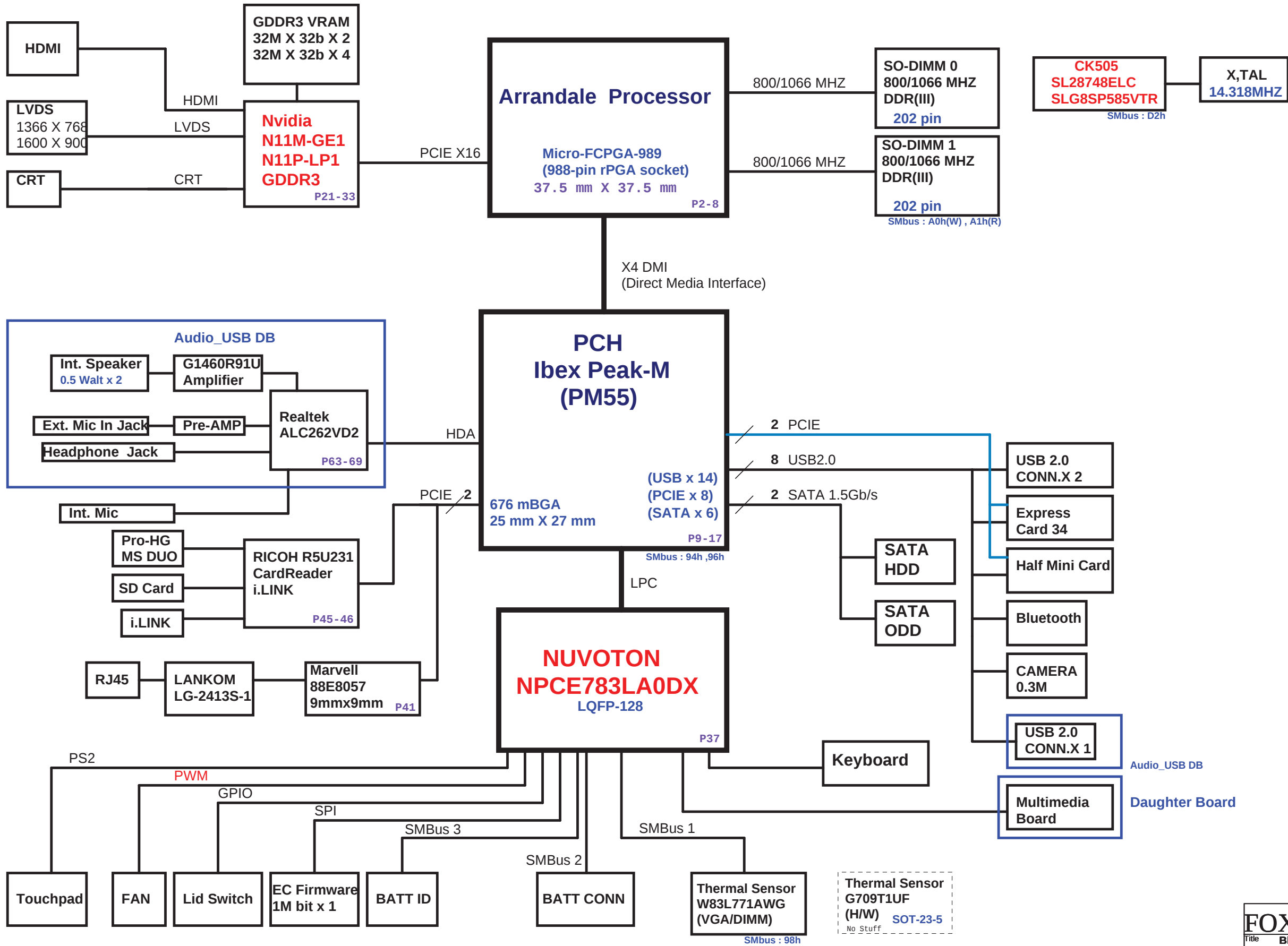


M-9A0 (Calpella + N11P/M Discrete Graphic)



TI CHARGER BQ24753 P.54	
OUTPUTS	
DC_IN	BT+ DCBATOUT

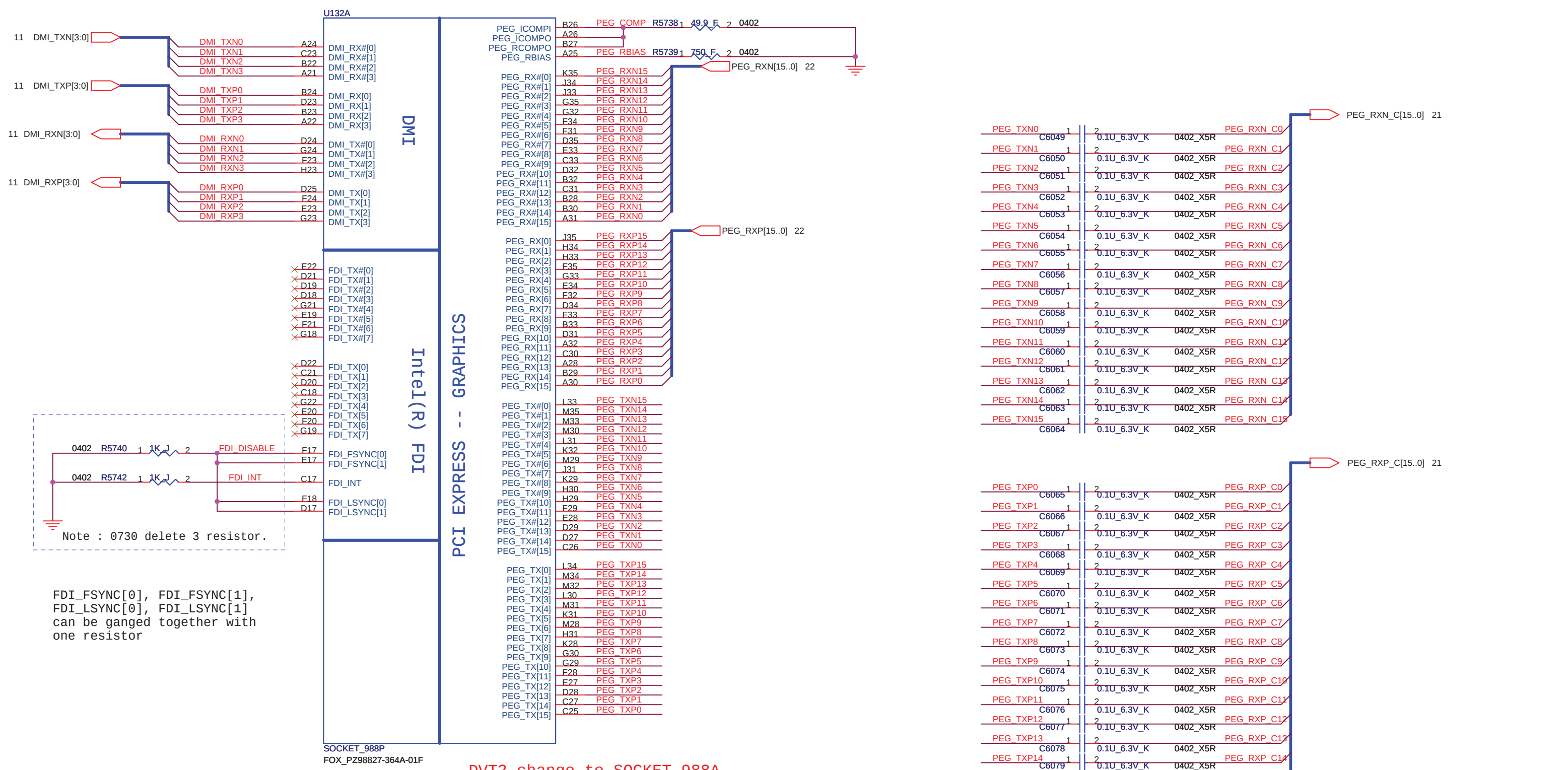
SYSTEM DC/DC MAX17020ETJ+ P.55	
INPUTS	OUTPUTS
DCBATOUT	+5VALW +5VALW_LDO +3VALW +ECVCC +12V

SYSTEM DC/DC SC412 P.56	
INPUTS	OUTPUTS
DCBATOUT	+1_5VRUN +1_05VRUN

SYSTEM DC/DC SC412+G2998 P.57	
INPUTS	OUTPUTS
DCBATOUT	+1_8VSUS +1_8VSUS
+1_8VSUS	+0_9VRUN

CPU DC/DC ISL6266A P.58	
INPUTS	OUTPUTS
DCBATOUT	VHORE

SYSTEM DC/DC SC411+APL5913 P.61	
INPUTS	OUTPUTS
DCBATOUT	NV_VDD +1_5VRUN
+1_5VRUN	PEX_VDD



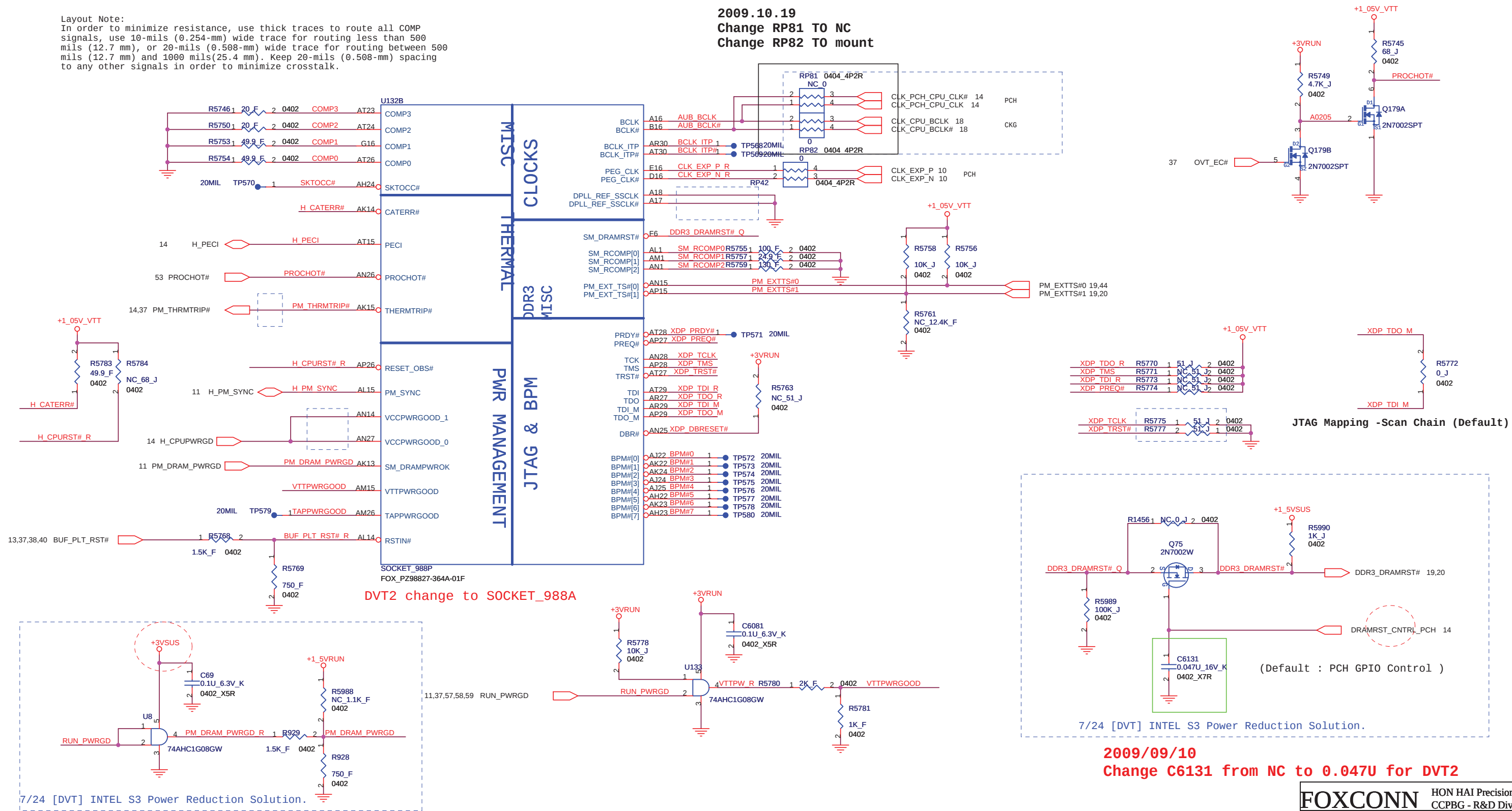
For Disable Arrandale Graphic
In addition, FDI_RXN[7:0] and FDI_RXP[7:0] can be left floating on the PCH.
FDI_TX[7:0] and FDI_TX#[7:0] can be left floating on the Arrandale. The FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1], and FDI_INT signals on the Arrandale side should be tied to GND (through 1-kΩ ±5% resistors).

DVT2 change to SOCKET_988A

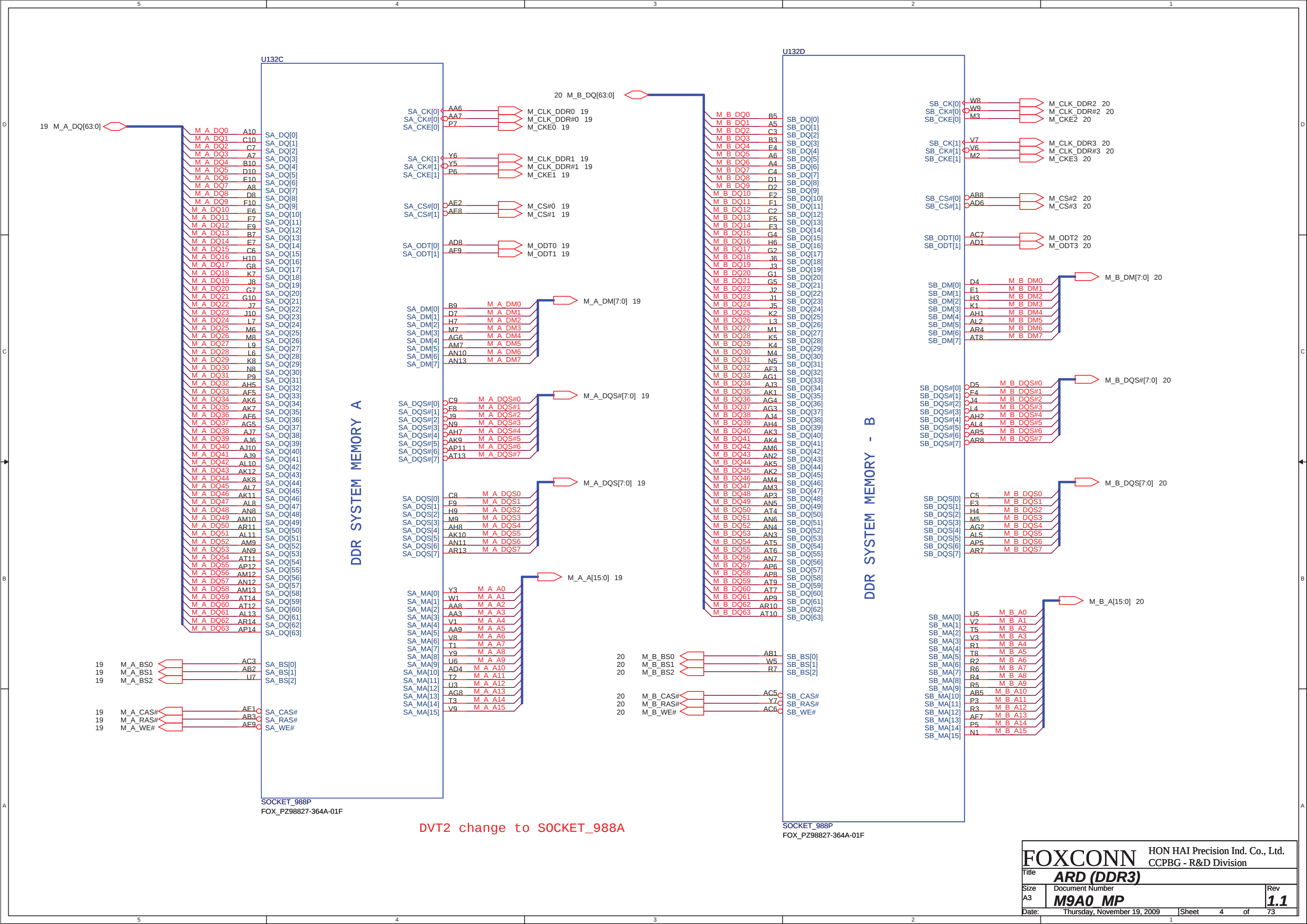
For Disable Arrandale Graphic
DPLL_REF_SSCLK and DPLL_REF_SSCLK# can be connected to GND on
Arrandale directly if motherboard only supports discrete graphics.

```
2009.10.19
Change RP81 TO NC
Change RP82 TO mount
```

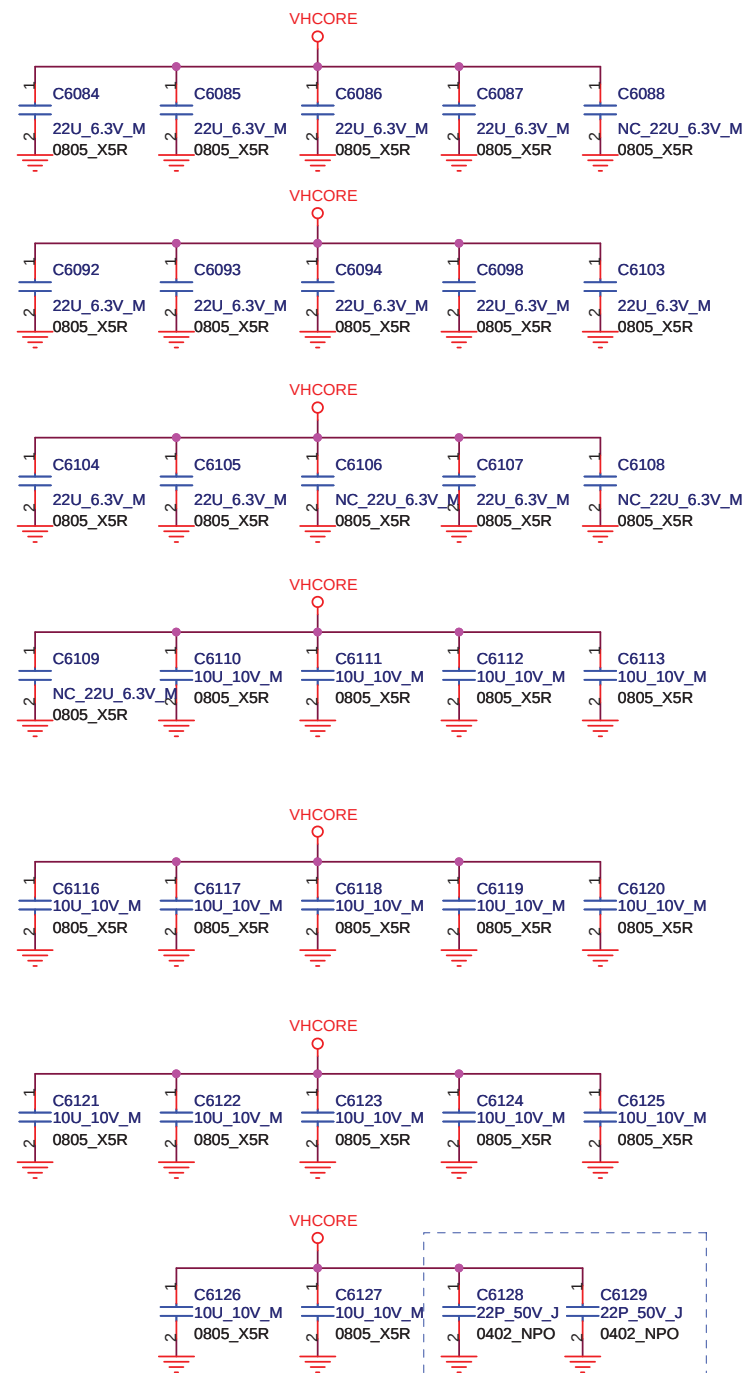
Layout Note:
In order to minimize resistance, use thick traces to route all COMP signals, use 10-mils (0.254-mm) wide trace for routing less than 500 mils (12.7 mm), or 20-mils (0.508-mm) wide trace for routing between 500 mils (12.7 mm) and 1000 mils (25.4 mm). Keep 20-mils (0.508-mm) spacing to any other signals in order to minimize crosstalk.



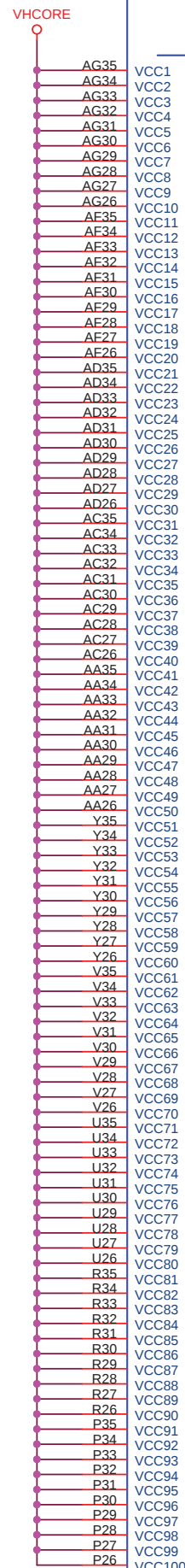
2009/09/10
Change C6131 from NC to 0.047U for DVT2



48A (ARD SV)



For RF Noise



SOCKET_988P
FOX_PZ98827-364A-01F

1.1V RAIL POWER

CPU CORE SUPPLY

POWER

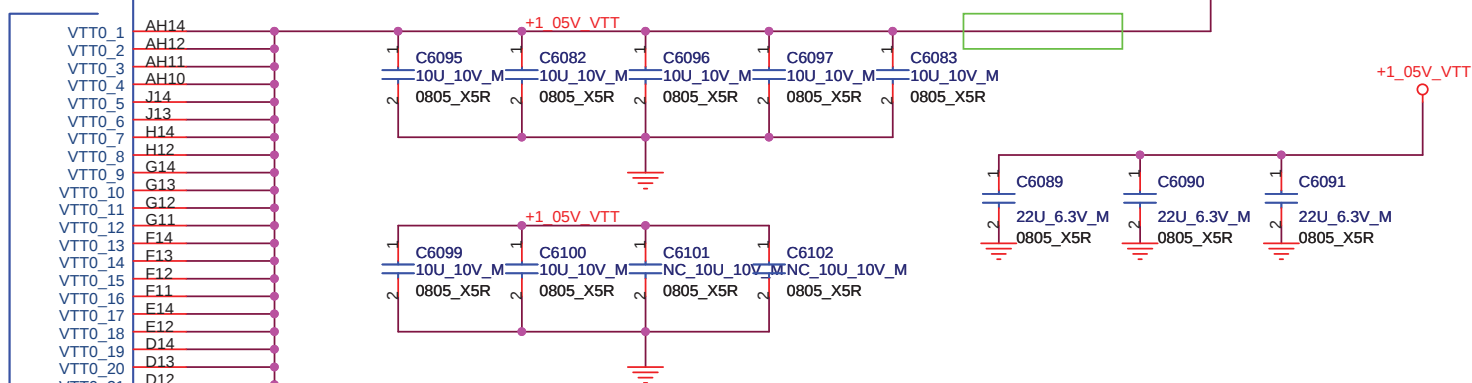
CPU VIDS

SENSE LINES

DVT2 change to SOCKET_988A

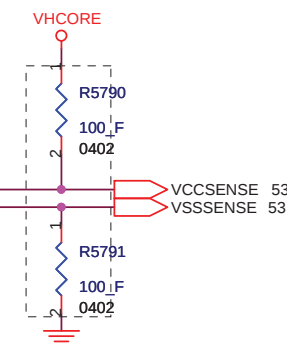
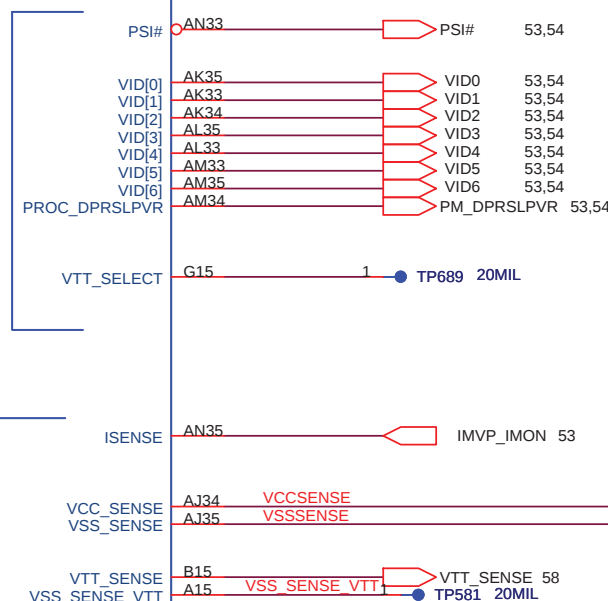
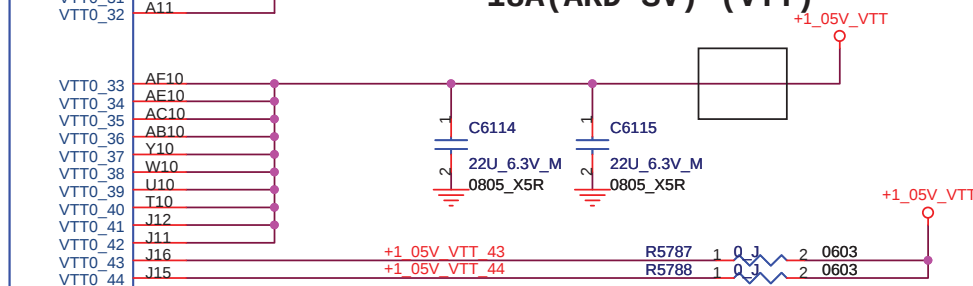
2009/09/12
Delete R5785 0ohm resistor for voltage drop problem

18A(ARD SV) (VTT)



2009.10.23
Delete R5786 for PVT

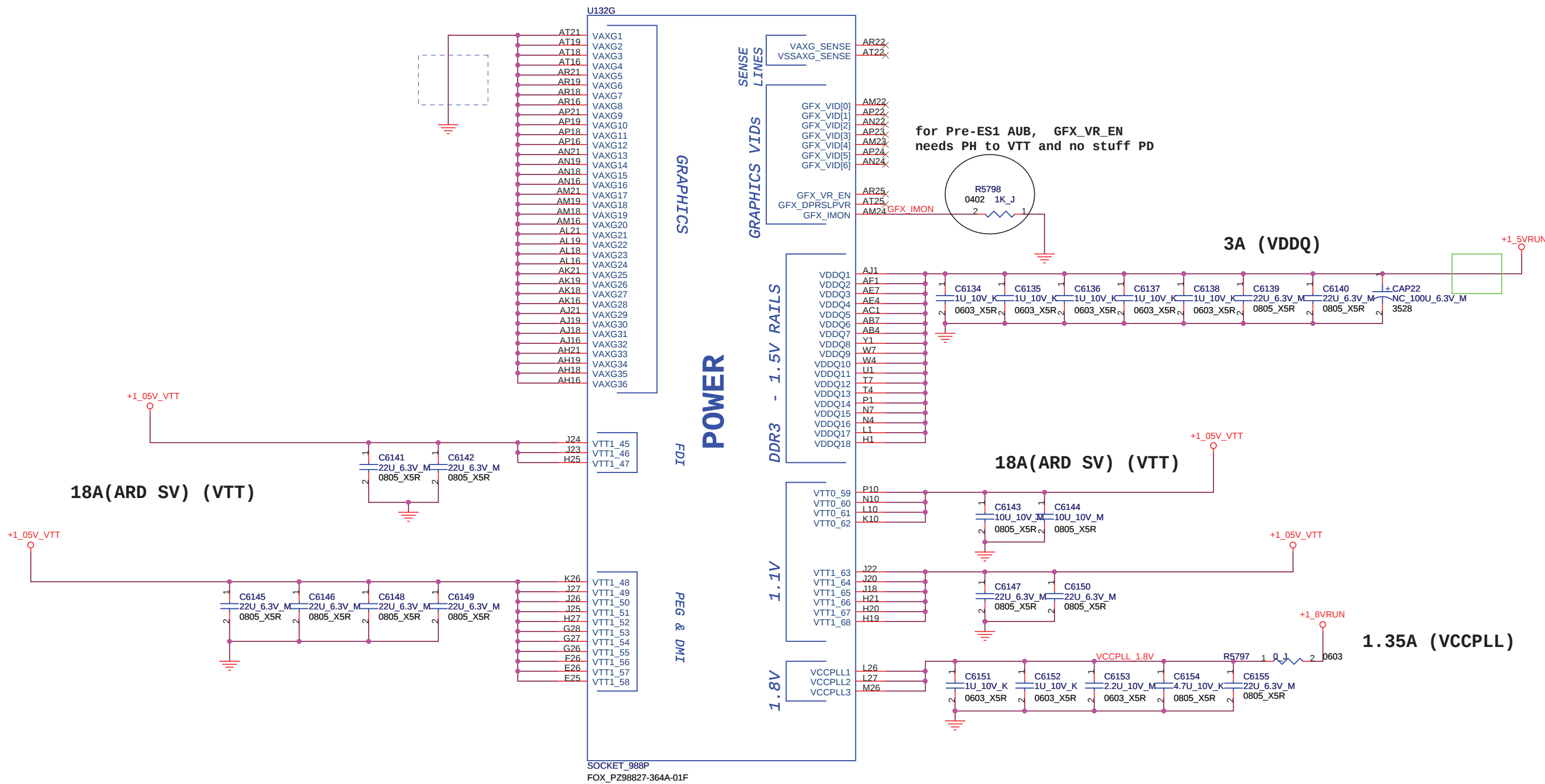
18A(ARD SV) (VTT)

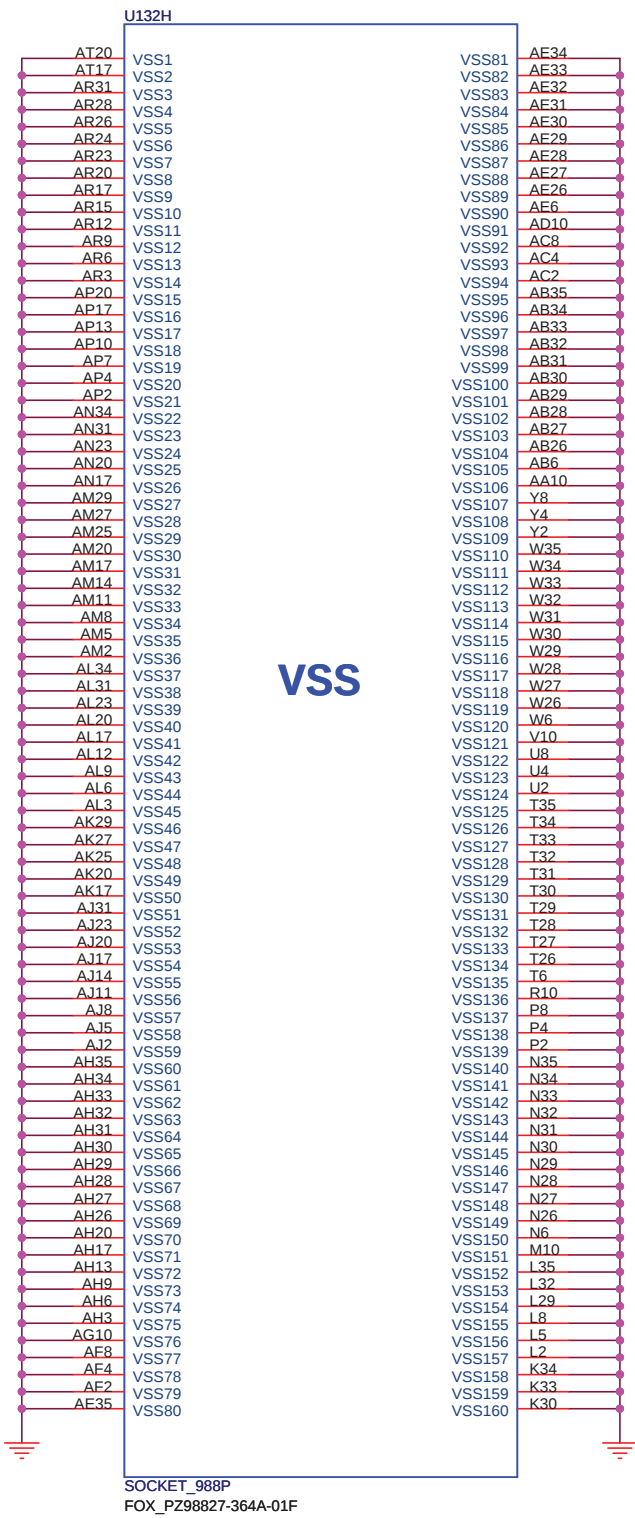


FOXCONN		HON HAI Precision Ind. Co., Ltd.	
Title		ARD(Power)	
Size	Document Number	Rev	
Custom	M9A0 MP	1.1	
Date:	Wednesday, October 28, 2009	Sheet	5 of 73

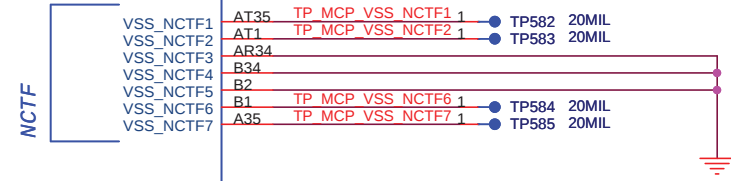
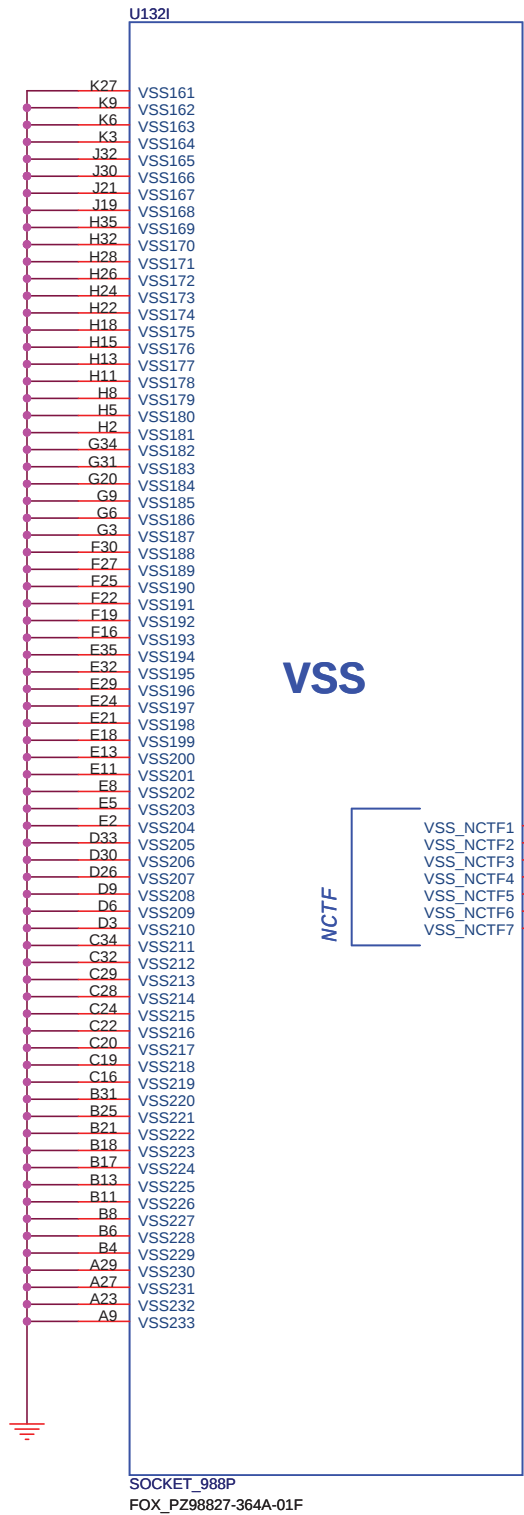
For Disable Arrandale Graphic
VAXG should be connected to GND when disable iGPU.

For Disable Arrandale Graphic
VAXG_SENSE and VSSAXG_SENSE on Arrandale can be left as no connect.





DVT2 change to SOCKET_988A



PCI Express Configuration Select
CFG0 1 : Single PEG * default
0 : Bifurcation enable

3393727 The VIL Voltage DC Specification for CFG[0] Pin is in Violation of the EDS Value by a Large Amount
The Clarksfield EDS Vol1 documents the CFG[1:0] pins for PCI Express Port Bifurcation, the straps may not work correctly when using a pull down resistor of value other than 250 Ohms to drive a value of zero on the CFG[0] pin. When left floating a value of one is sensed and there is no impact in this case.

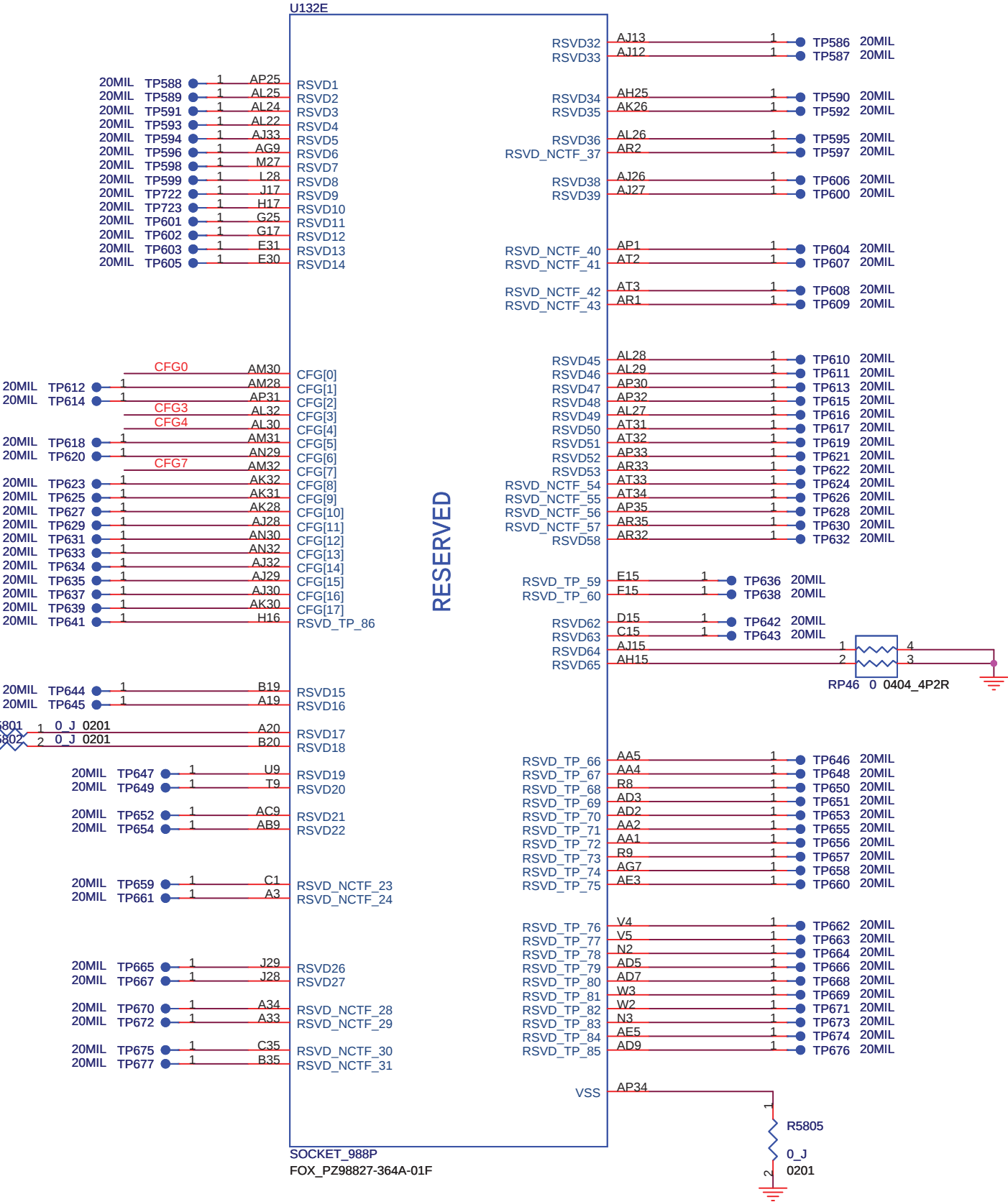
CFG pin is latch on the rising edge of CPU powergood.

CFG3 PCI Express Static Lane Reversal
CFG3 1 : Normal
0 : Lane Numbers Reversed *
15 -> 0 , 14 -> 1 , ...

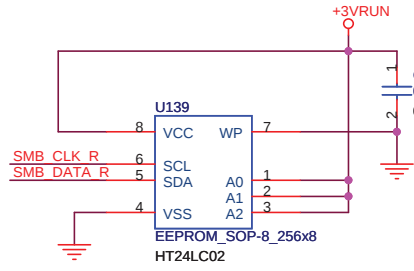
CFG4 Display Port Presence
CFG4 1 : Disabled ; No Physical Display Port attached to Embedded Display Port
0 : Enable ; An external Display Port device is connected to the Embedded Display Port

2611030 PCI Express Interface May Not Meet PCI Express 2.0 Jitter Specifications

Intel has determined that the workaround (3.01K pull down to Vss on signal CFG[7]) is not robust. Intel recommends not implementing this workaround at this time (CFG[7] should not be pulled down).
Intel recommends not to test for PCI-E Express 2.0 Jitter specification compliance for the affected steppings.



Port	Function
Port1	WLAN
Port2	Ricoh R5U231
Port3	GbE LAN
Port4	NC
Port5	NC
Port6	ExpressCard/34 (PCIE)
Port7	NC
Port8	NC



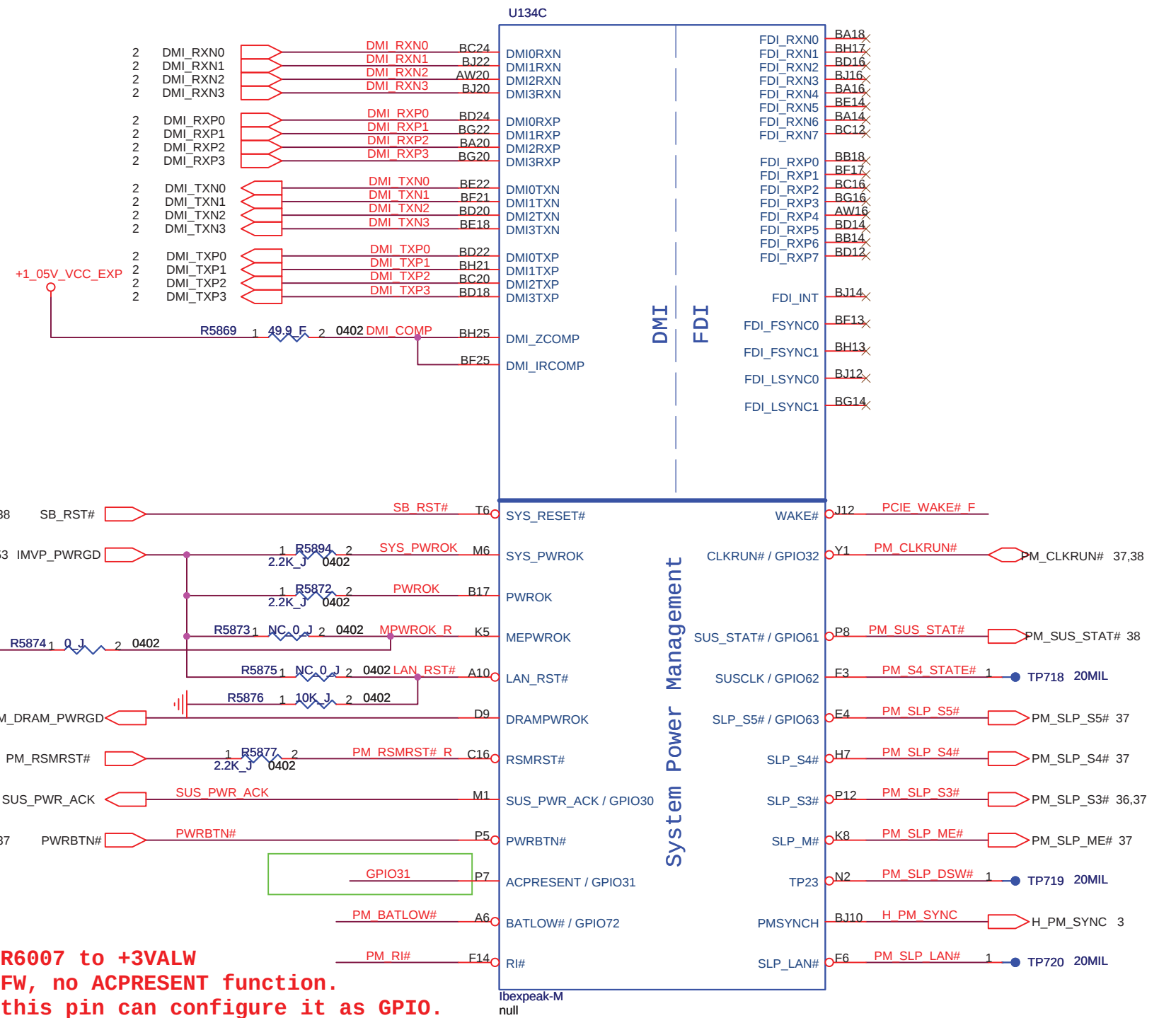
Calpella Platform - Design Guide - Addendum /
Update - Rev. 1.52 (Doc #414044).).

XTAL_IN should be pulled to GND via a 0ohm by default.

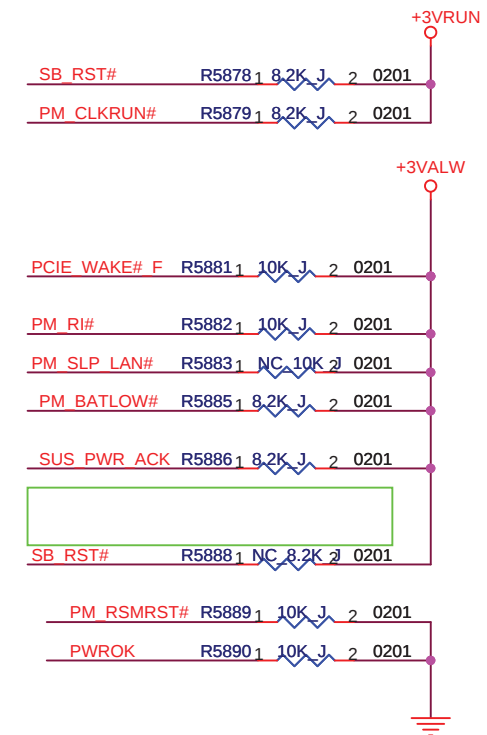
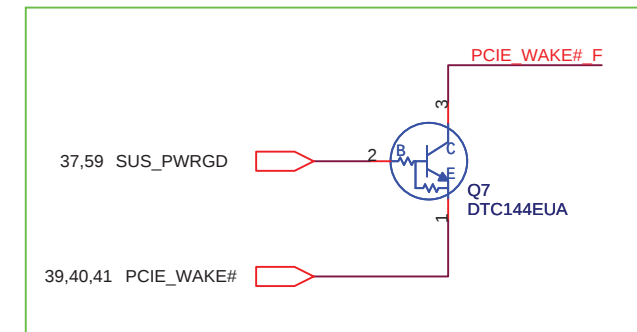
This pull-down resistor on XTAL_IN should only be un-stuffed when 25MHZ crystal is used.

FOXCONN		HON HAI Precision Ind. Co., Ltd.	
		CCPBG - R&D Division	
Title	PCH (PCI-E, SMBUS, CLK)		
Size	Document Number	Rev	
Custom	M9A0 MP	1.1	
Date:	Friday, October 23, 2009	Sheet	10 of 73

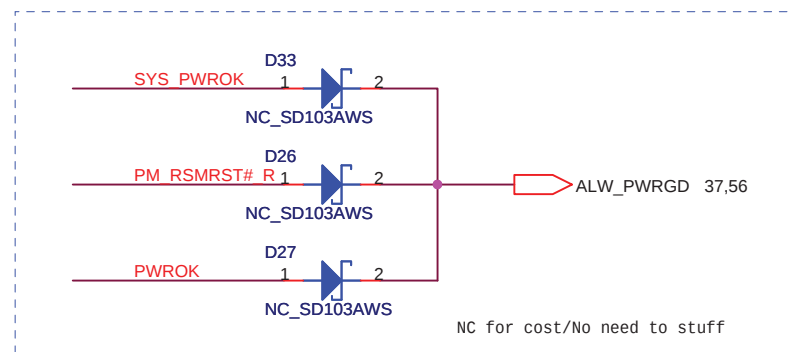
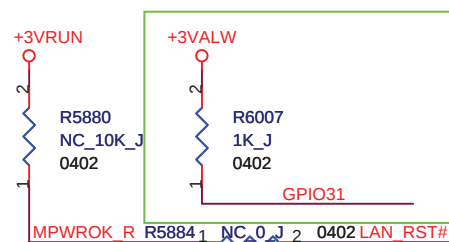
For Disable Auburndale Graphic
In addition, FDI_RXN[7:0] and FDI_RXP[7:0] can be left floating on the PCH.
FDI_TX[7:0] and FDI_TX#[7:0] can be left floating on the Arrandale. The
GFX_IMON, FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1], and FDI_INT
signals on the Arrandale side should be tied to GND (through 1-kΩ ±5% resistors).



2009.0928
Add the Q7 as MOR request.

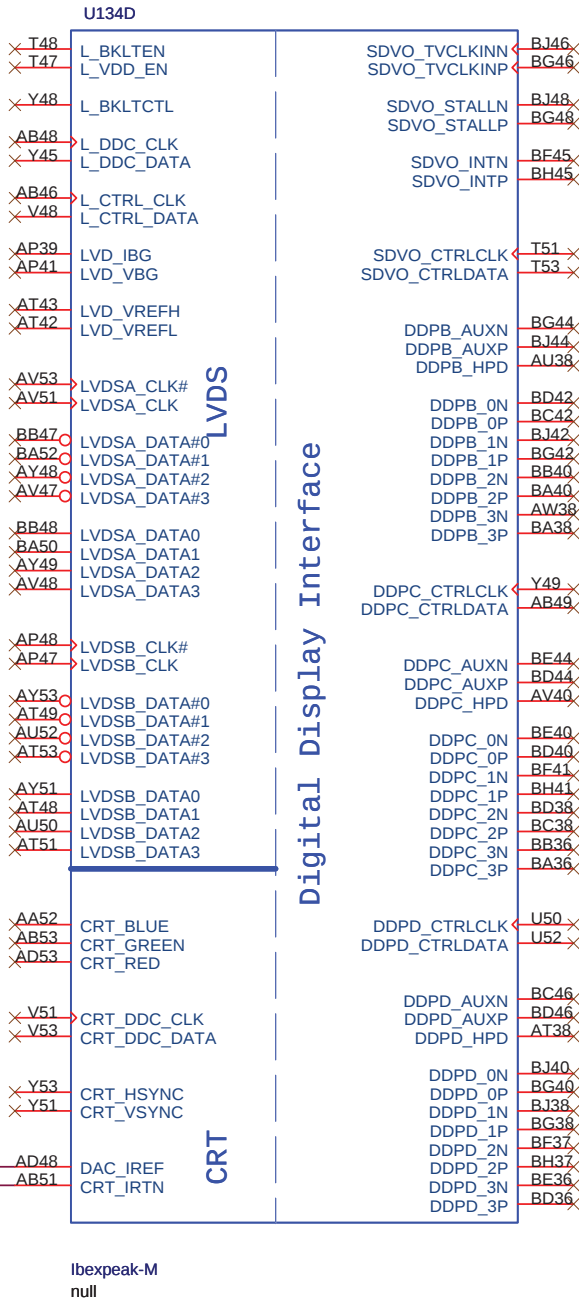
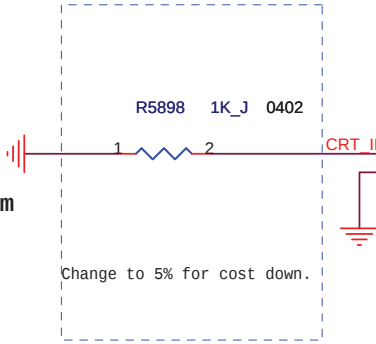


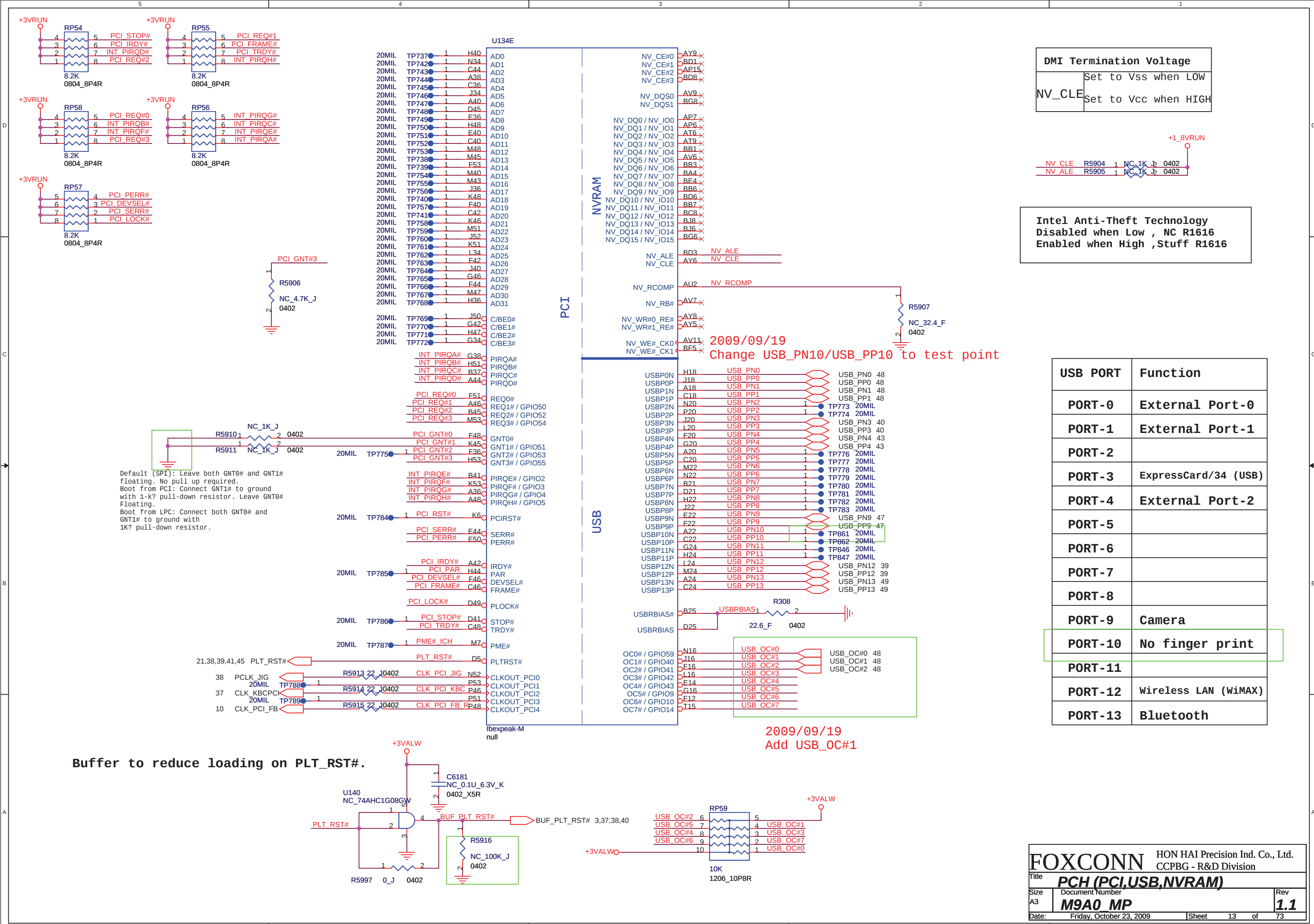
2009/09/10 (DVT2)
Delete R5893, add R6007 to +3VALW
M9A0 use Ignition FW, no ACPRESENT function.
Intel FAE suggest this pin can configure it as GPIO.

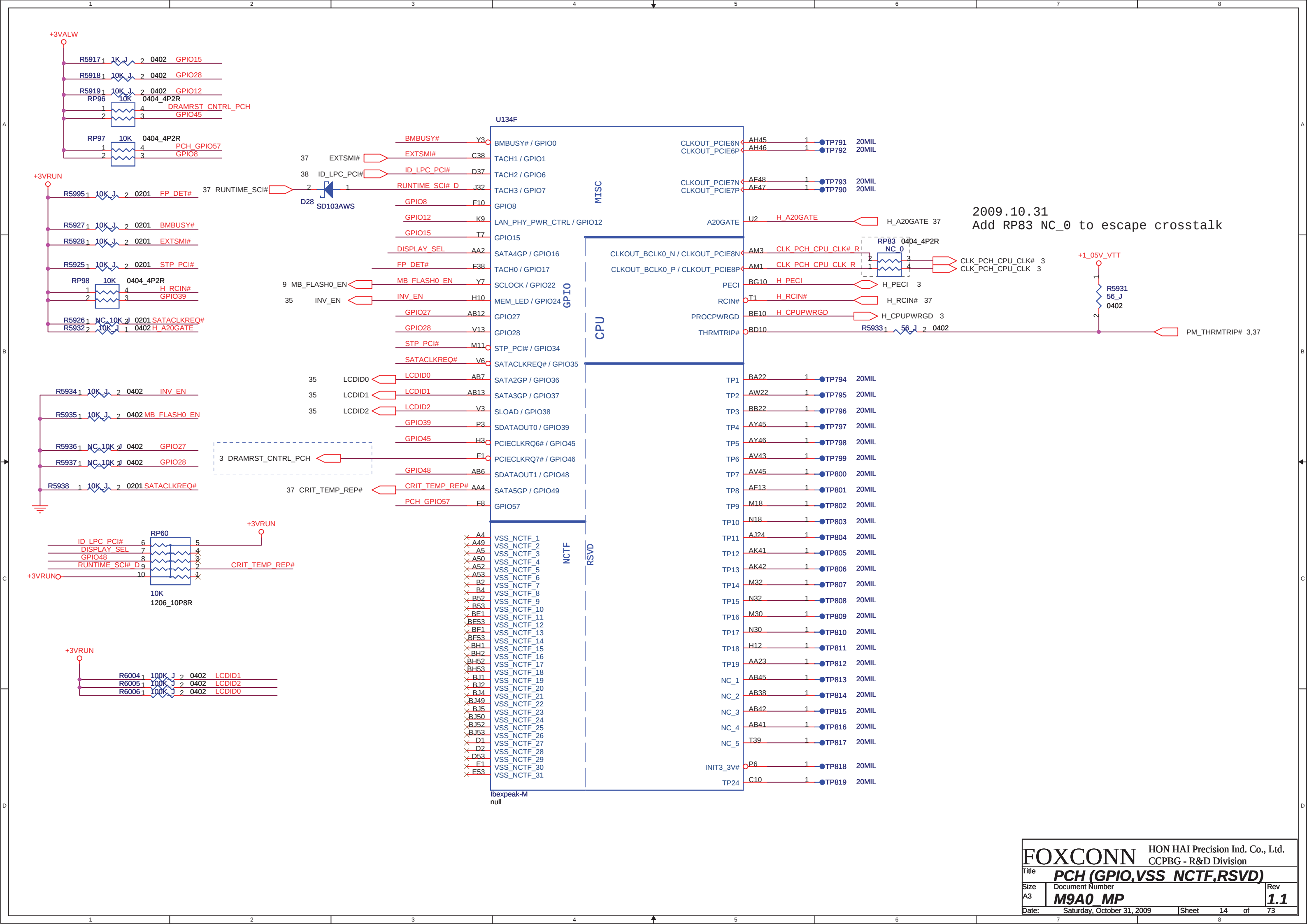


2009/09/10 (DVT2)
Delete R5887 and Net name AC_Present
M9A0 use Ignition FW, no ACPRESENT function.
Intel FAE suggest this pin can configure it as GPIO.

Calpella Platform - Design Guide - Addendum
/ Update - Rev. 1.52 (Doc #414044).).

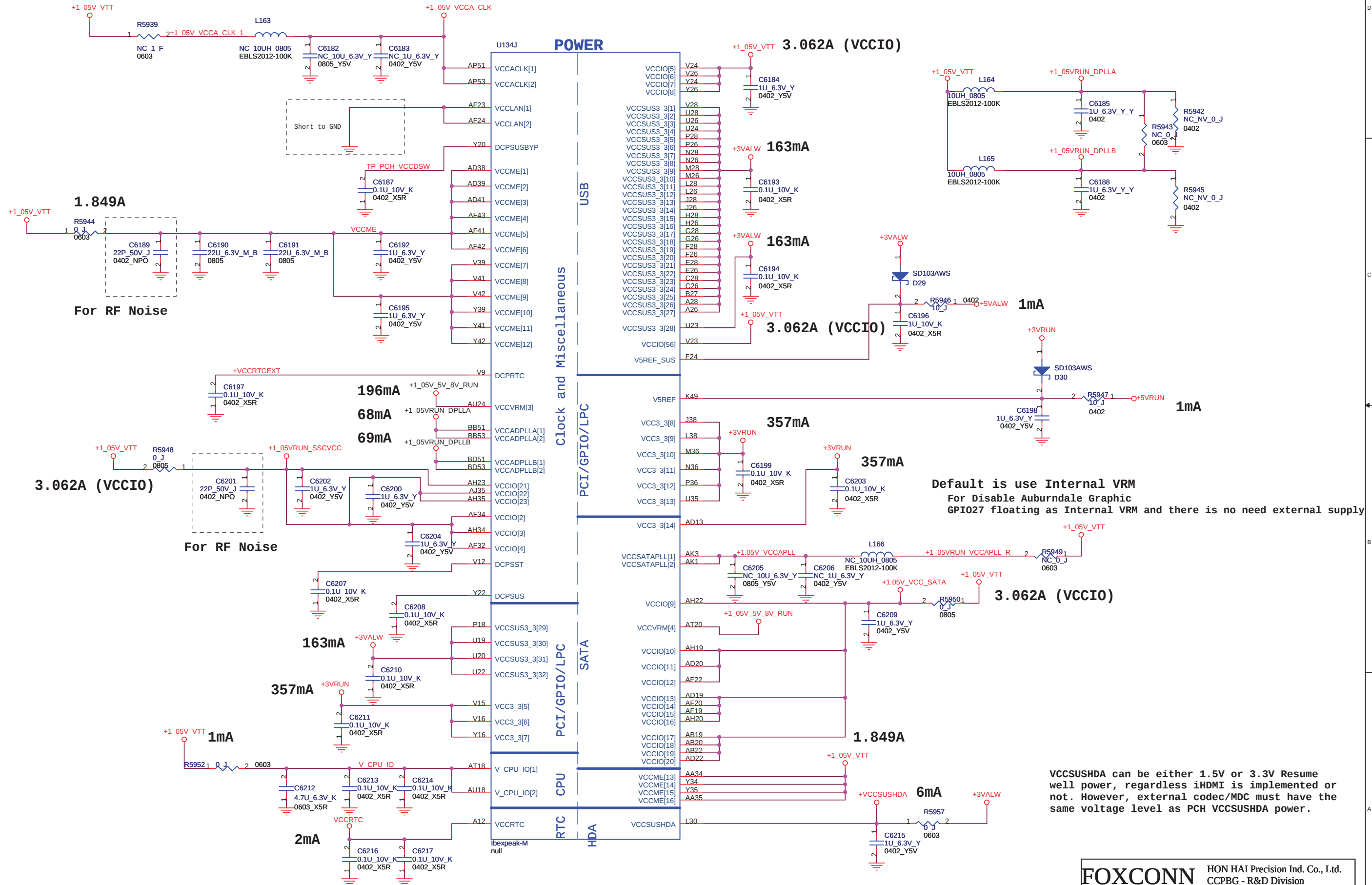




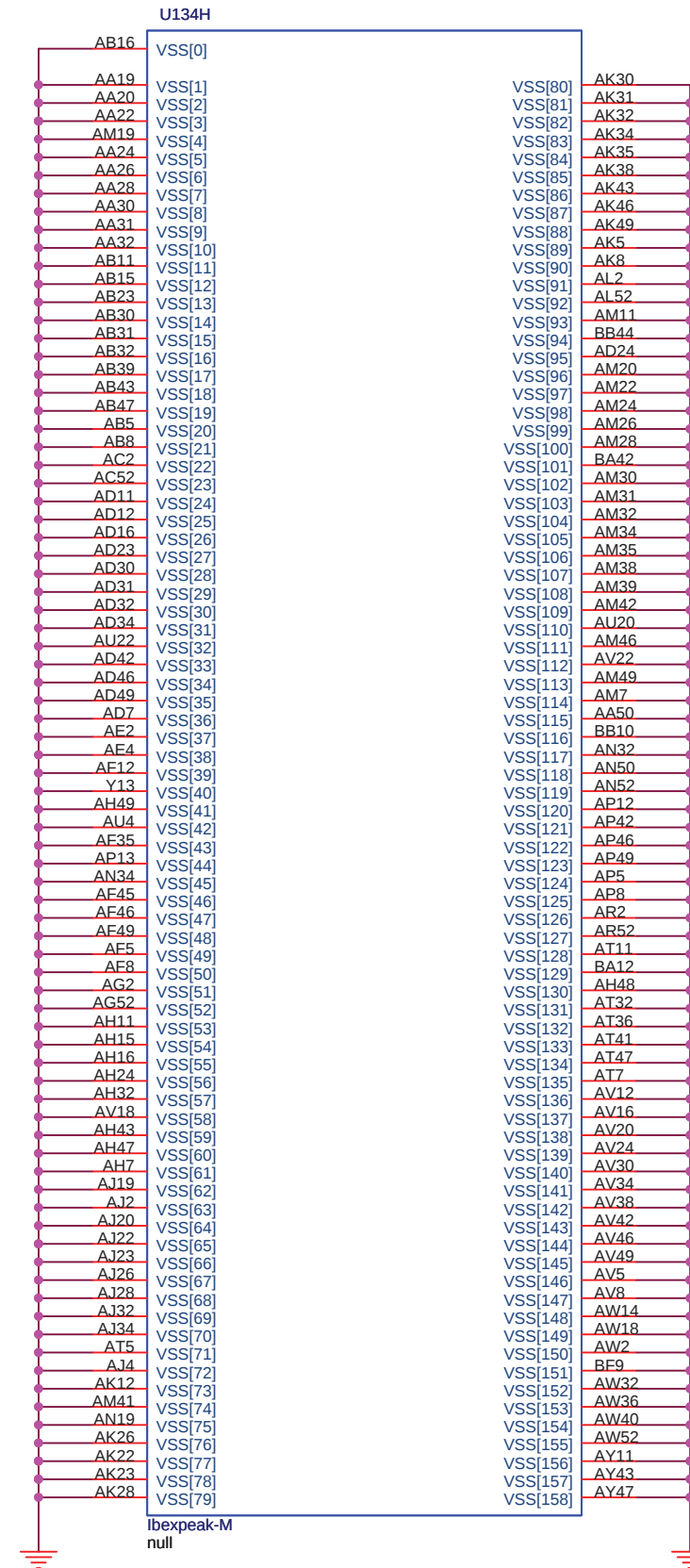
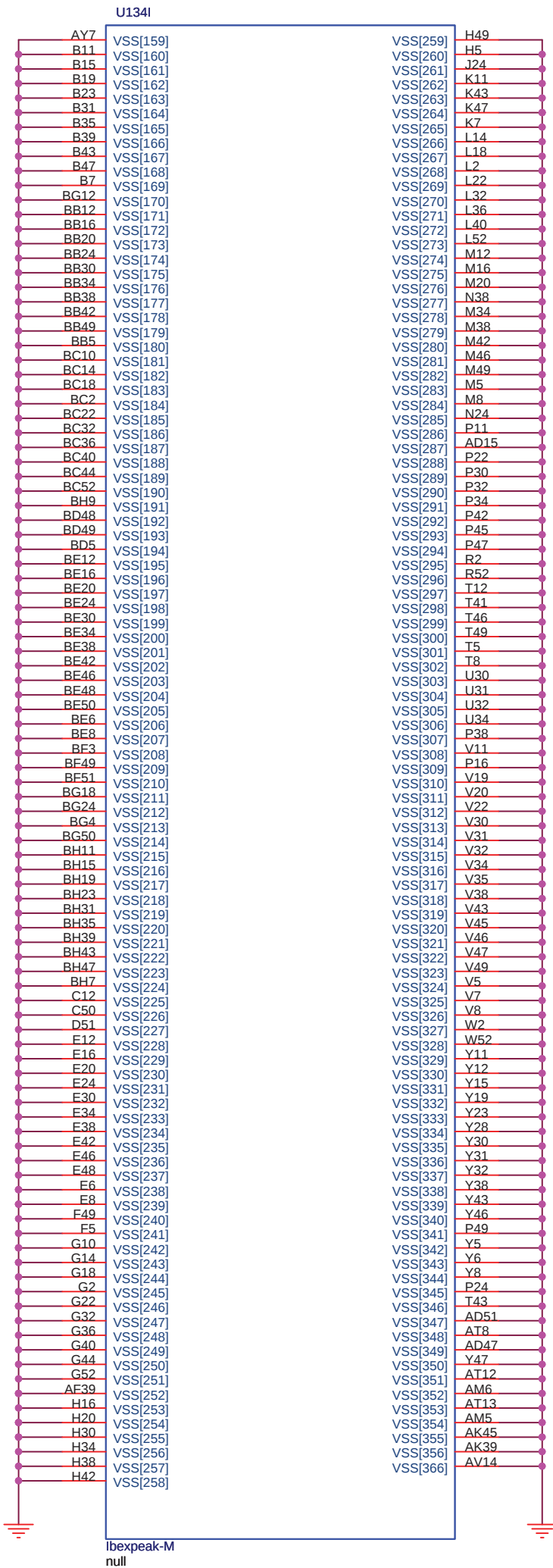


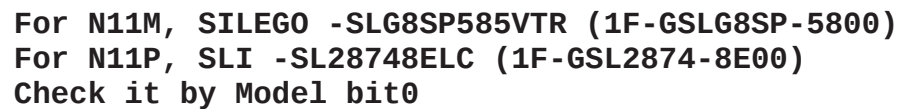
2009.10.31
Add RP83 NC_0 to escape crosstalk

Default is use Internal VRM
For Disable Auburndale Graphic
GPIO27 floating as Internal VRM and there is no need external supply

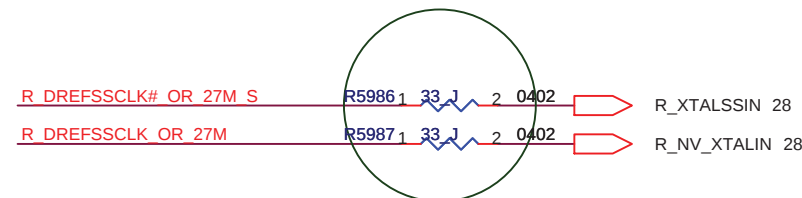


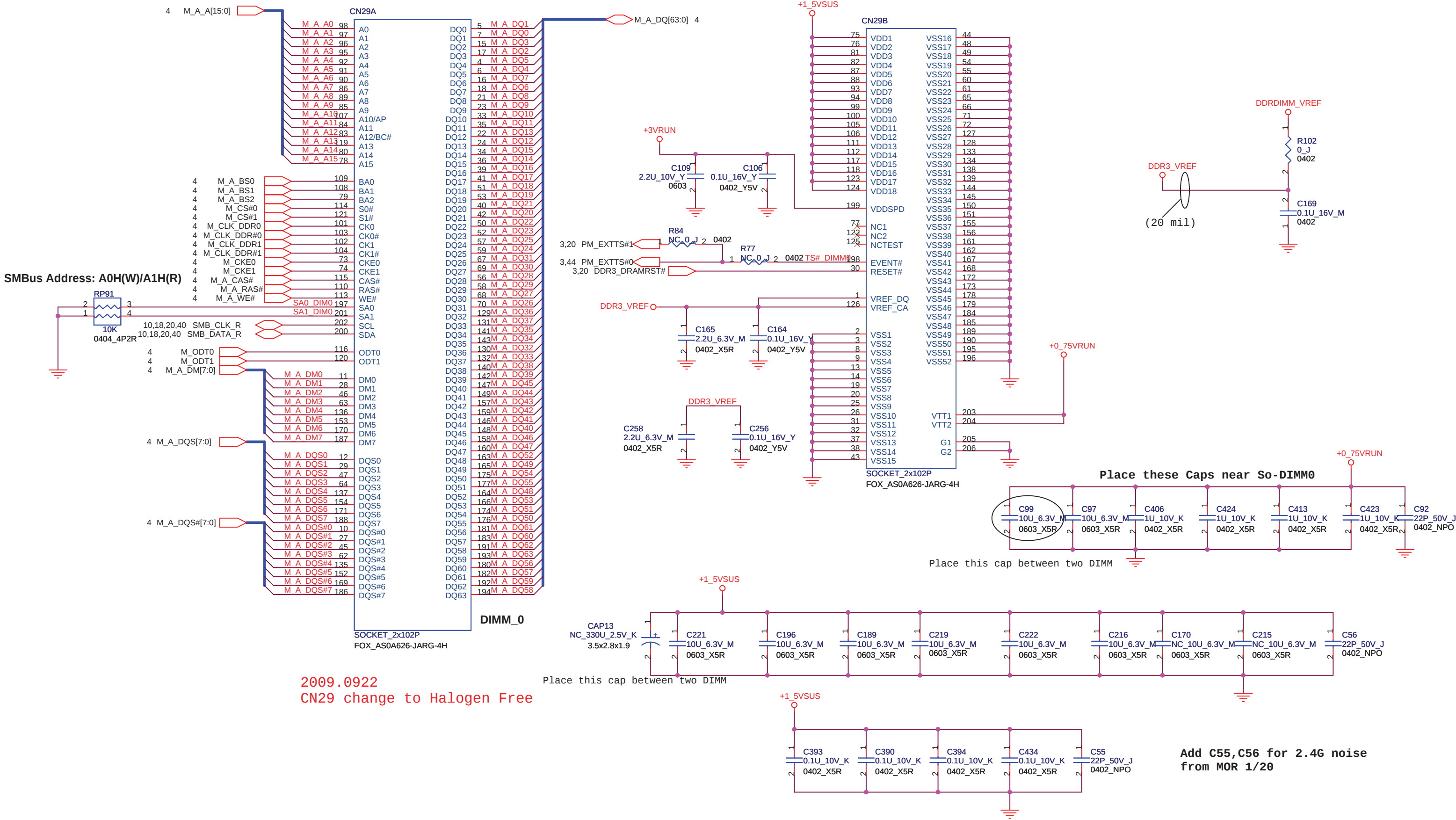
VCCSUSHDA can be either 1.5V or 3.3V Resume well power, regardless iHDMI is implemented or not. However, external codec/MDC must have the same voltage level as PCH VCCSUSHDA power.

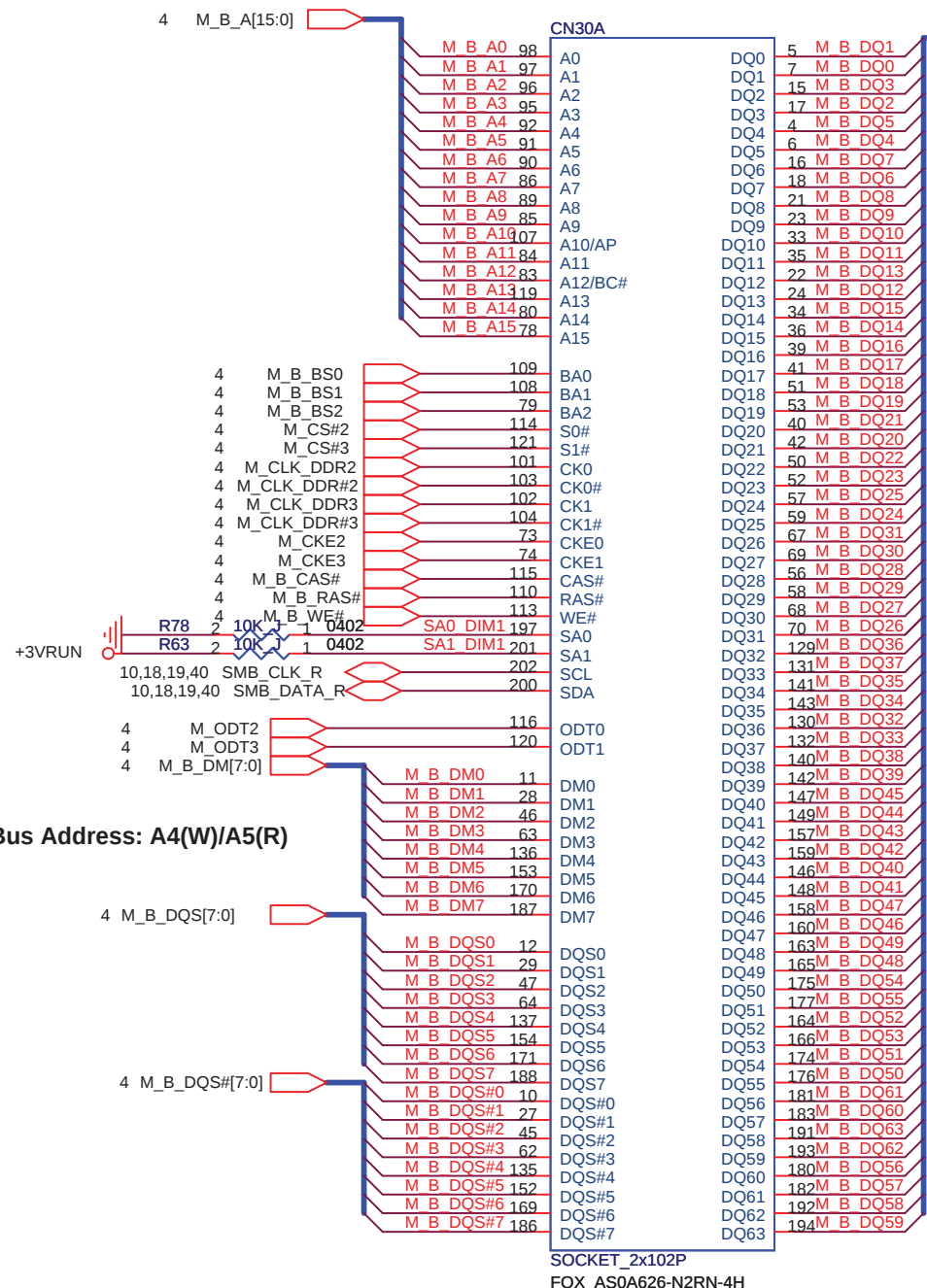




FS	CPU	Power On	SRC	SATA	DOT96	27MHz	REF
0	133MHz	Default	100MHz	100MHz	96MHz	27MHz	14.318MHz
1	100MHz						

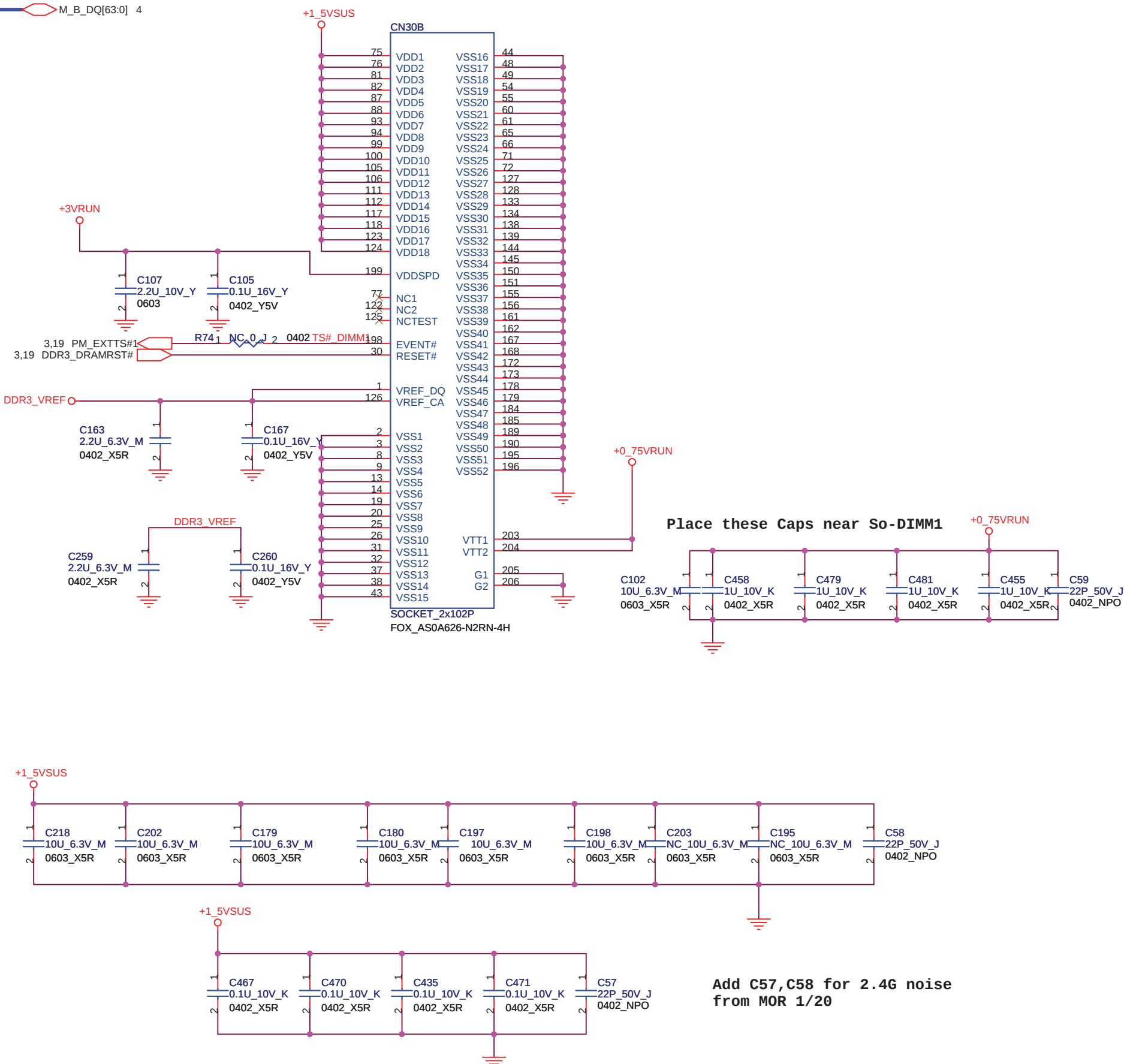


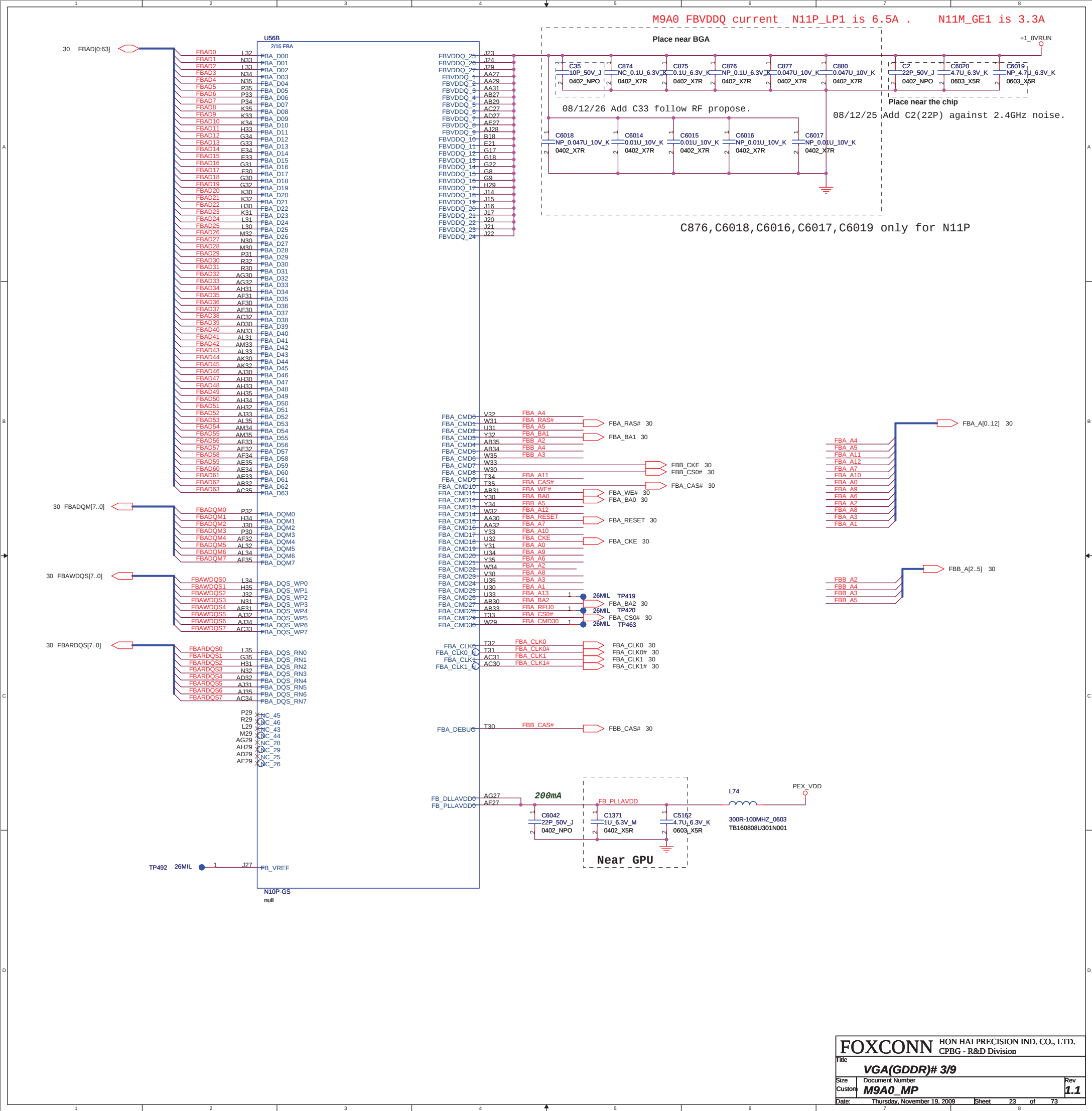


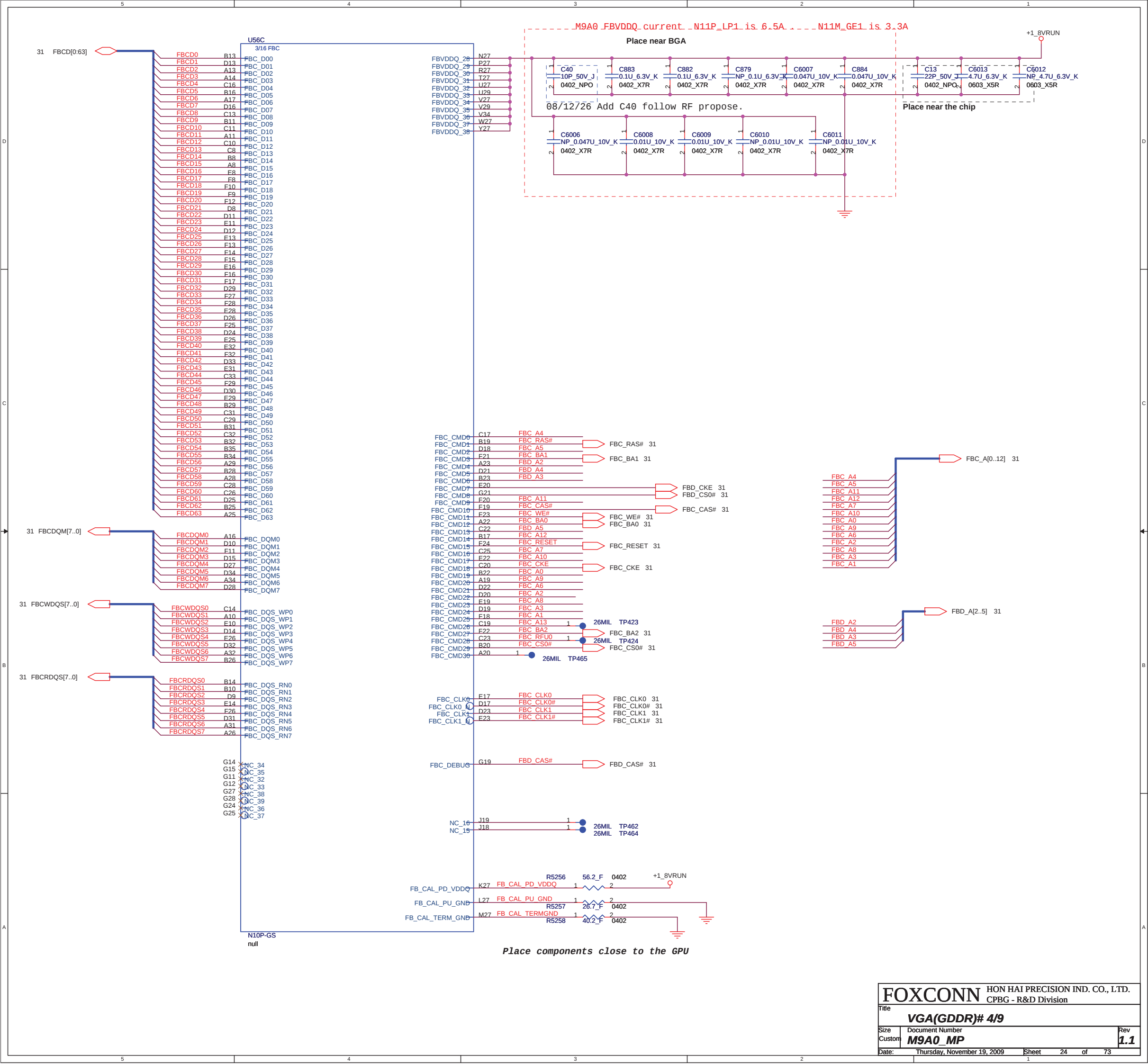


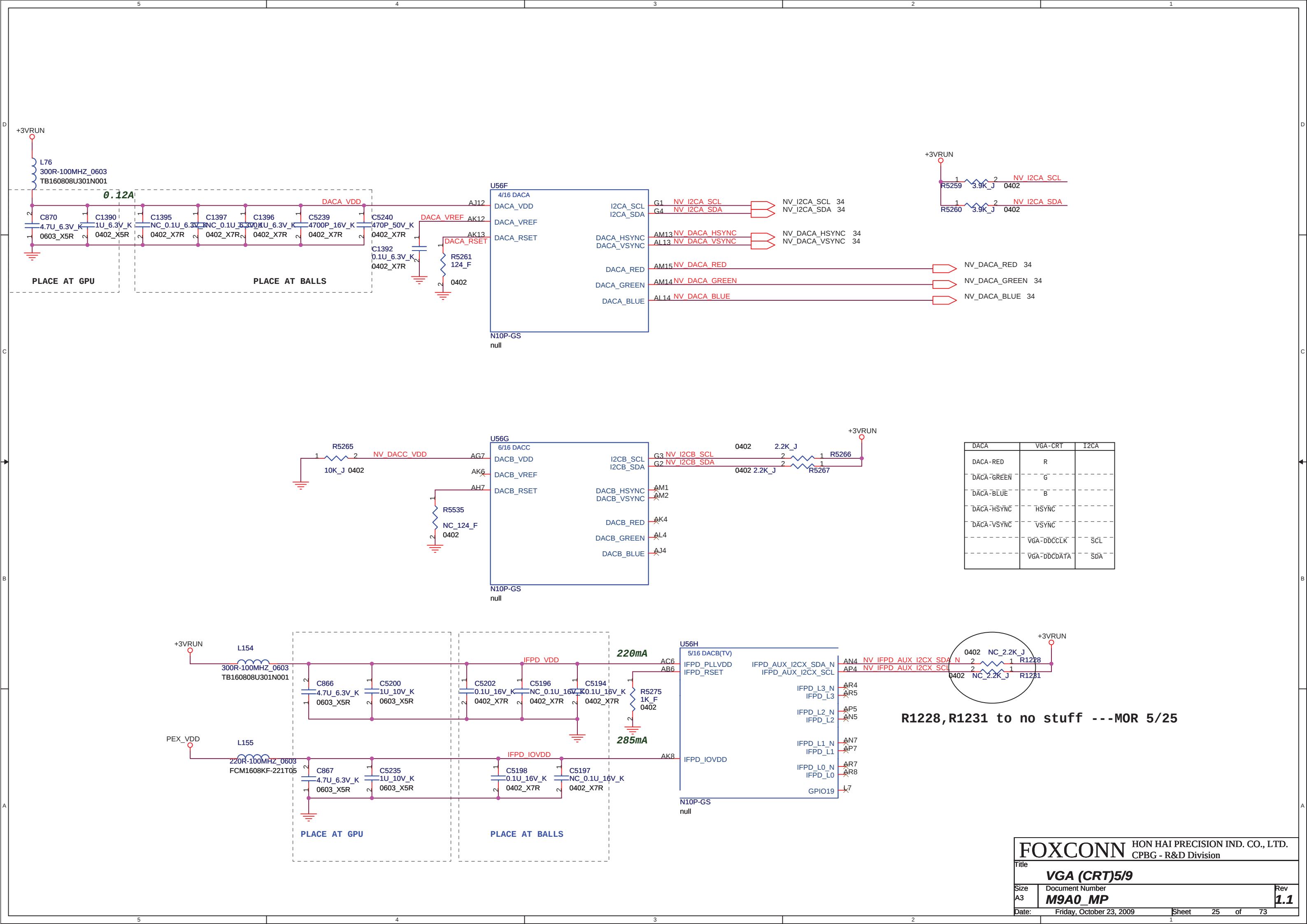
SMBus Address: A4(W)/A5(R)

2009.0922
CN30 change to Halogen Free



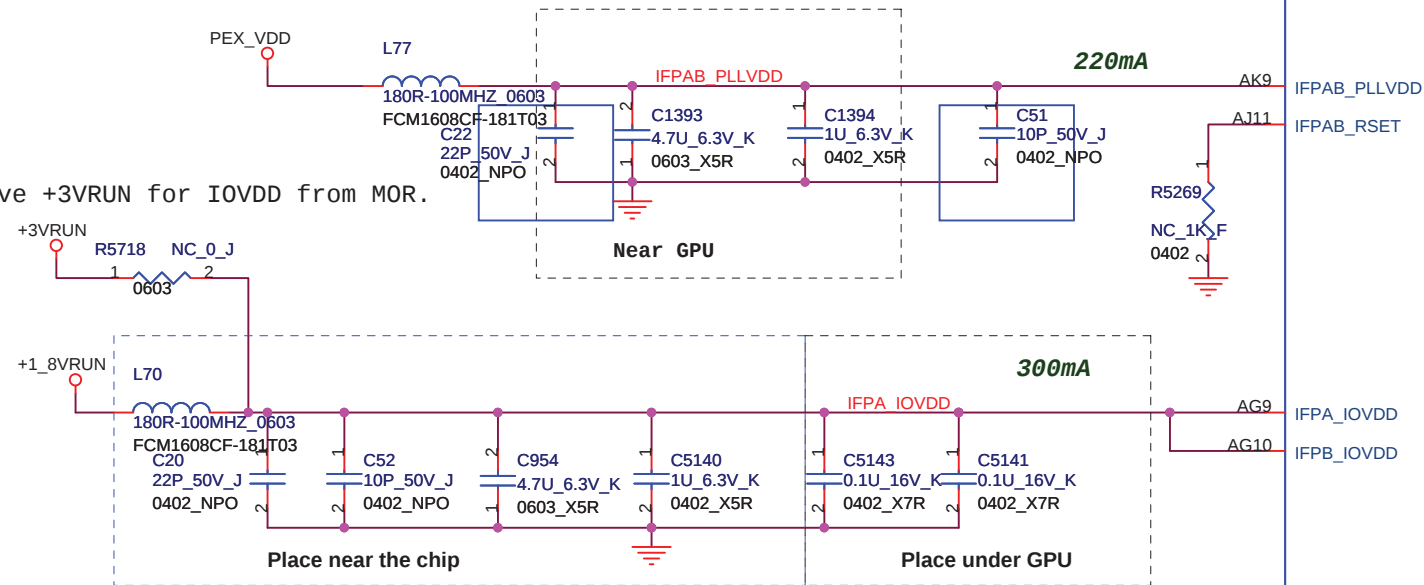




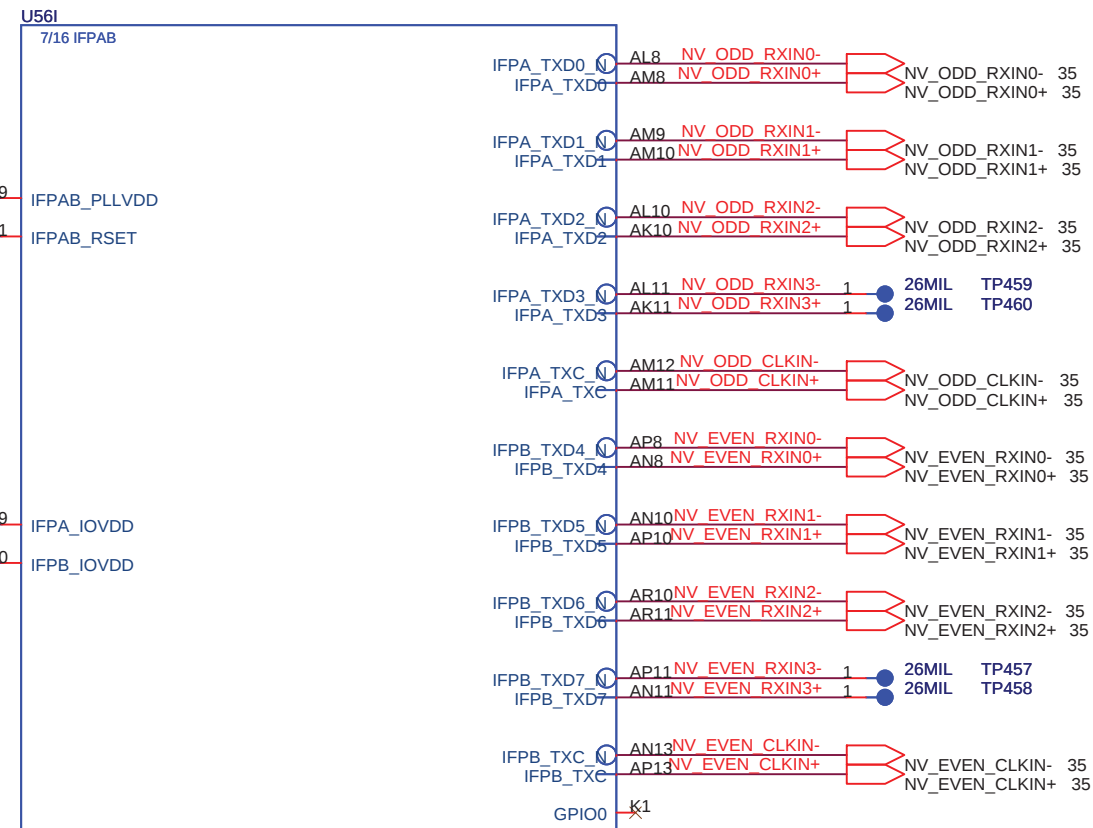


08/12/26 Add C51,C52 10p follow RF propose.

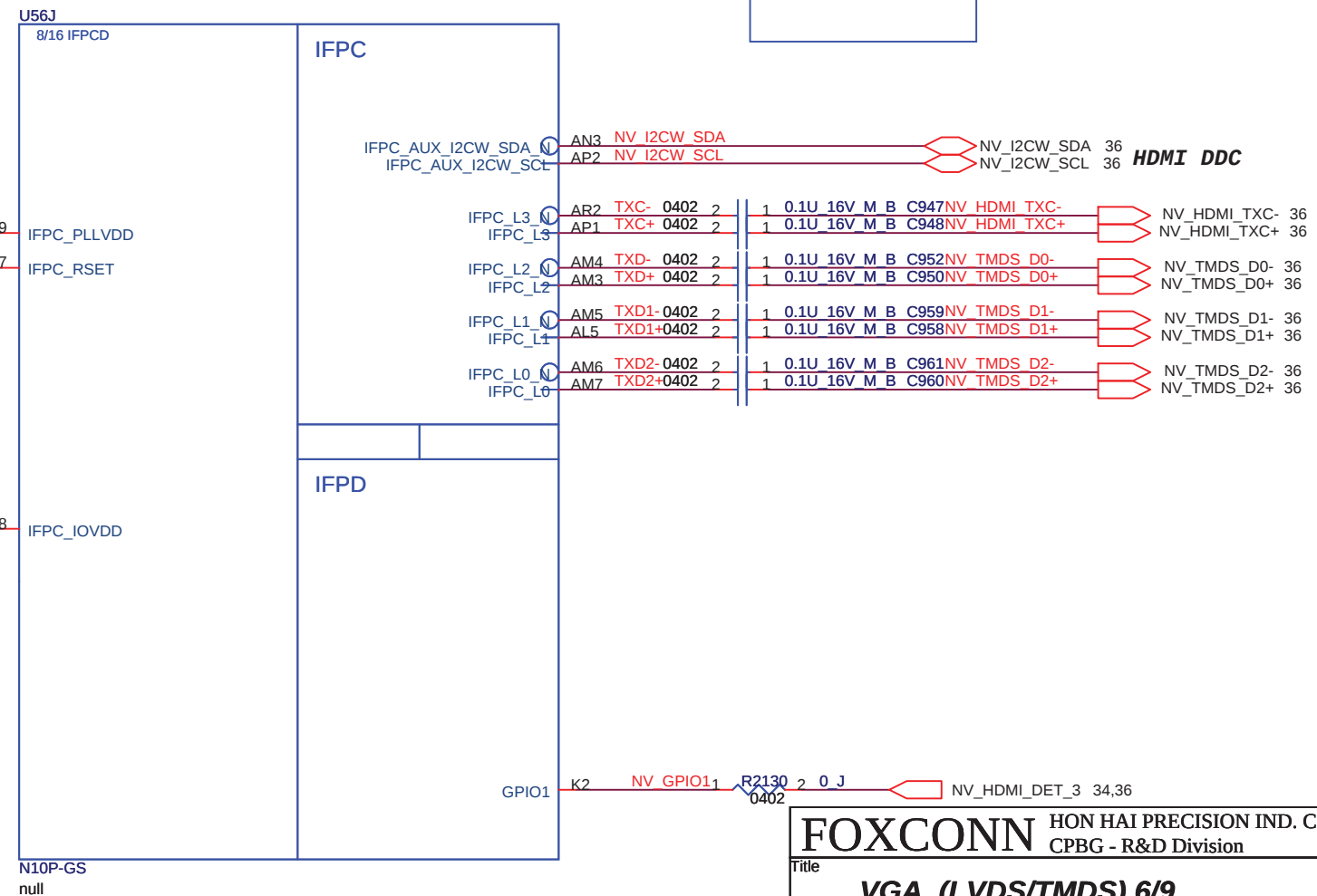
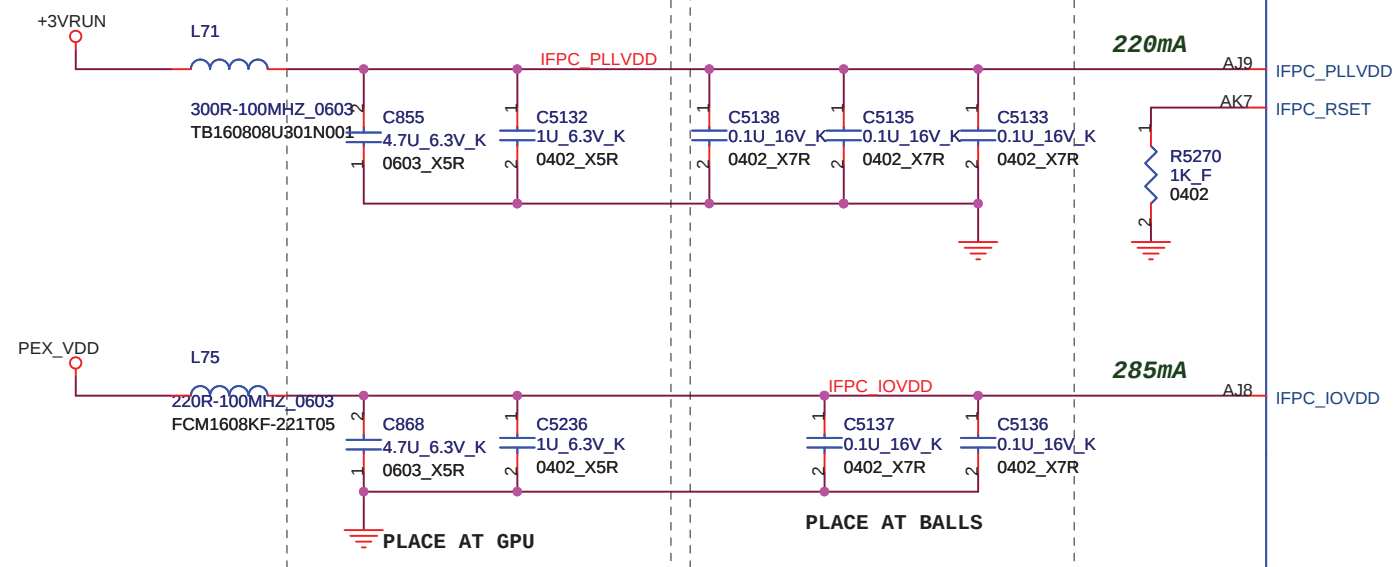
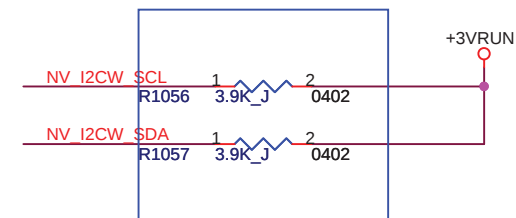
09/02/05 Reserve +3VRUN for IOVDD from MOR.

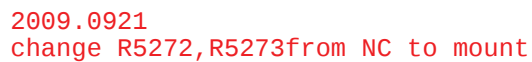


08/12/25 Add C20,C22 against 2.4GHz noise.



08/12/22 Change R1056,R1057 from 2.2K to 3.9K follow Mor-side propose.



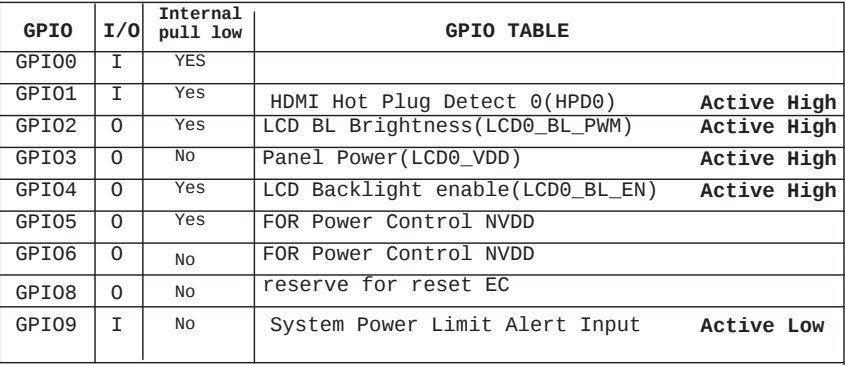


follow Mor-side propose.

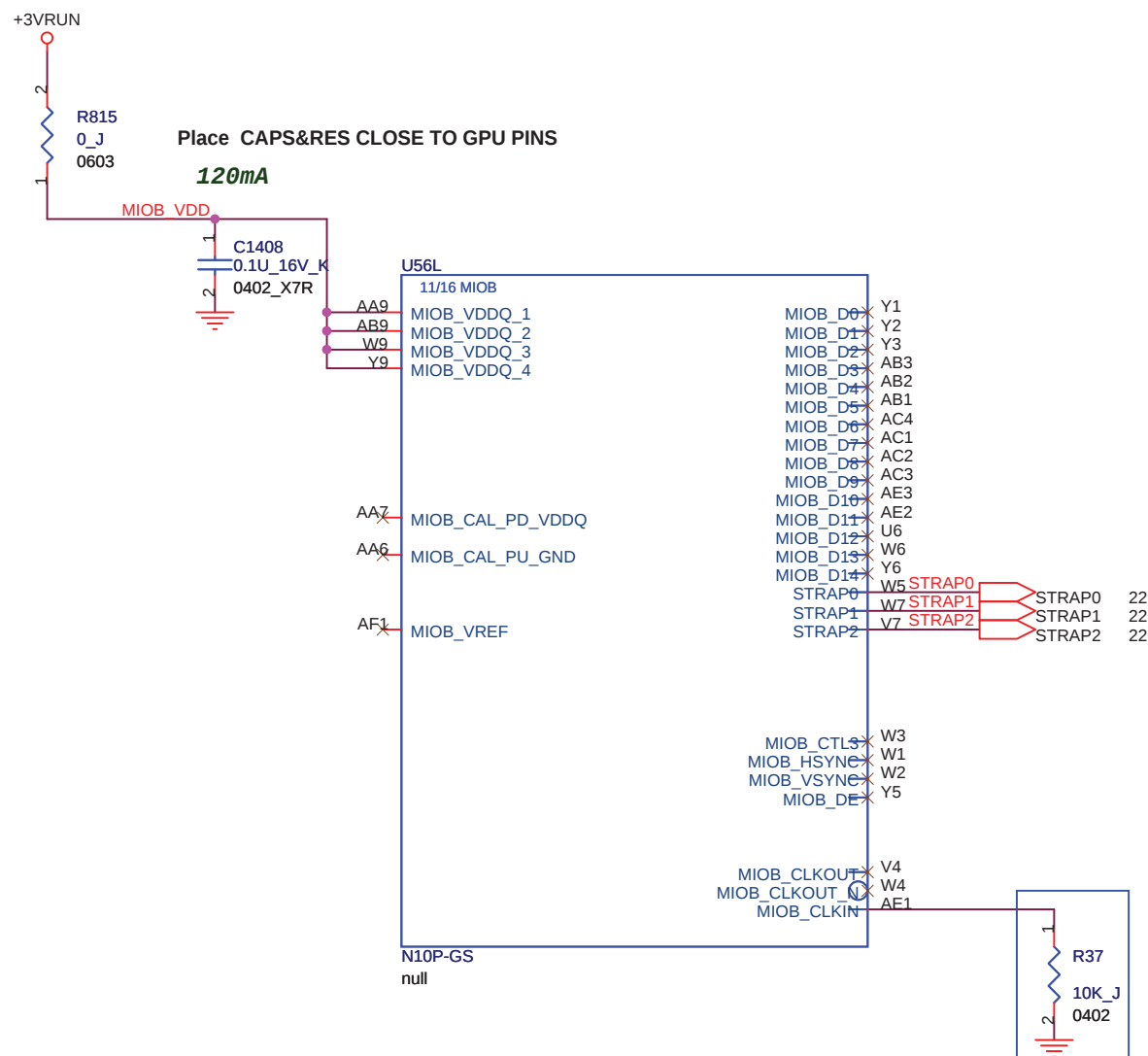
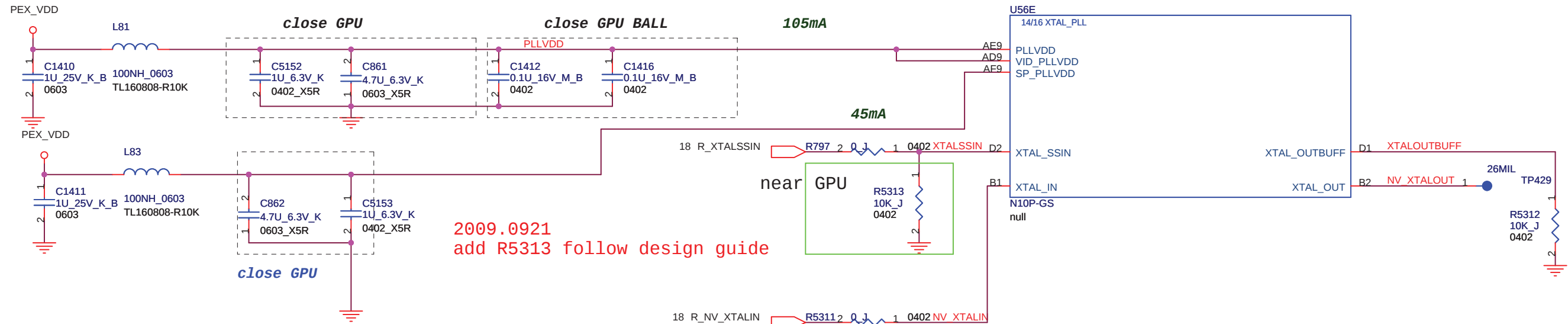
The schematic diagram shows the U56D component with the following connections and components:

- Power and Ground:**
 - +3VRUN:** Connected to pin 126 (J26) and pin 41 (J25).
 - Ground:** Connected to pin 40 (J25), pin 11 (D7), pin 10 (D6), pin 8 (C7), pin 7 (B7), pin 3 (A7), pin 1 (A5), pin 30 (C5), pin 14 (AK14), and pin 2 (K9).
- CEC:**
 - AB5:** Connected to pin 11 (D7).
- Multi-Strap:**
 - N9:** Connected to pin 11 (D7) via R5278 (40.2K).
 - M9:** Connected to pin 10 (D6) via R5279 (40.2K).
- ROM:**
 - ROM_SI:** Connected to pin 3 (A7) via C3.
 - ROM_SO:** Connected to pin 4 (A8) via C4.
 - ROM_SCLK:** Connected to pin 5 (A9) via D4.
- HD-CDC:**
 - HDCH_SCL:** Connected to pin 6 (A10) via F6.
 - HDCH_SDA:** Connected to pin 7 (A11) via G6.
- Other Components:**
 - R5:** 10K, 0402, connected to +3VRUN and ground.
 - R5278, R5279:** 40.2K, 0402, connected to N9 and M9 respectively.
 - R5717:** NC_36K_F, 0402, connected to pin 1 (A5) and ground.

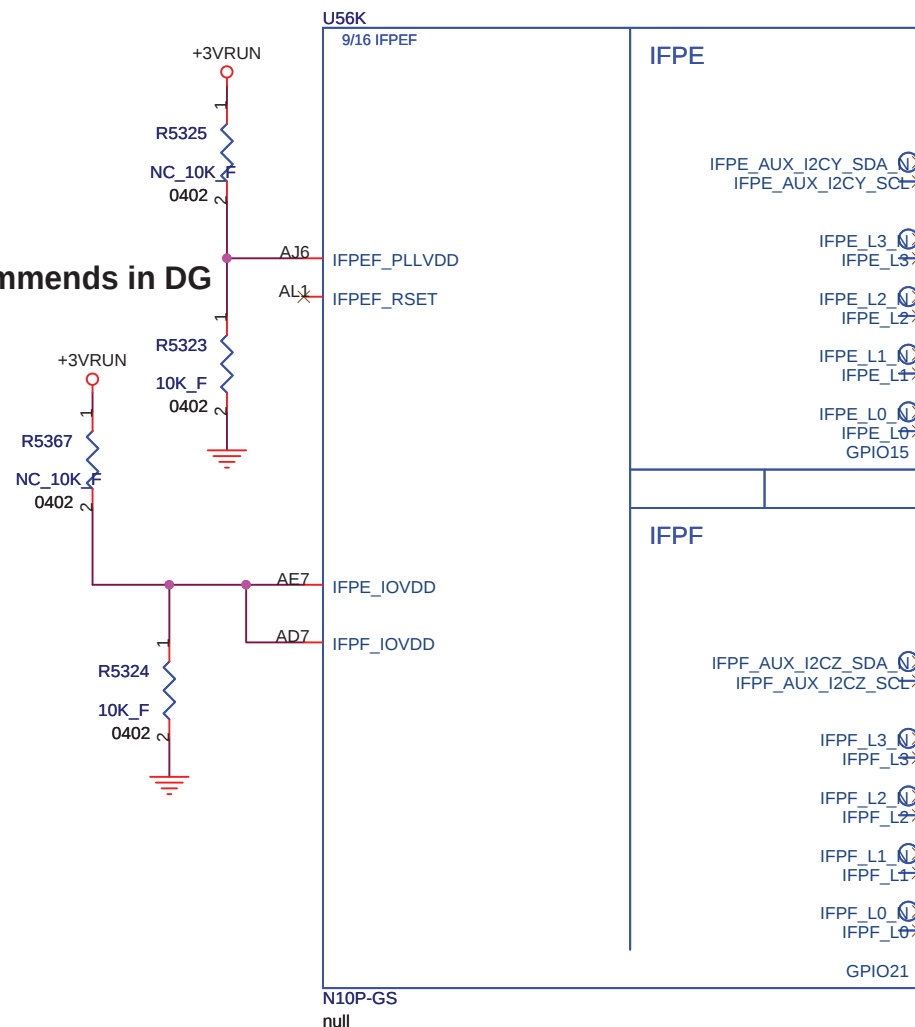
09/02/05 Reserve R5717 follow Mor-side propose.



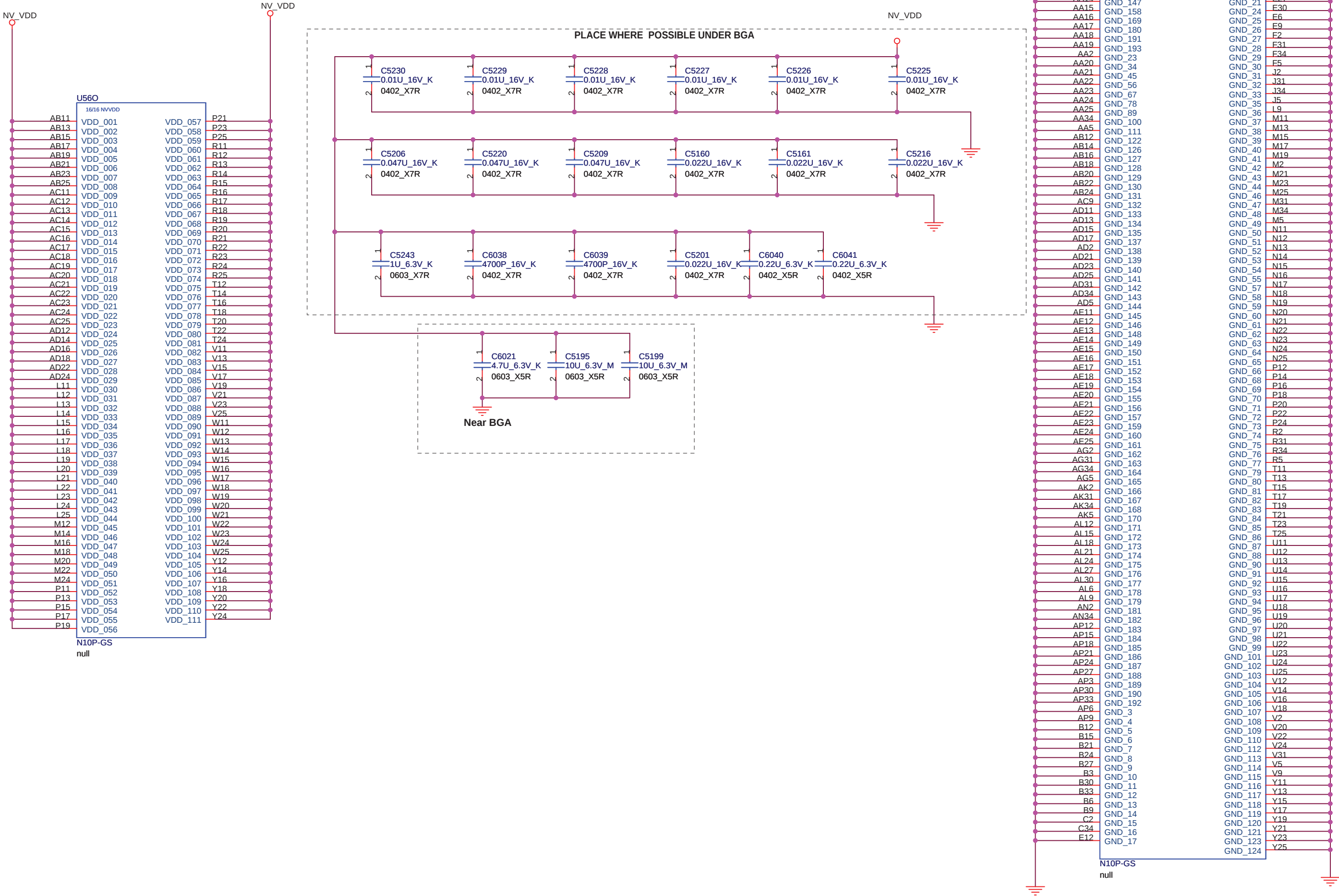
SIGNAL	I/O	Description
I2CA_SCL I2CA_SDA	I/O	For CRT VGA I2C_Compatibal Bus Signals
I2CB_SCL I2CB_SDA	I/O	NC(for DVI I2C_Compatibal Bus Signals)
I2CC_SCL I2CC_SDA	I/O	NC(Notebook DVI I2C_Compatibal Bus Signals)
I2CS_SCL I2CS_SDA	I/O	For VGA thermal I2C_Compatibal Bus Signals. Support a direct interface to the internal temperature sensor

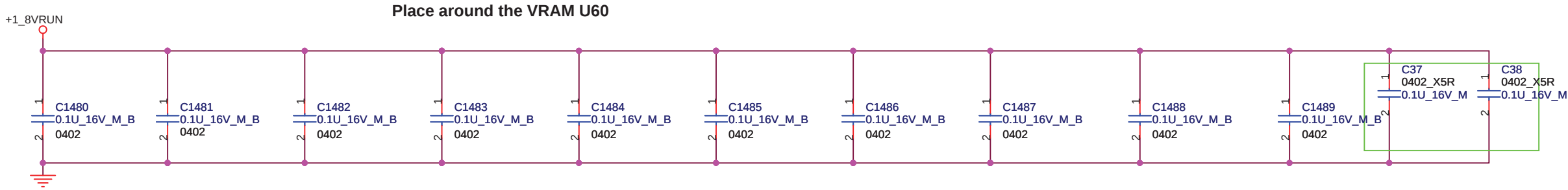


NVIDIA recommends in DG

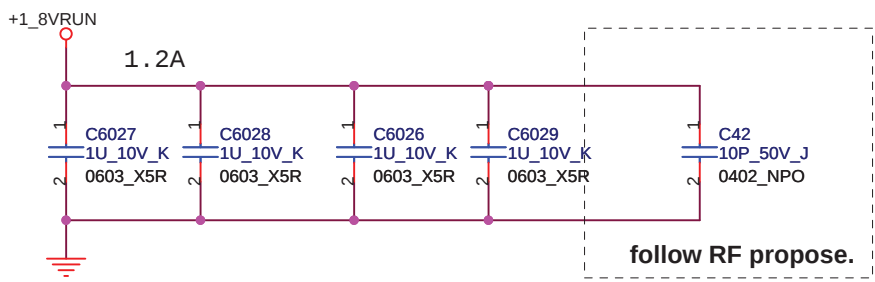
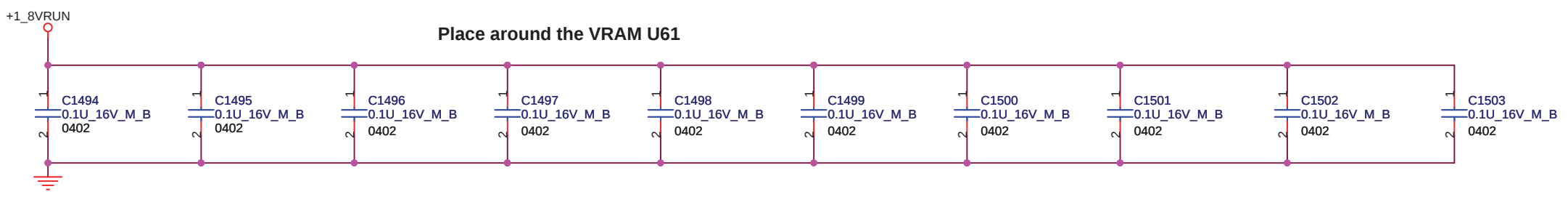
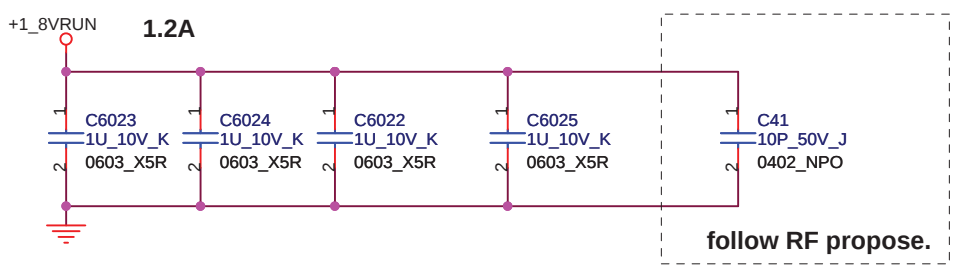


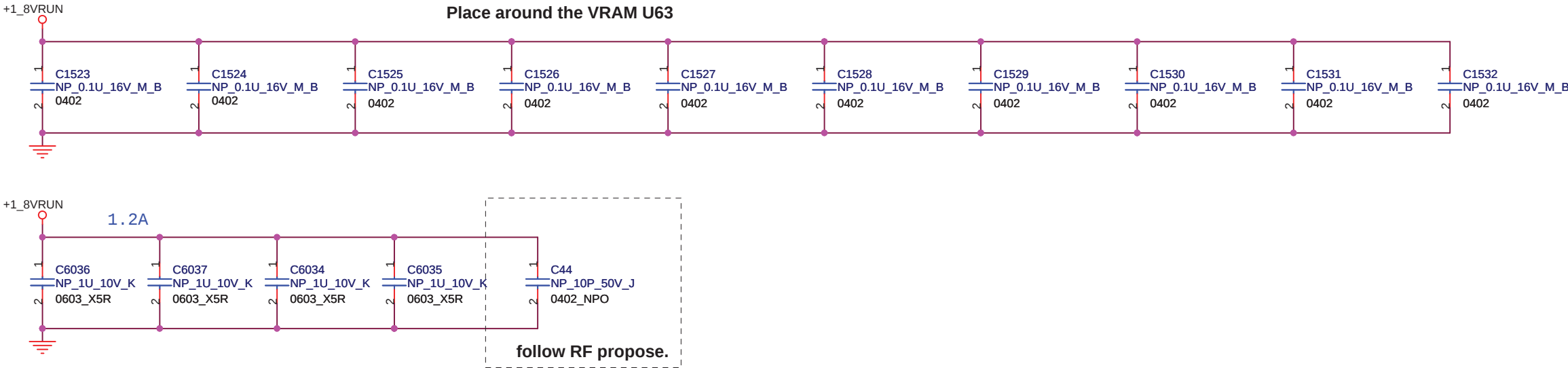
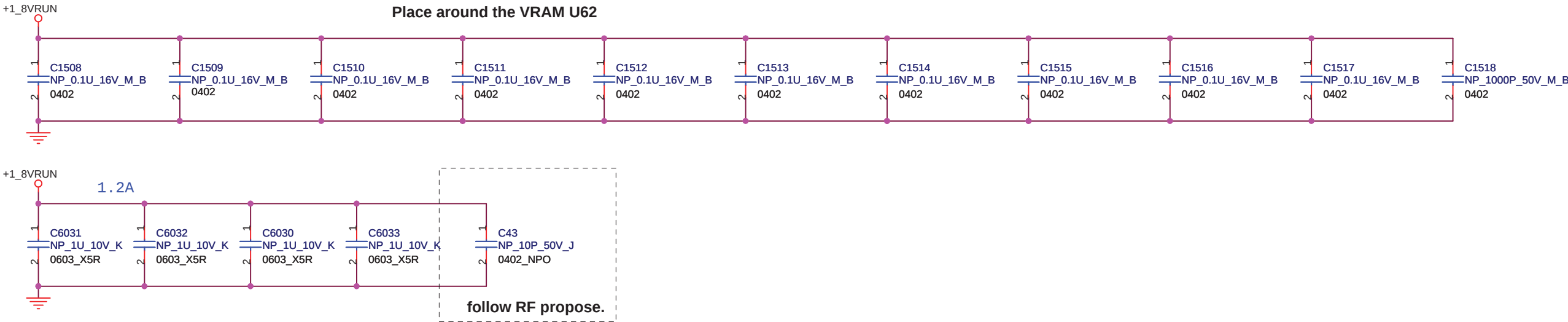
M9A0 NVVDD current N11P_LP1 is 21.94A N11M_GE1 is 16.29A

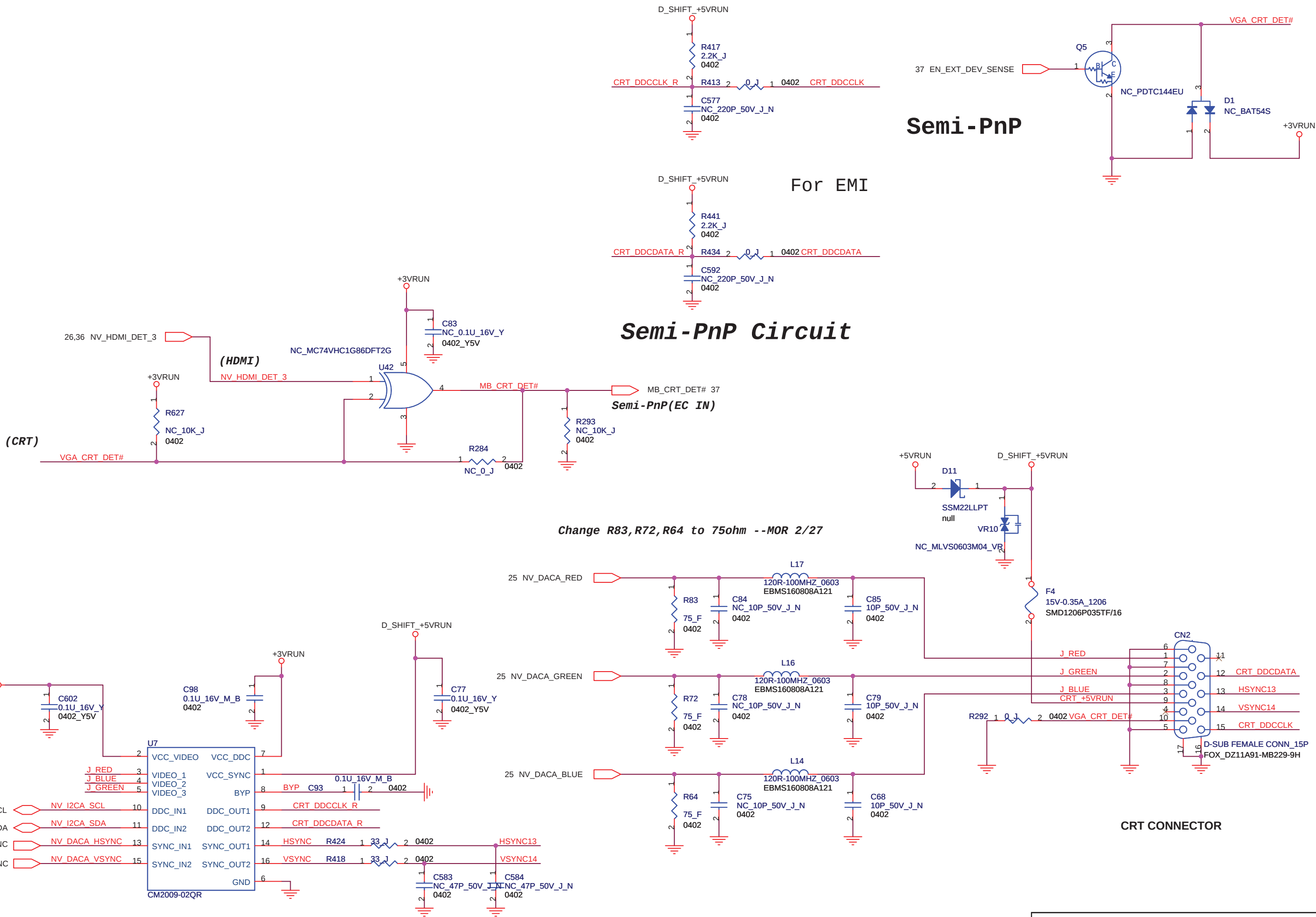




2009.0925
ADD C37,C38 for EMI request







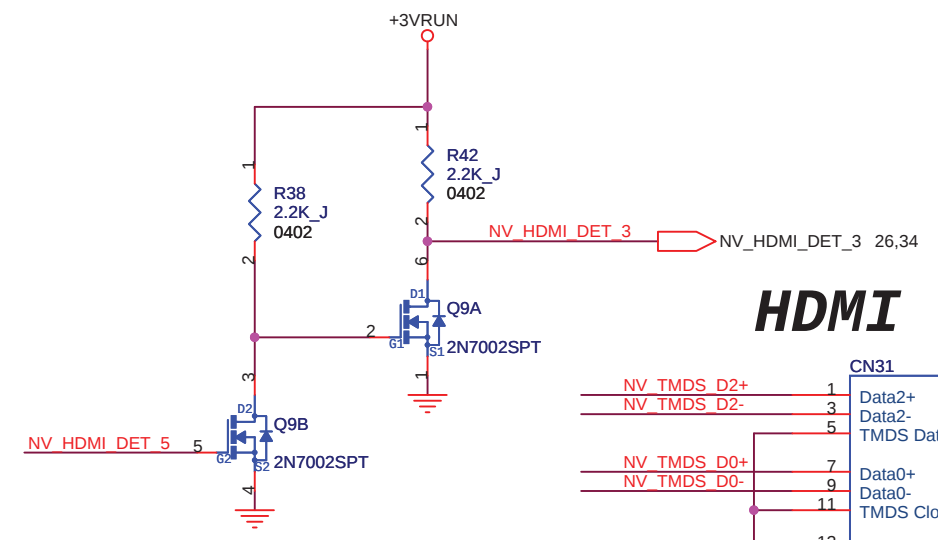
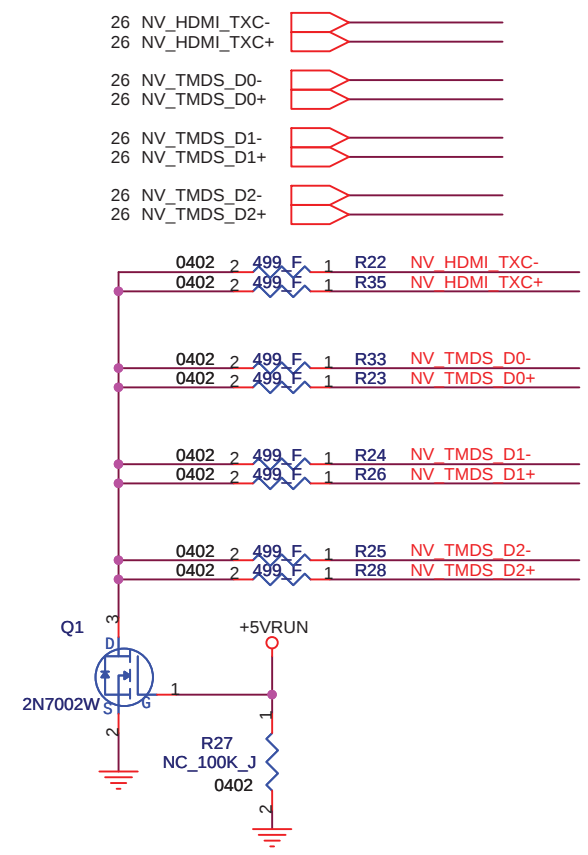
Semi-PnP

For EMI

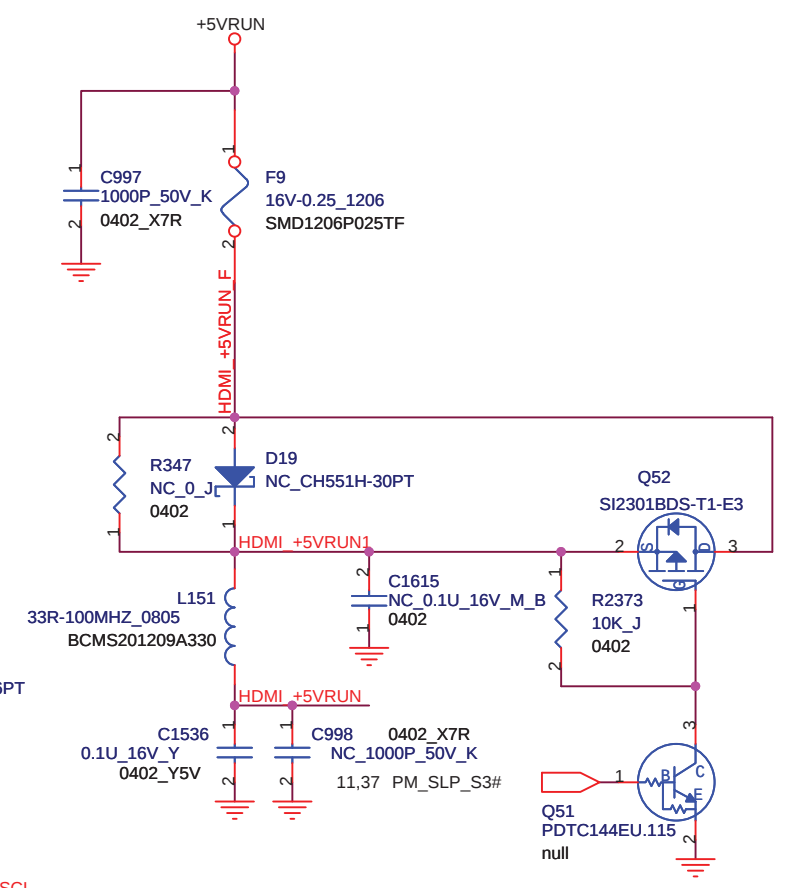
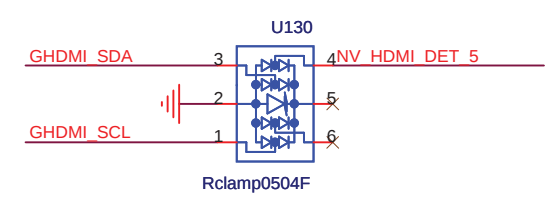
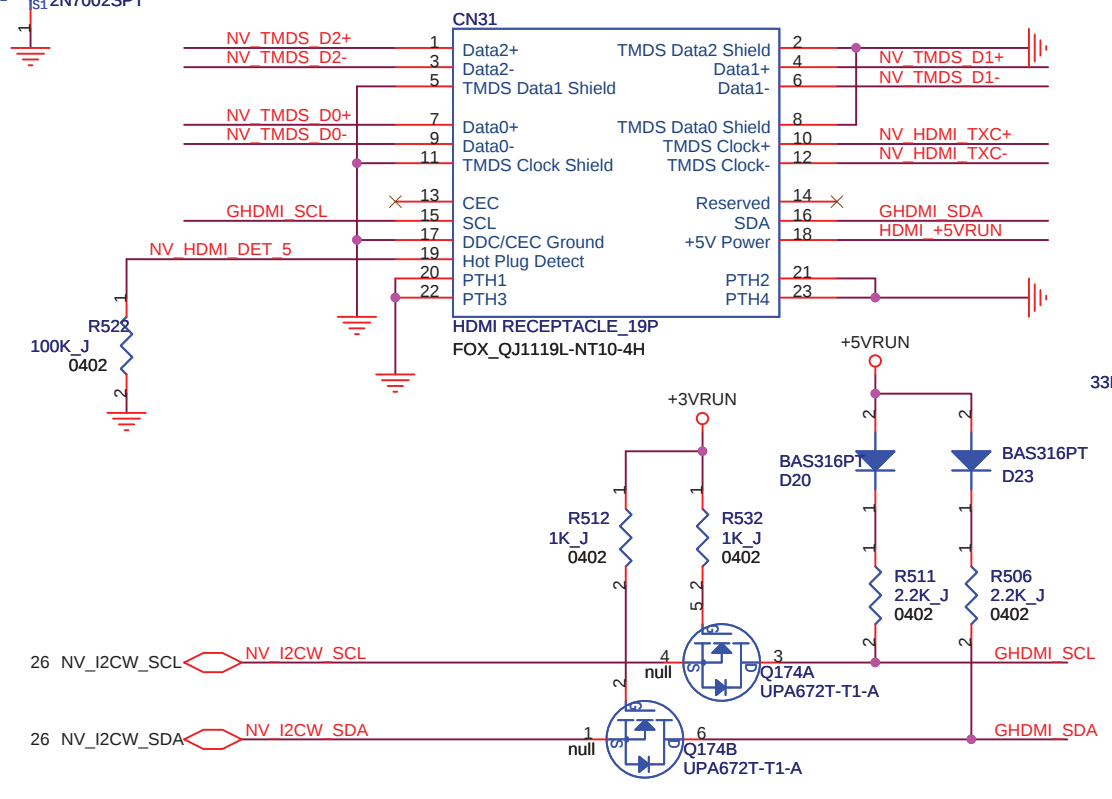
Semi-PnP Circuit

Change R83,R72,R64 to 75ohm --MOR 2/27

CRT CONNECTOR



HDMI CONNECTOR

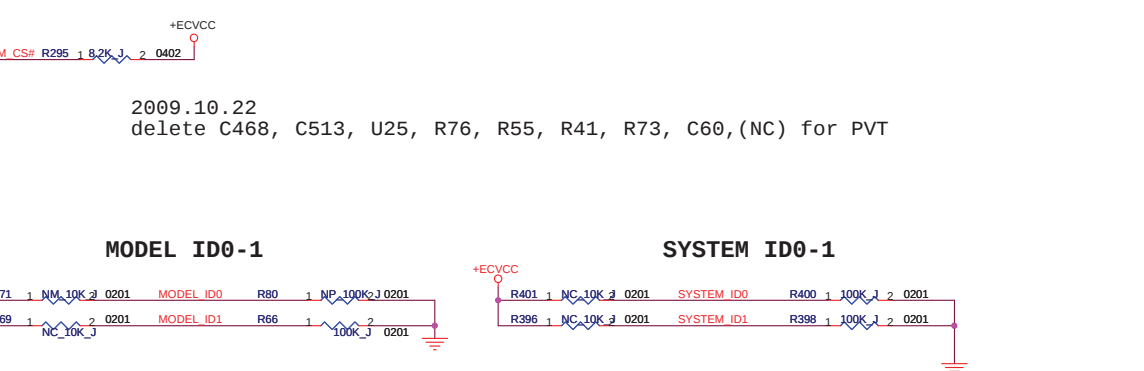
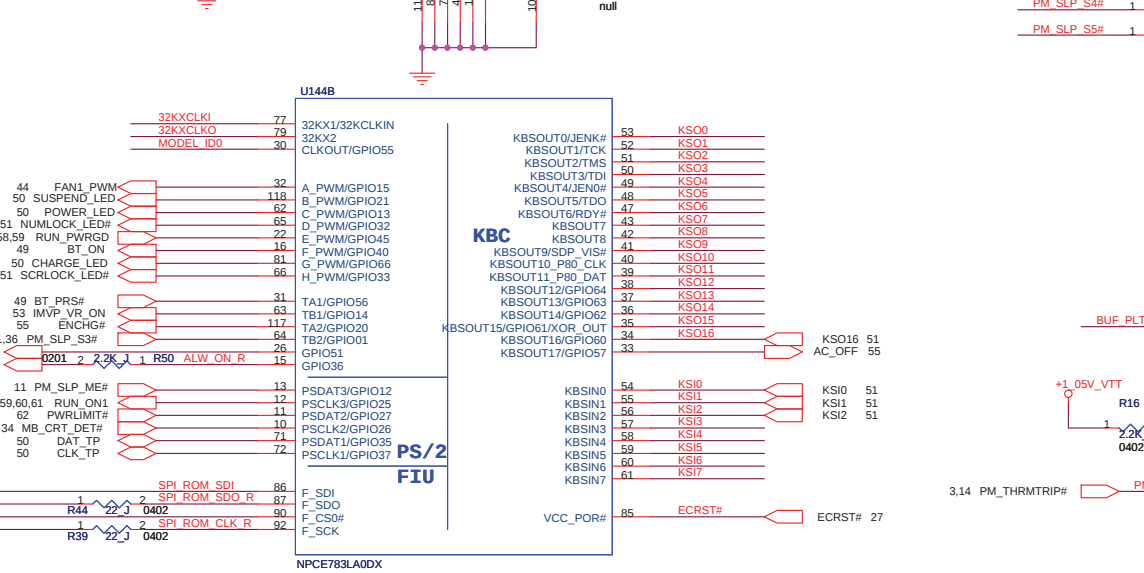
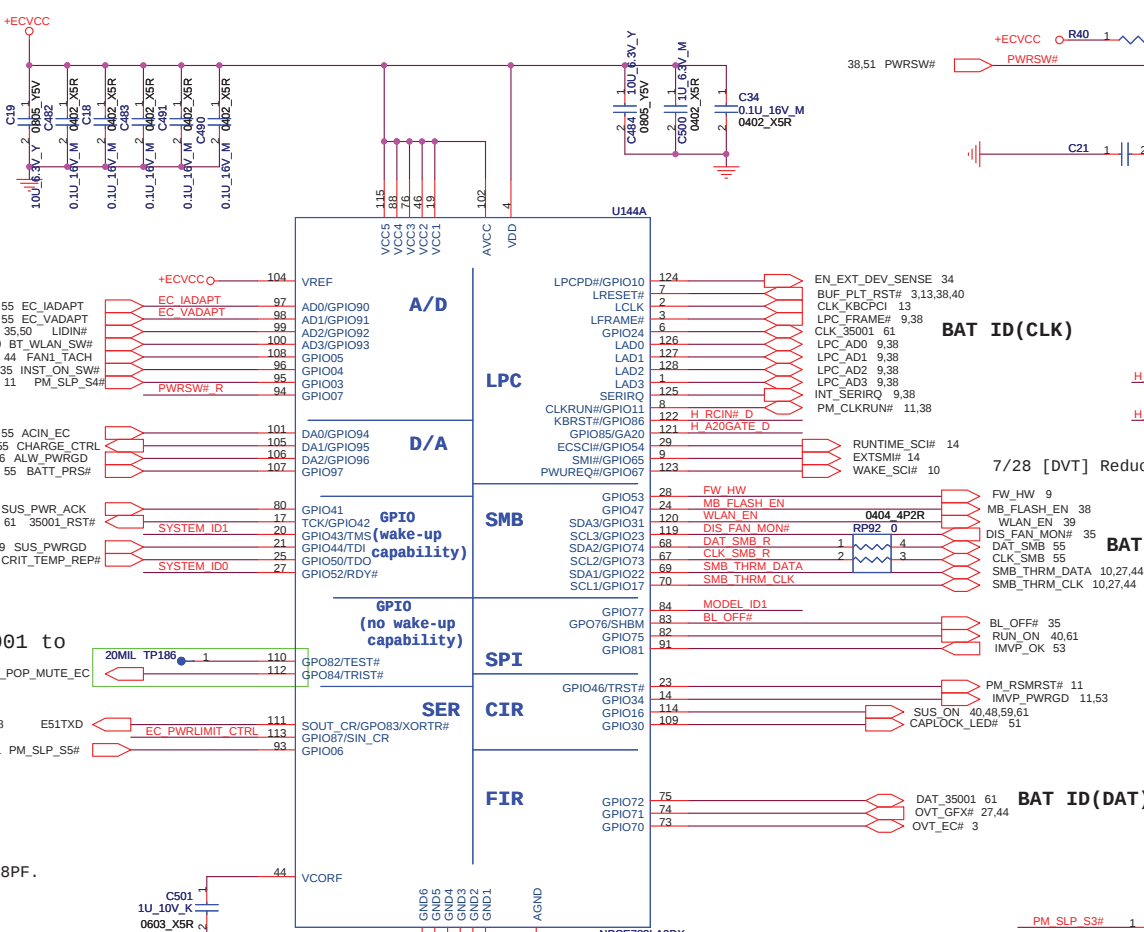
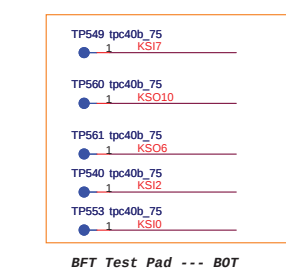
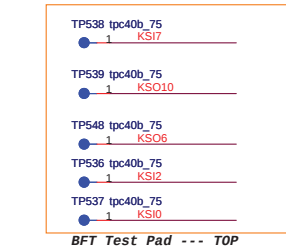
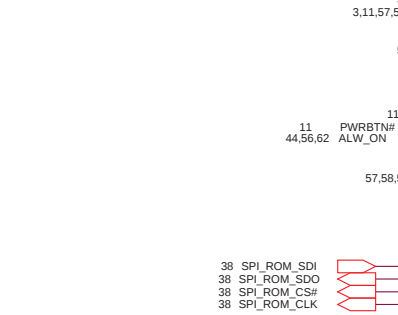
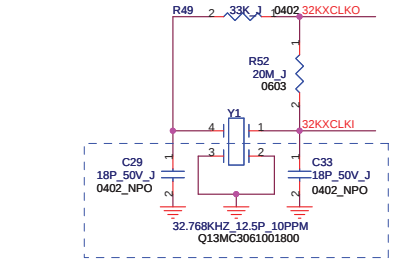


FOXCONN		HON HAI Precision Ind. Co., Ltd.	
Title HDMI		CCPBG - R&D Division	
Size A3	Document Number M9A0_MP	Rev 1.1	
Date:	Friday, October 30, 2009	Sheet	36 of 73

2009.10.19
change C6256 from 1C-2B20102-K001 to
1C-2B20473-K300 for PVT

2009/09/10
Delete Net name 'AC_Present'
add test point

7/17 [DVT] - C26/C27 change to 18PF.



ID1 (Reserve)	ID0	SKU
0	0	SLI+N11P
0	1	SILEGO+N11M
1	0	
1	1	

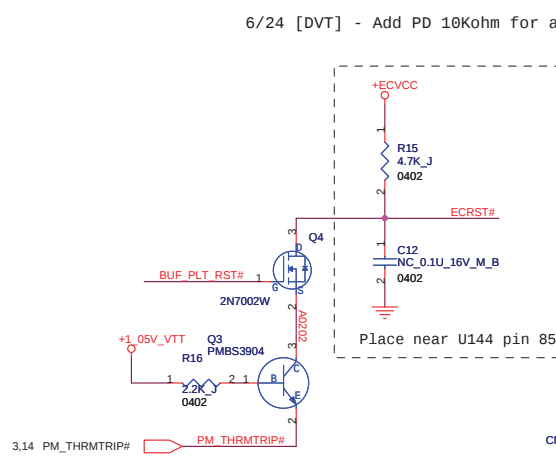
ID1	ID0	SKU
0	0	M9A0
0	1	Reserve
1	0	Reserve
1	1	Reserve

BAT ID(CLK)

BAT

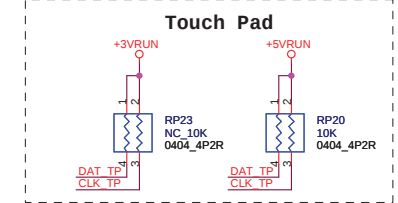
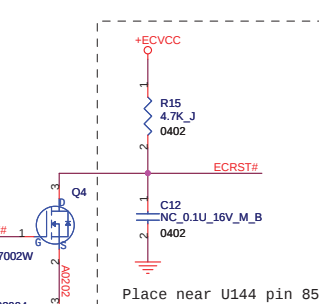
BAT ID(DAT)

PM_SLP_S3#
PM_SLP_S4#
PM_SLP_S5#

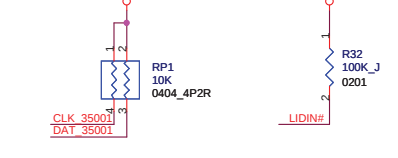


PCH/ALS/THM/Amp/dGPU

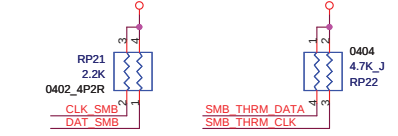
6/24 [DVT] - Add PD 10Kohm for avoid the abnormal behavior.



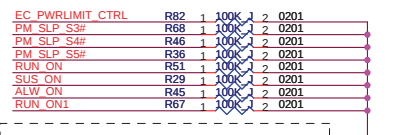
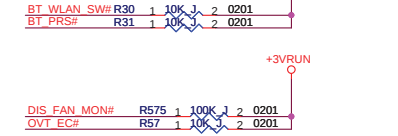
Identify BATT ID



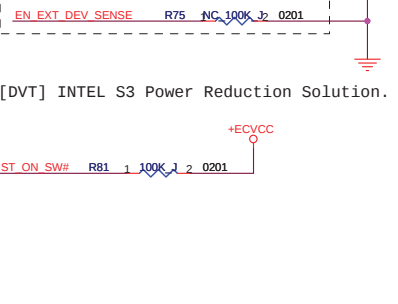
SMBUS Channel 2



SMBUS Channel 1

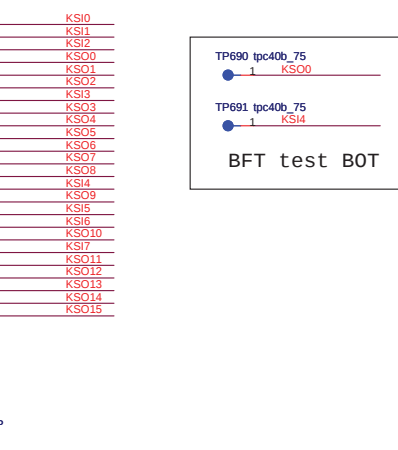


7/24 [DVT] INTEL S3 Power Reduction Solution.

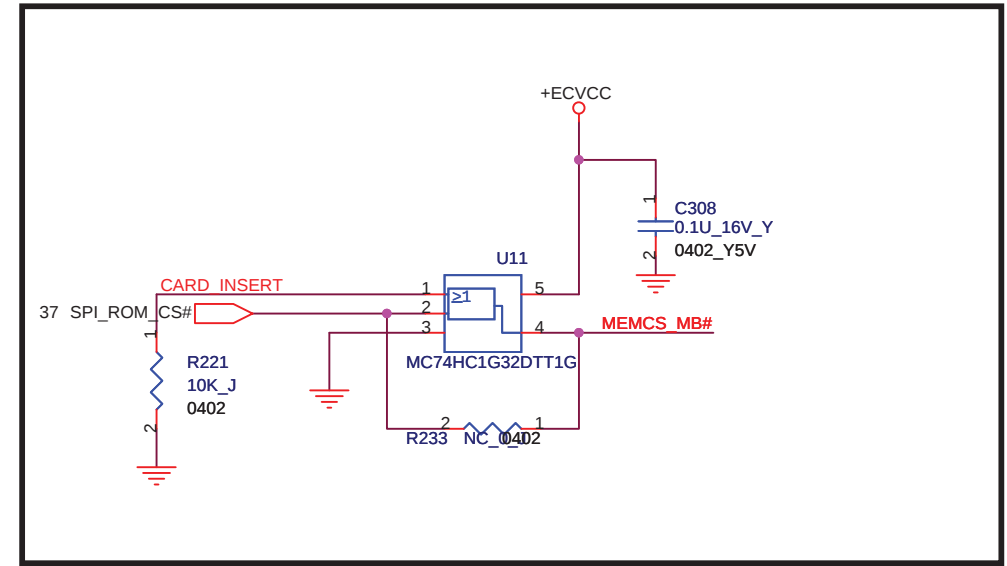
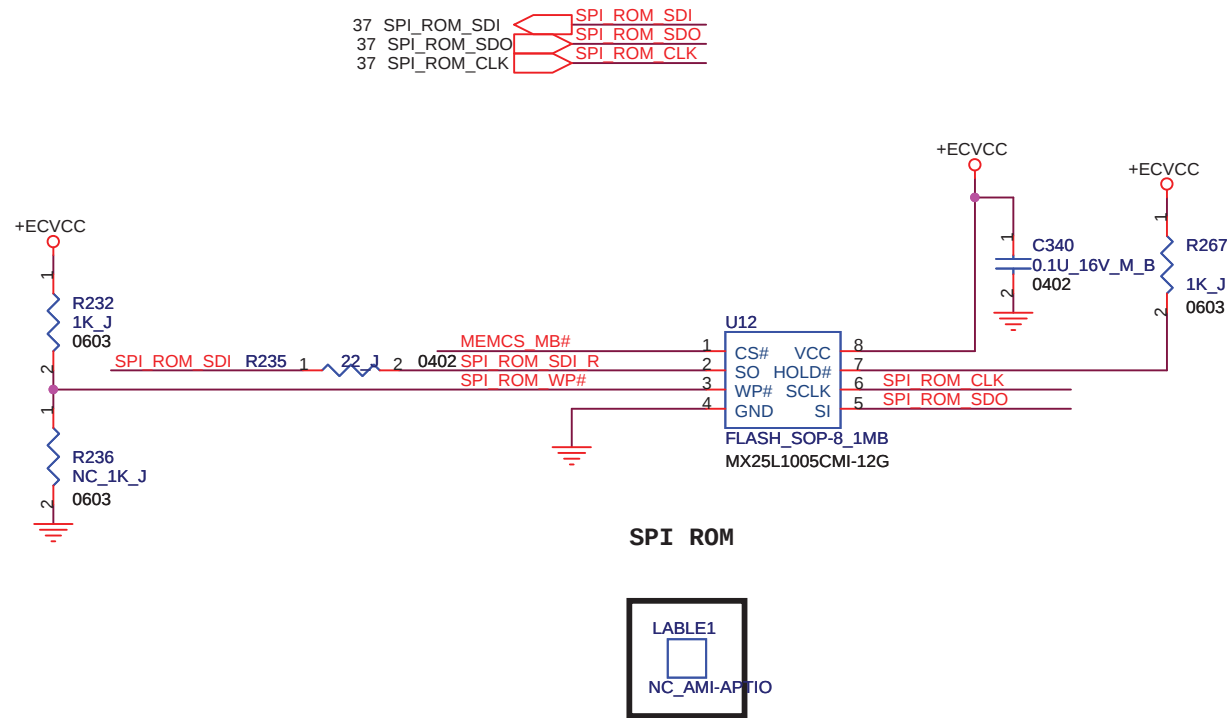


2009.10.23

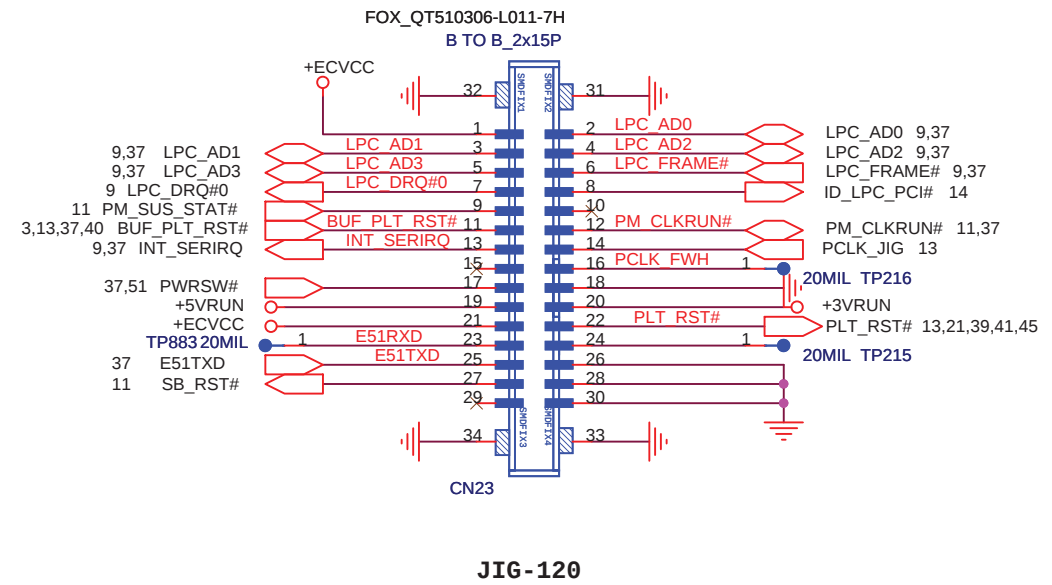
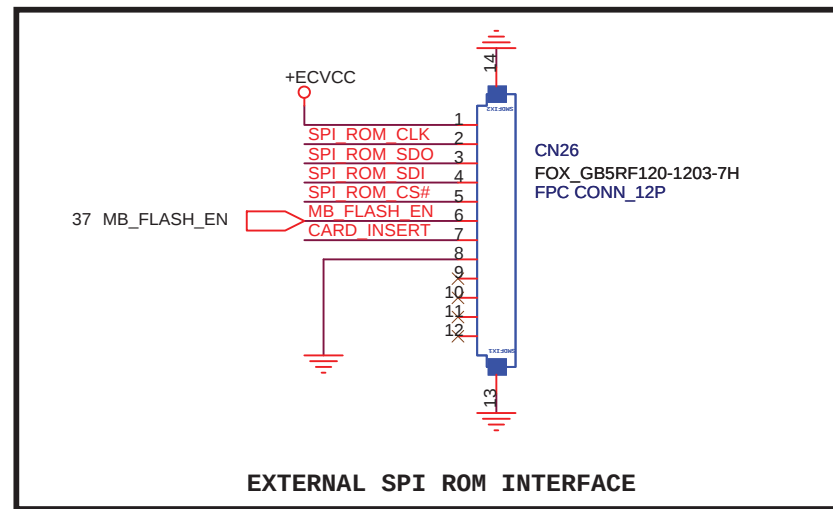
Add test point TP690,TP691 for PVT

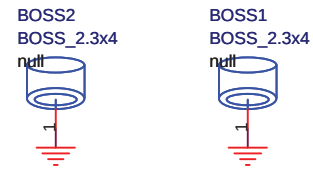


ID1	ID0	SKU
0	0	M9A0
0	1	Reserve
1	0	Reserve
1	1	Reserve



2009.10.23
Delete TP531,TP530,TP532,TP533,TP529,TP520,519,TP518

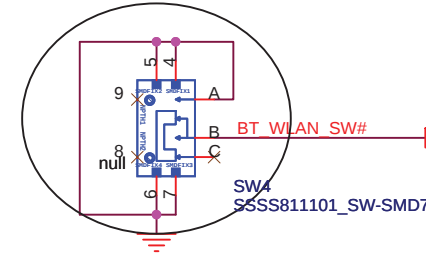




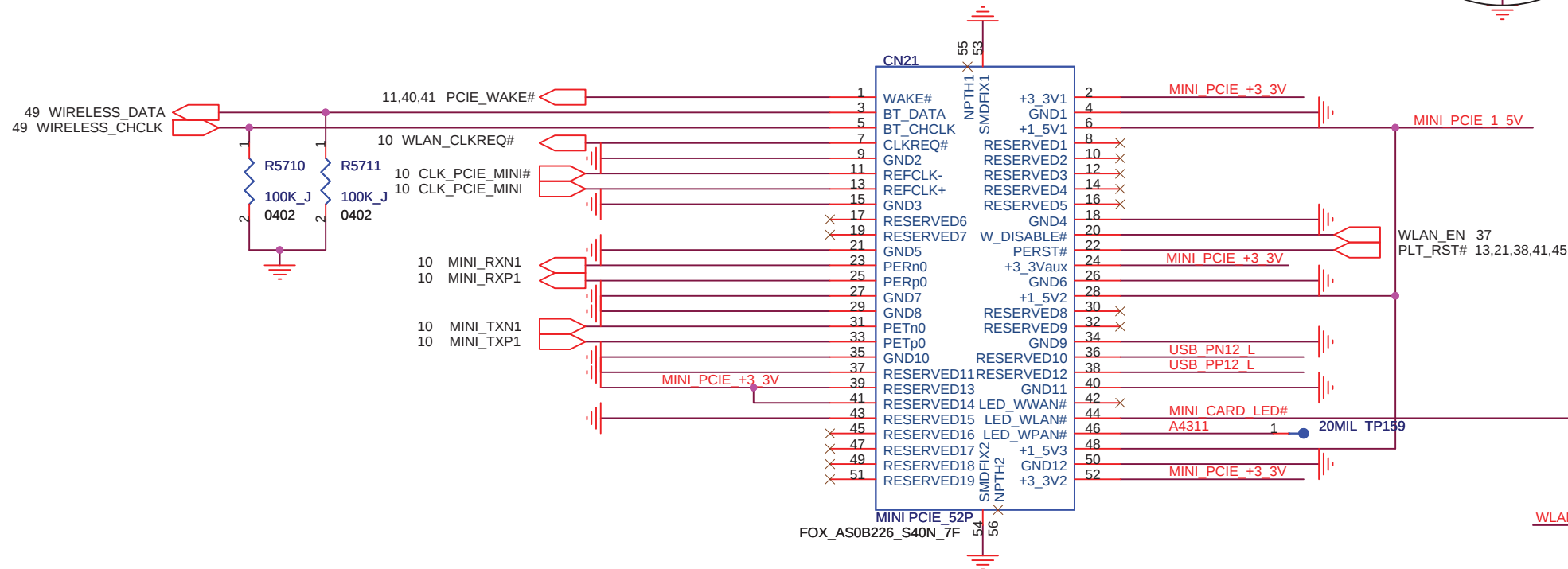
2009.0922
change BOSS1,BOSS2 to 1M-1F40M20-1500 for ME request

SW4.C pin delete and SW4.A connect to GND.

DVT



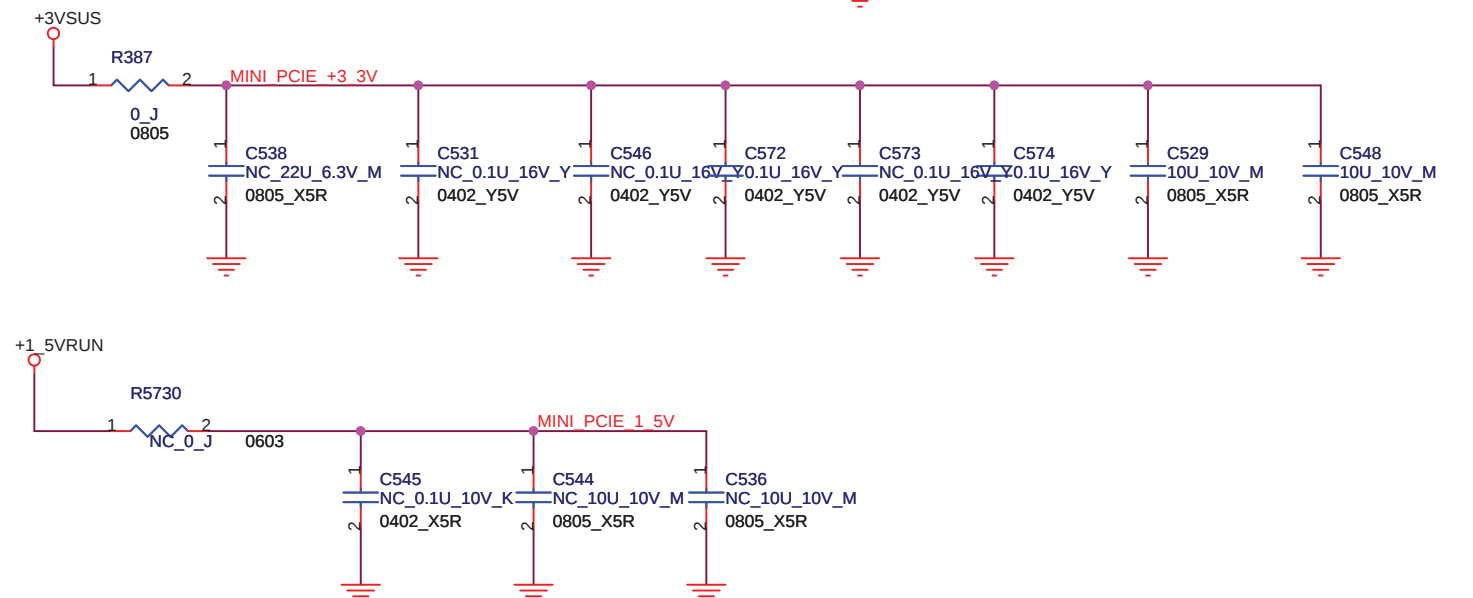
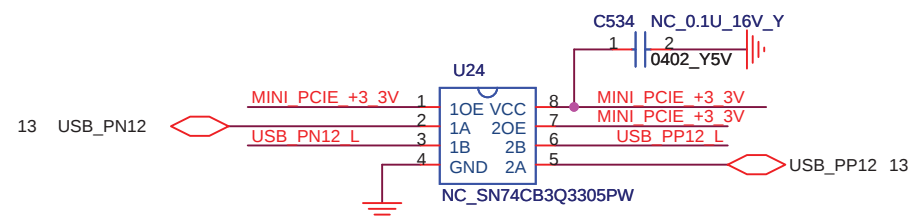
TP640 tpc40t_50 1 BT_WLAN_SW#

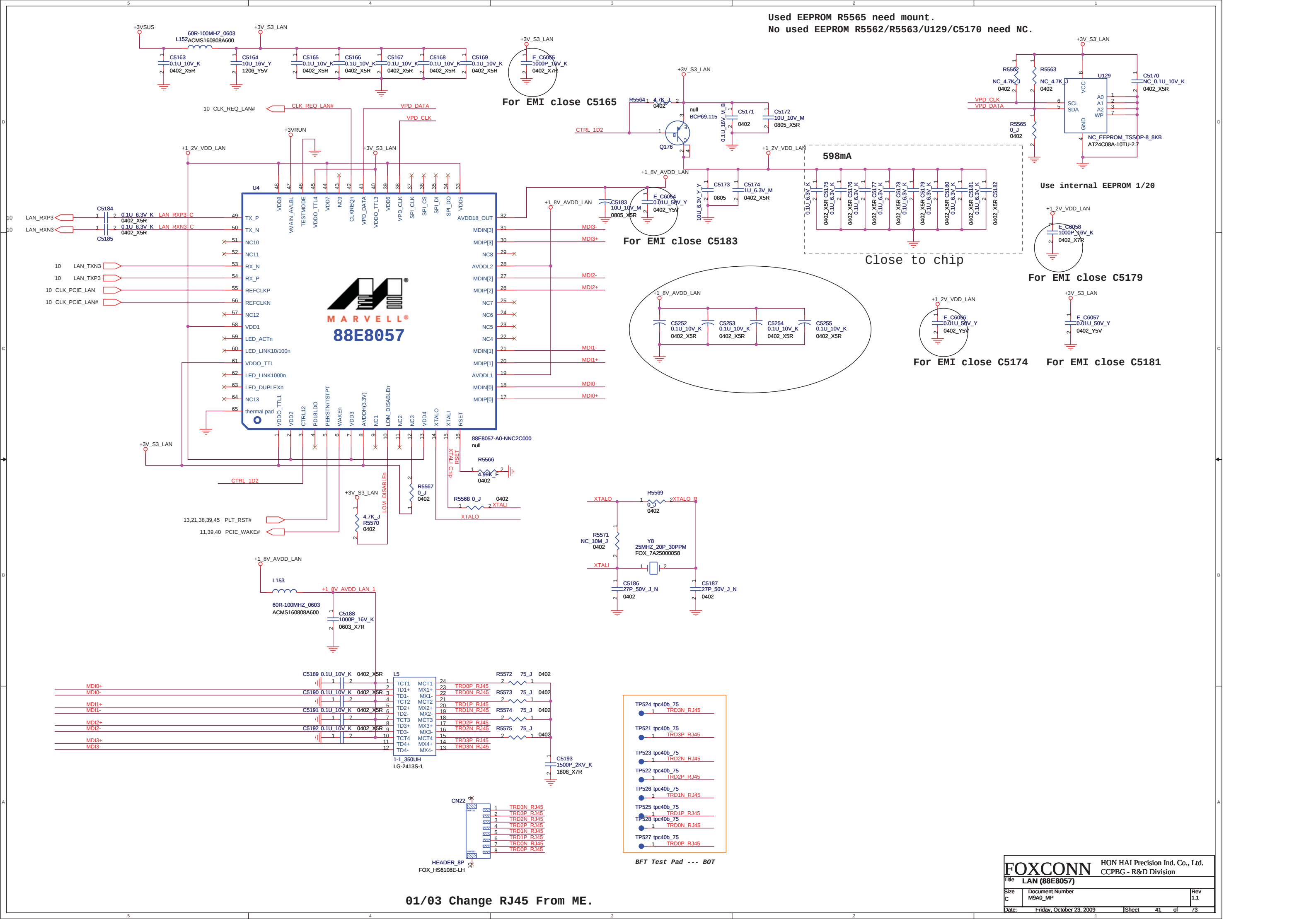


2009.0922
change CN21 TO 1N-1052000-0000 for ME request

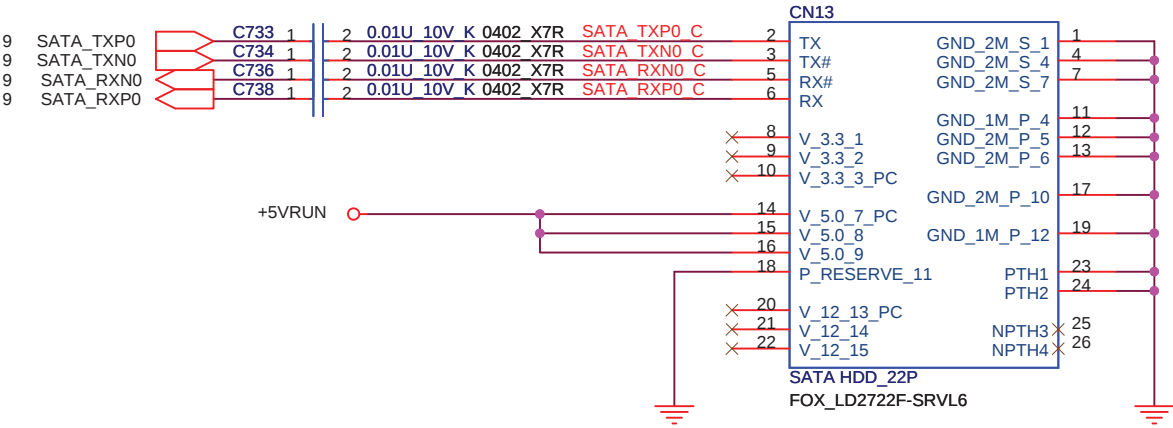
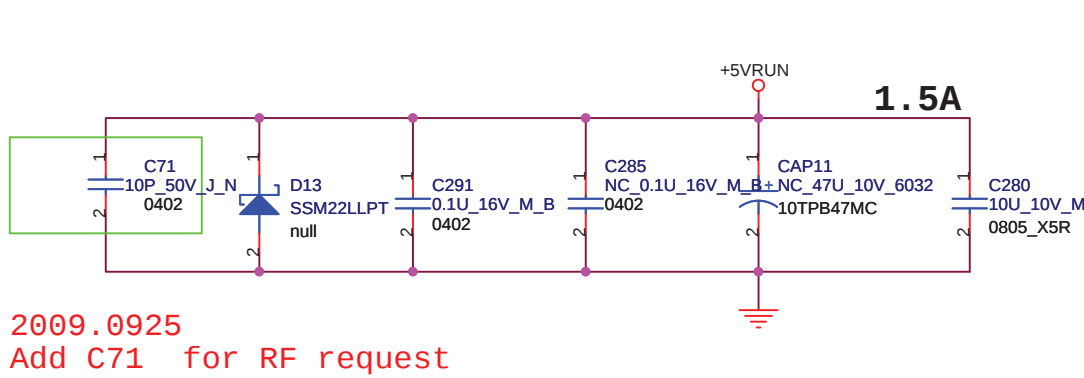
20MIL TP160 1 CLK PCIE MINI#
20MIL TP161 1 CLK PCIE MINI

For DVT SI validation,
Top-side and closer Pin11.13

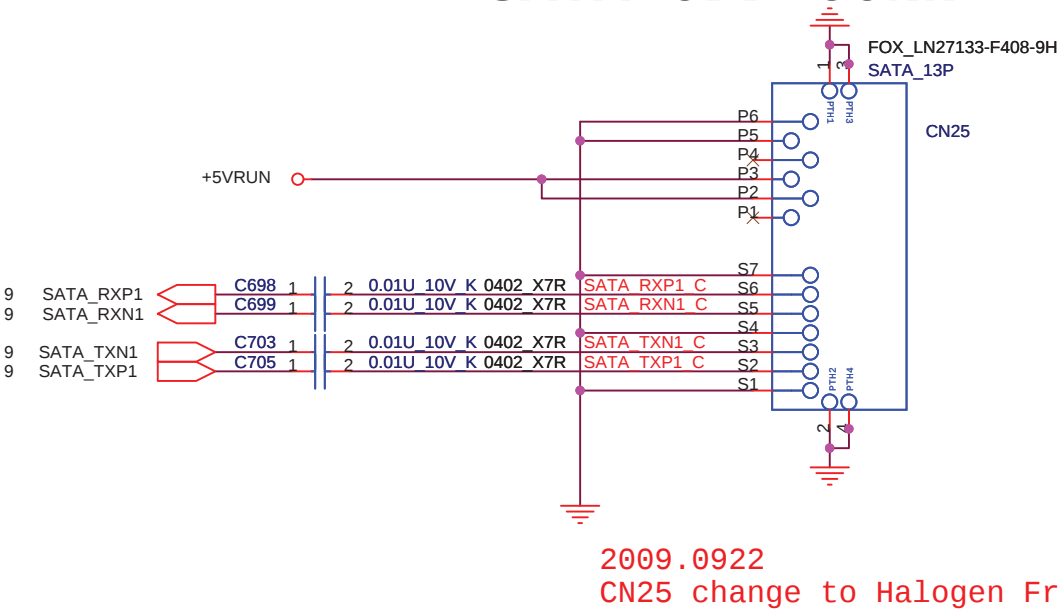
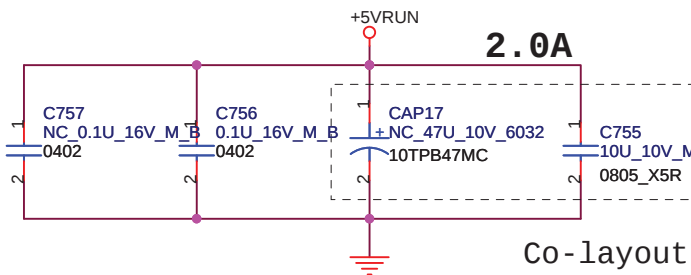


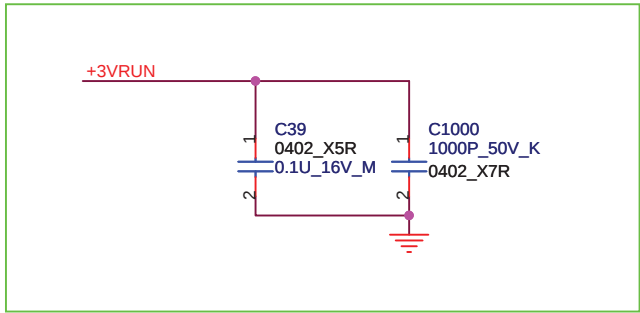


SATA HDD CONN



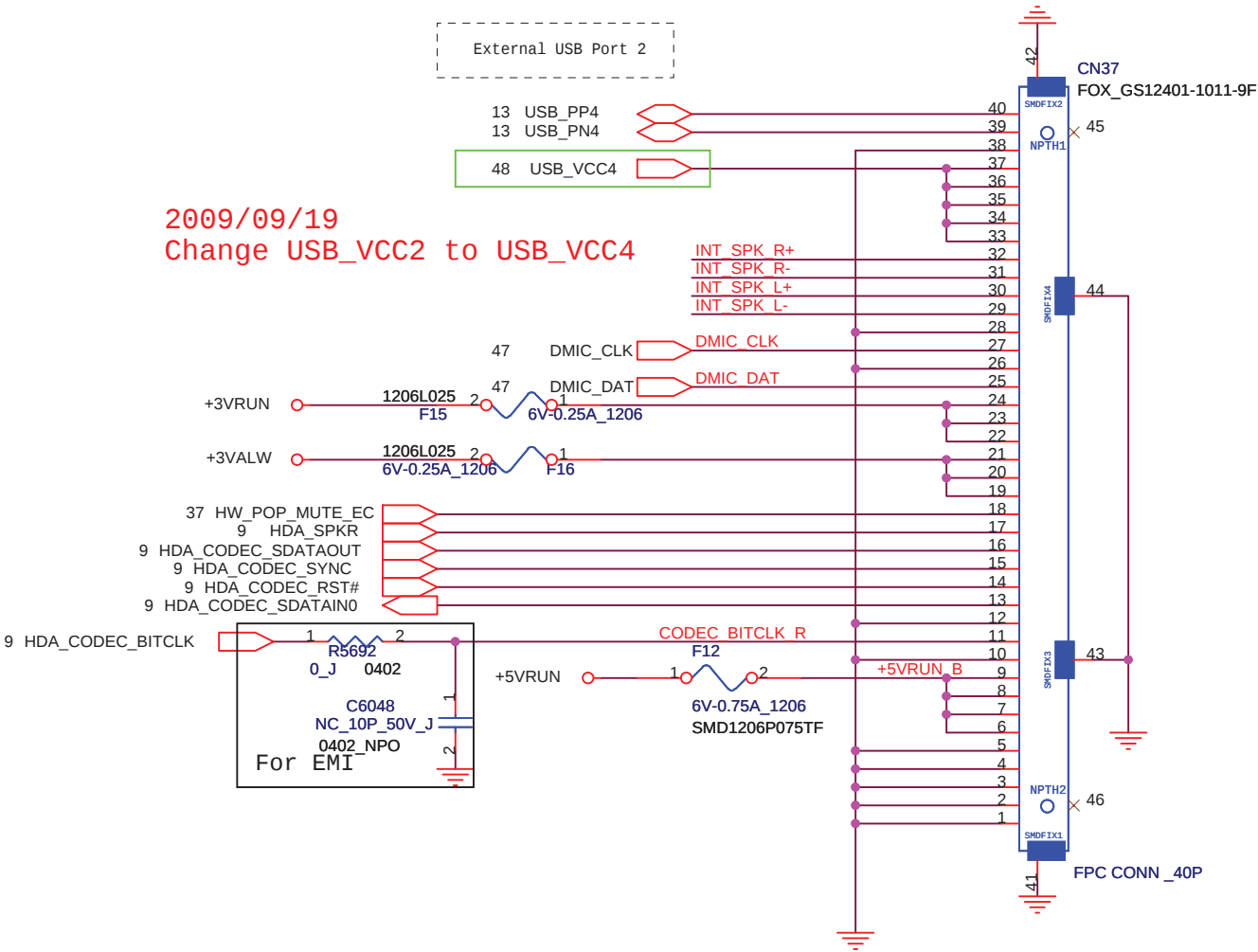
SATA ODD CONN



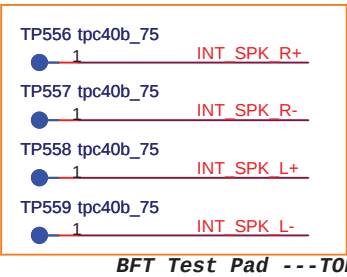
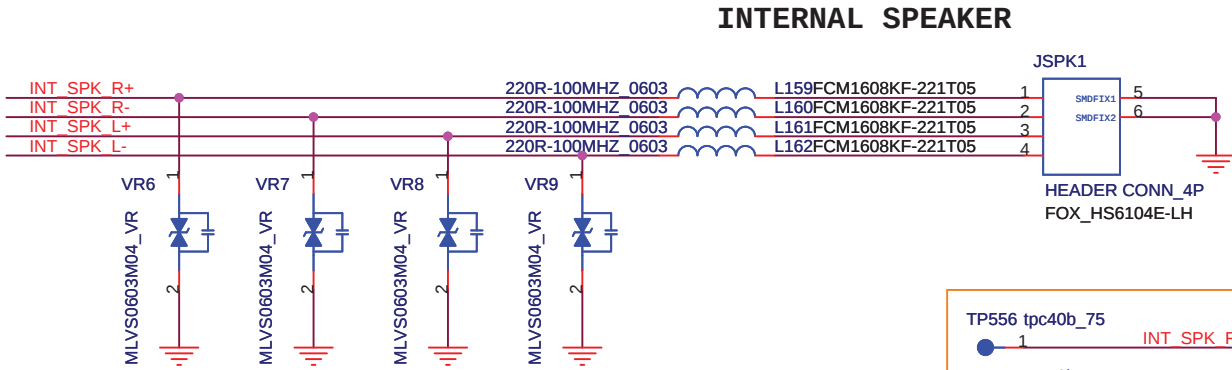


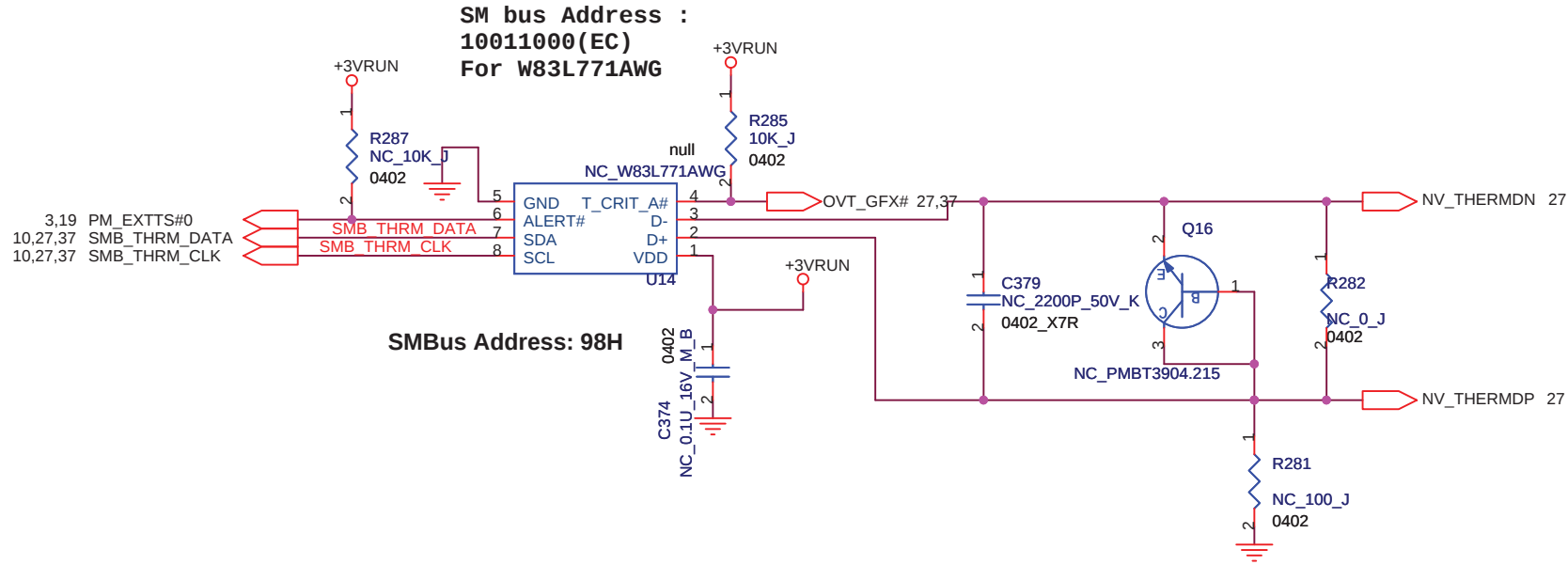
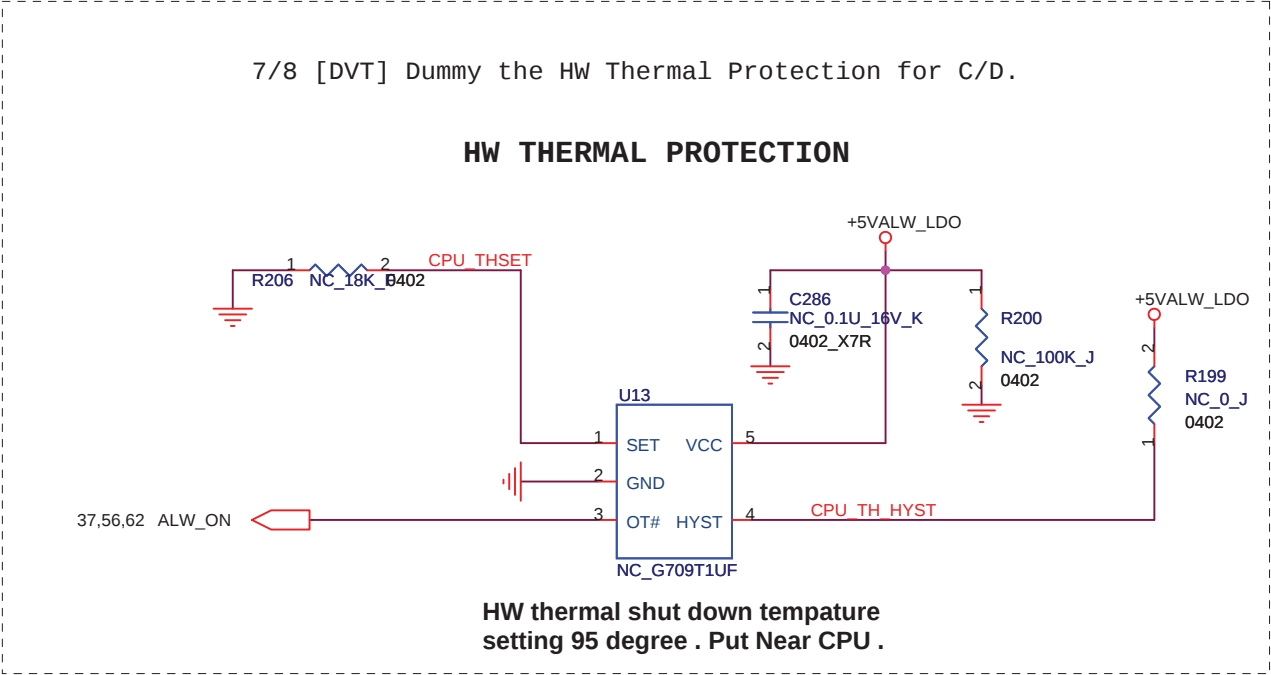
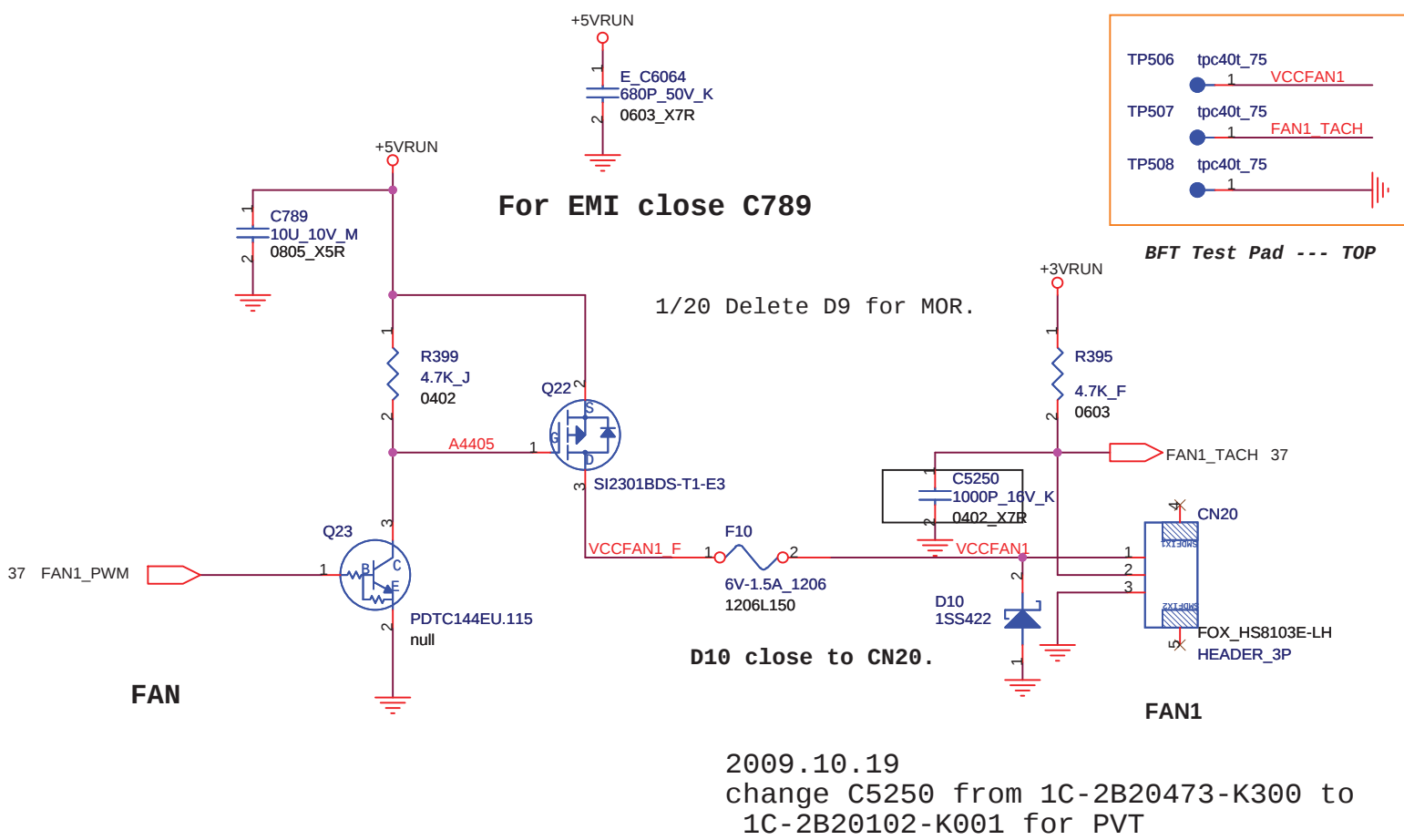
2009.0925
ADD for EMI request

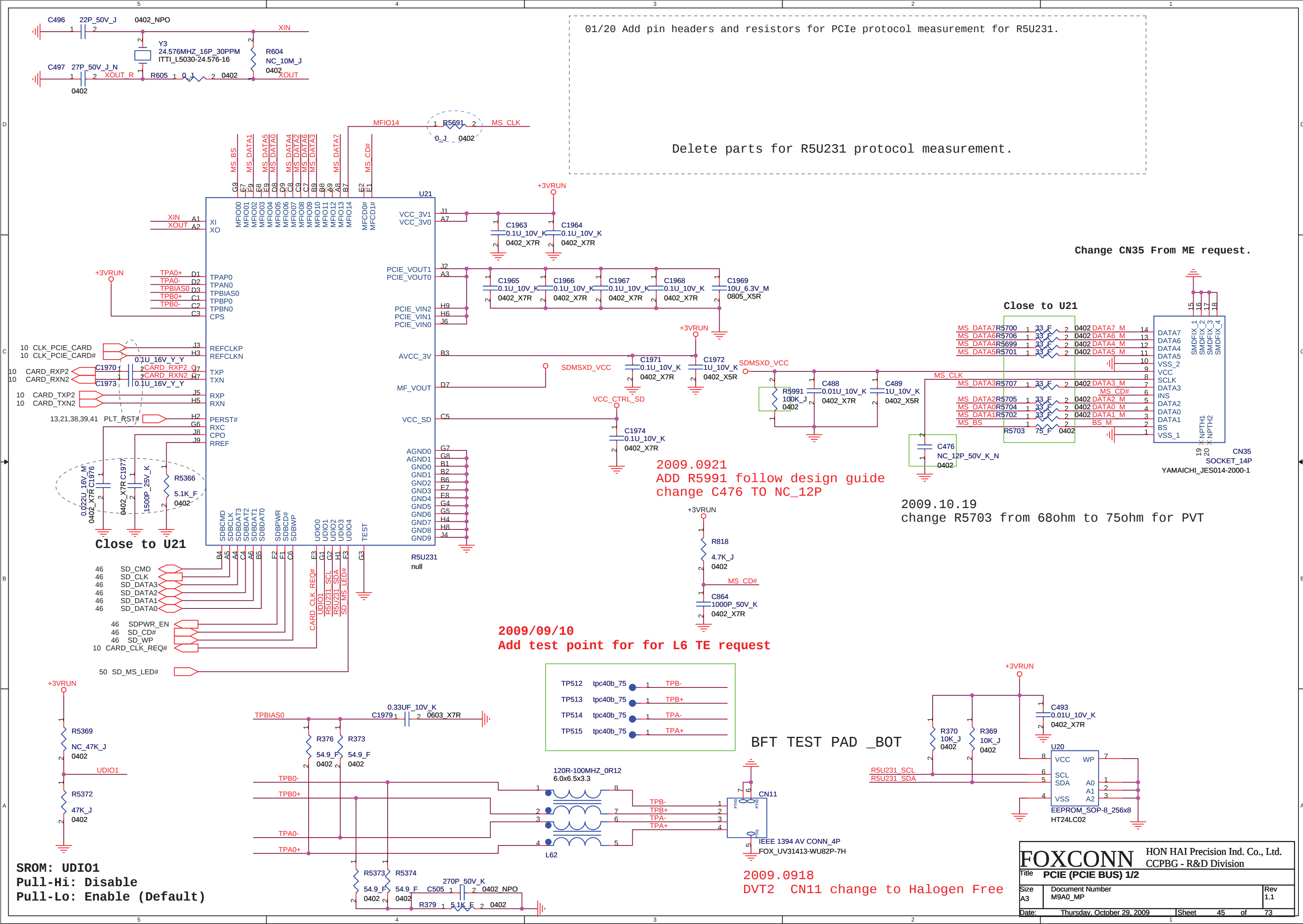
2009/09/19
Change USB_VCC2 to USB_VCC4

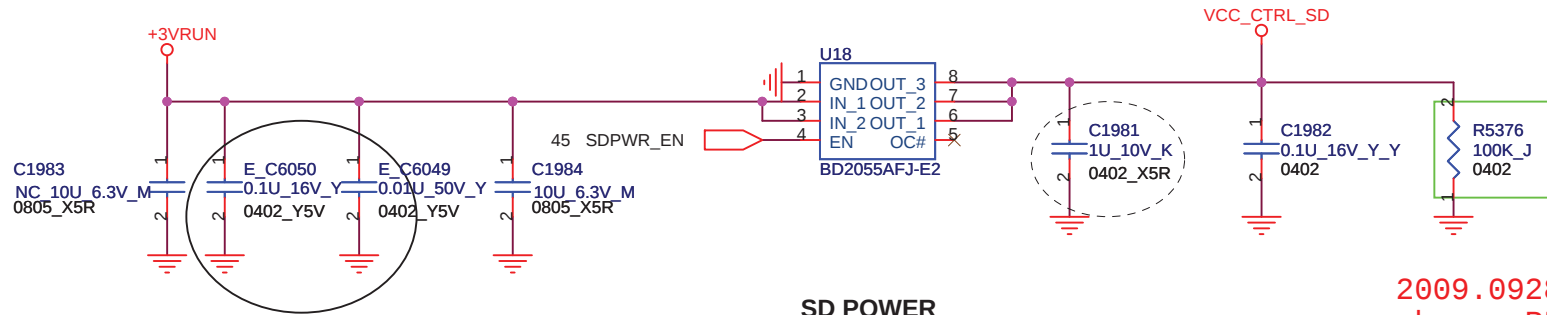


Audio & USB WTB CONN.









For EMI close C1983

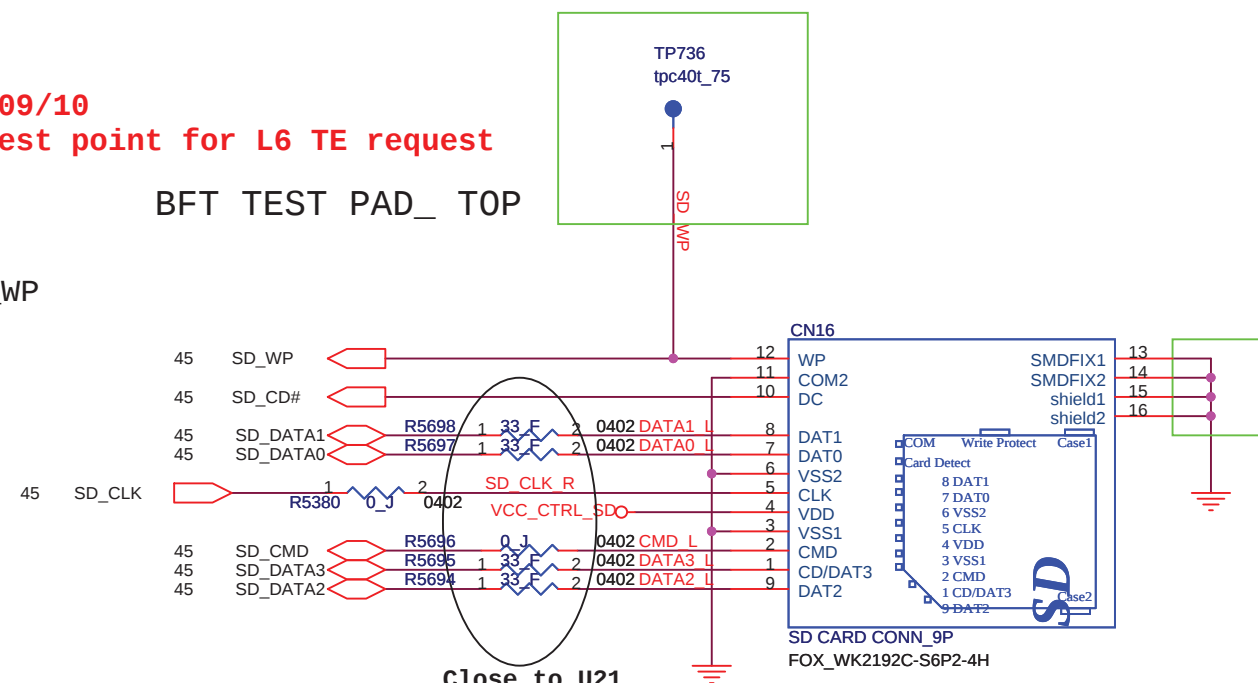
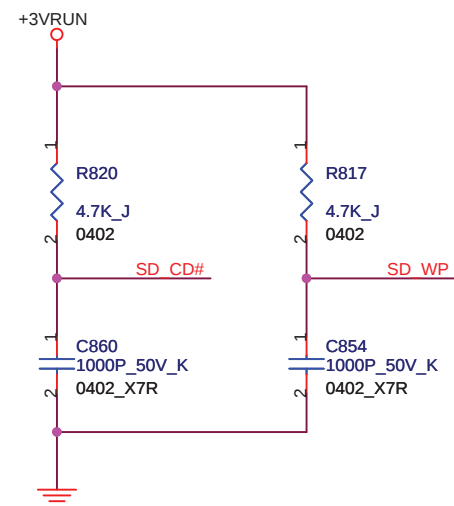
SD POWER

2009.0928
change R5376 to 100K follow design guide

2009/09/10
Add test point for L6 TE request

BFT TEST PAD_ TOP

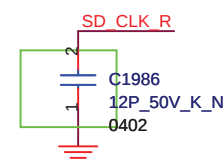
2009.10.23
change net SD_WP# to SD_WP



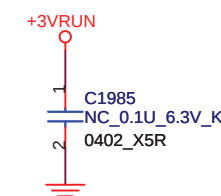
Close to U21

SD CONN.

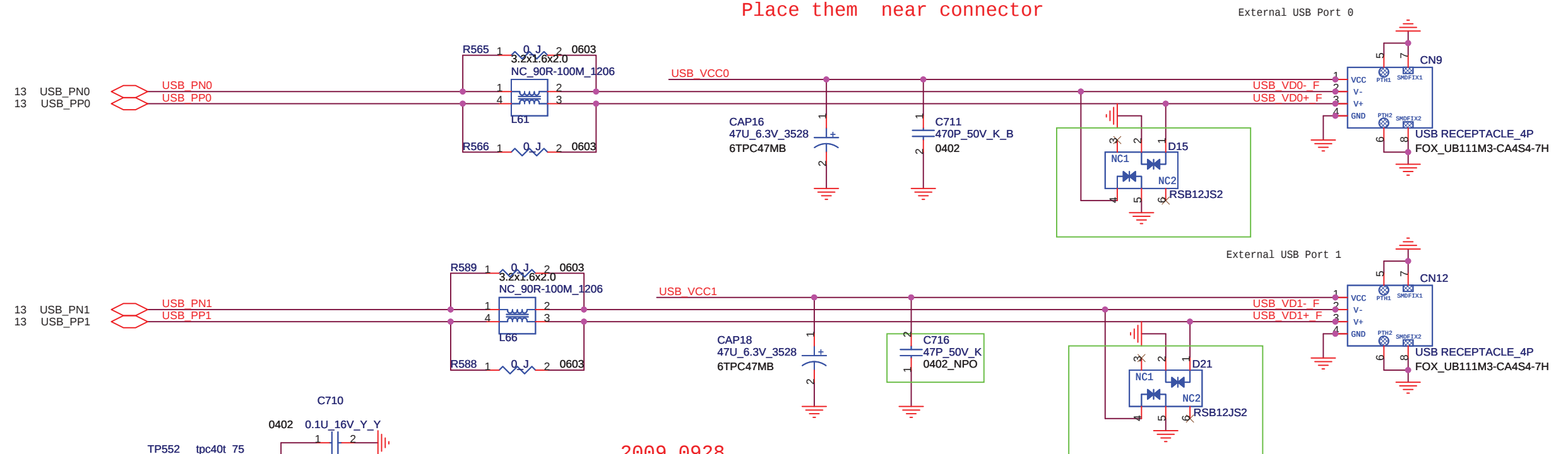
For EMI



2009.0921
change C1986 to 12p

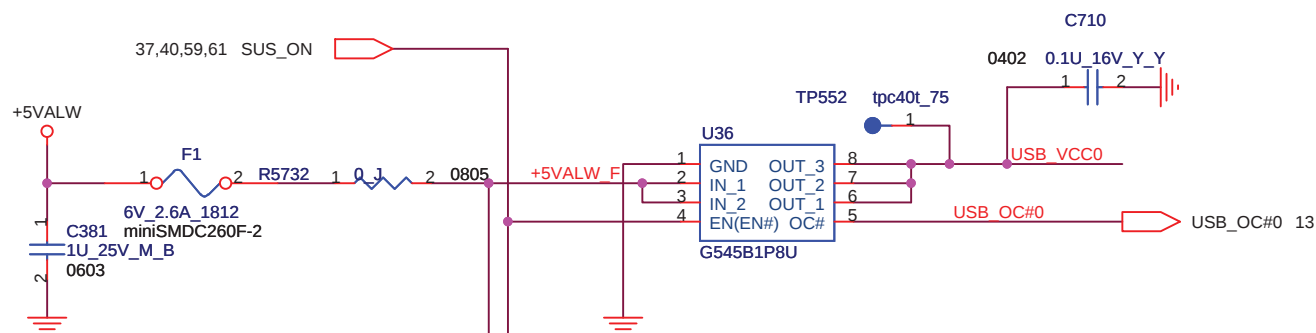


2009.0921
change D15,D21from NC to mount
Place them near connector

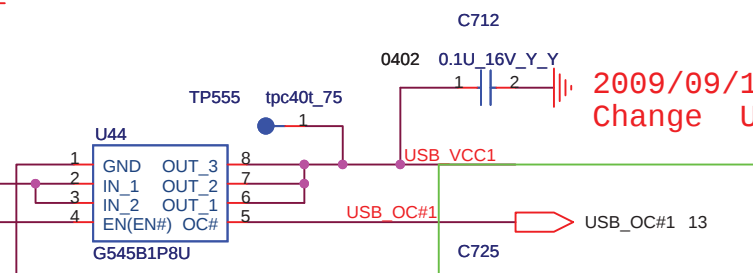


2009.0928
change C716 to 47P for RF request

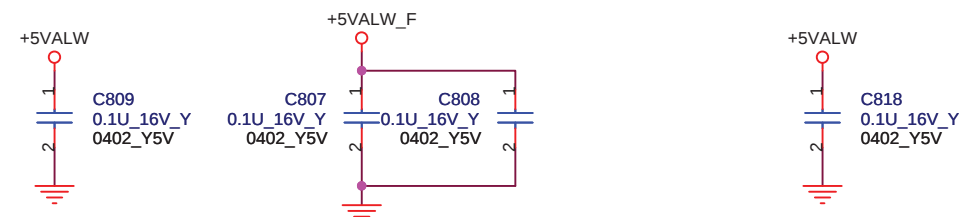
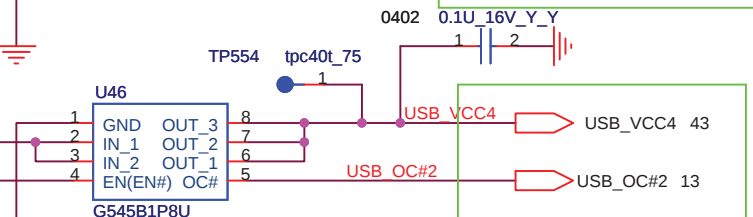
2009.0918
DVT2 CN9,CN12 change to Halogen Free



2009/09/19
Change USB_OC#0 to USB_OC#1



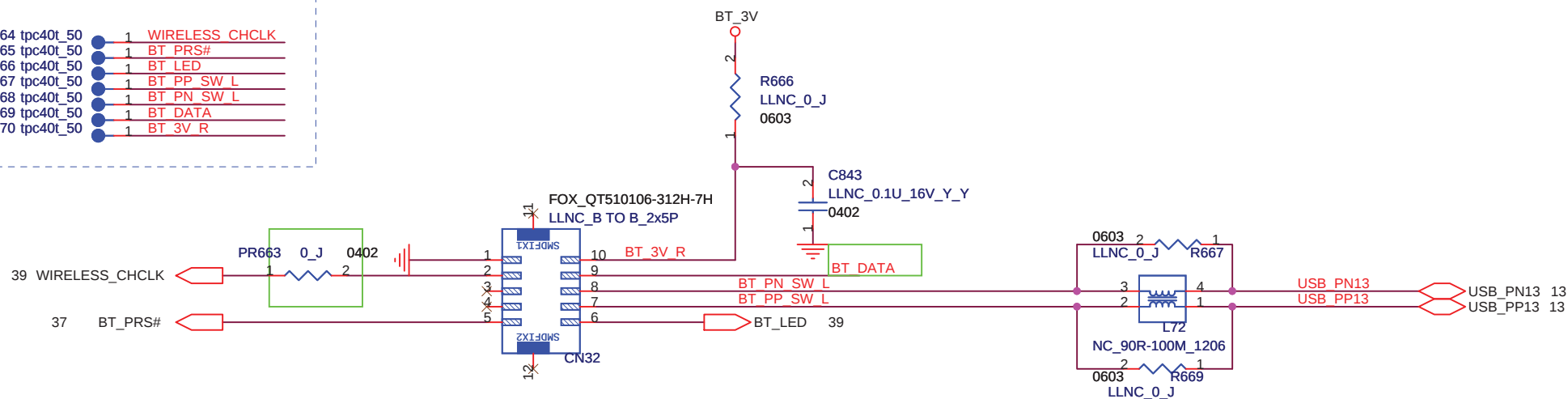
2009/09/19
Change USB_VCC2 to USB_VCC4



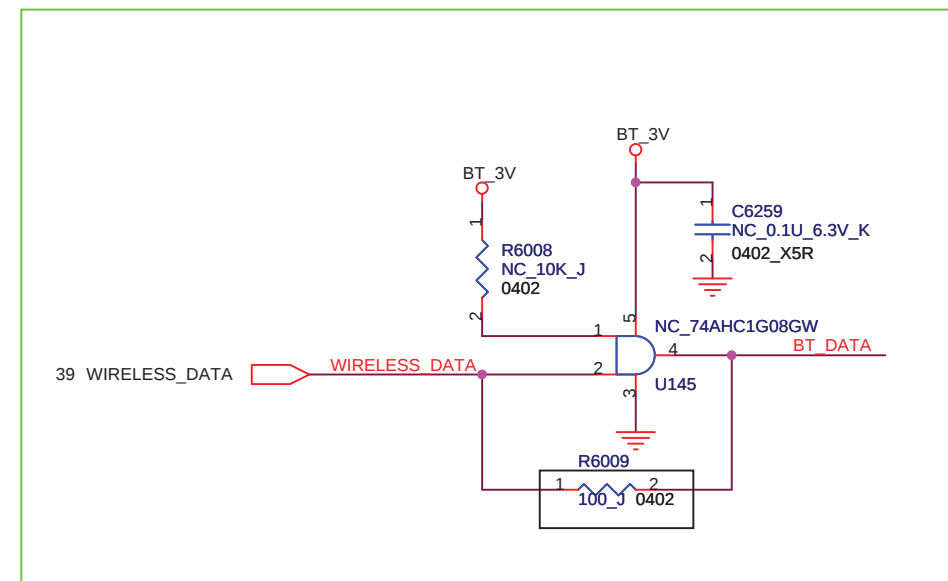
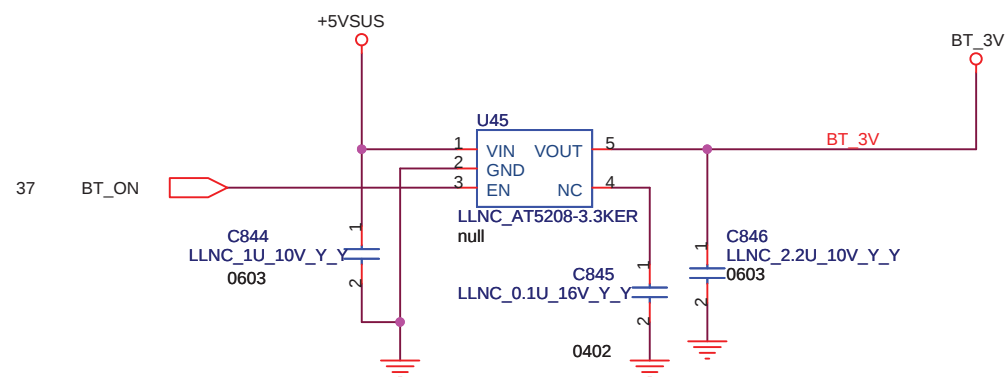
BOT Side PVT

Bluetooth connector

TP864 tpc40t_50	1	WIRELESS_CHCLK
TP865 tpc40t_50	1	BT_PRS#
TP866 tpc40t_50	1	BT_LED
TP867 tpc40t_50	1	BT_PP_SW_L
TP868 tpc40t_50	1	BT_PN_SW_L
TP869 tpc40t_50	1	BT_DATA
TP870 tpc40t_50	1	BT_3V_R

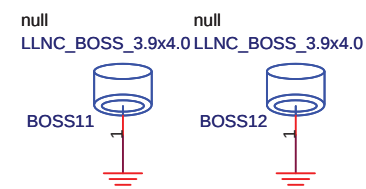


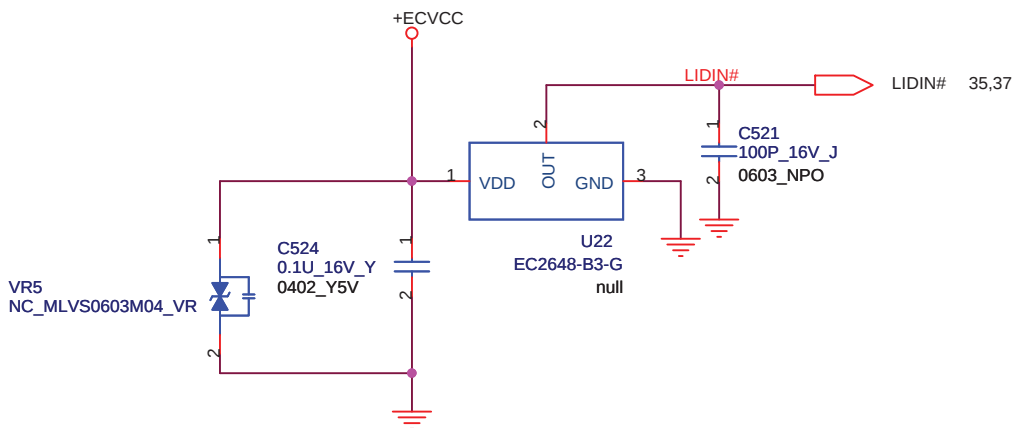
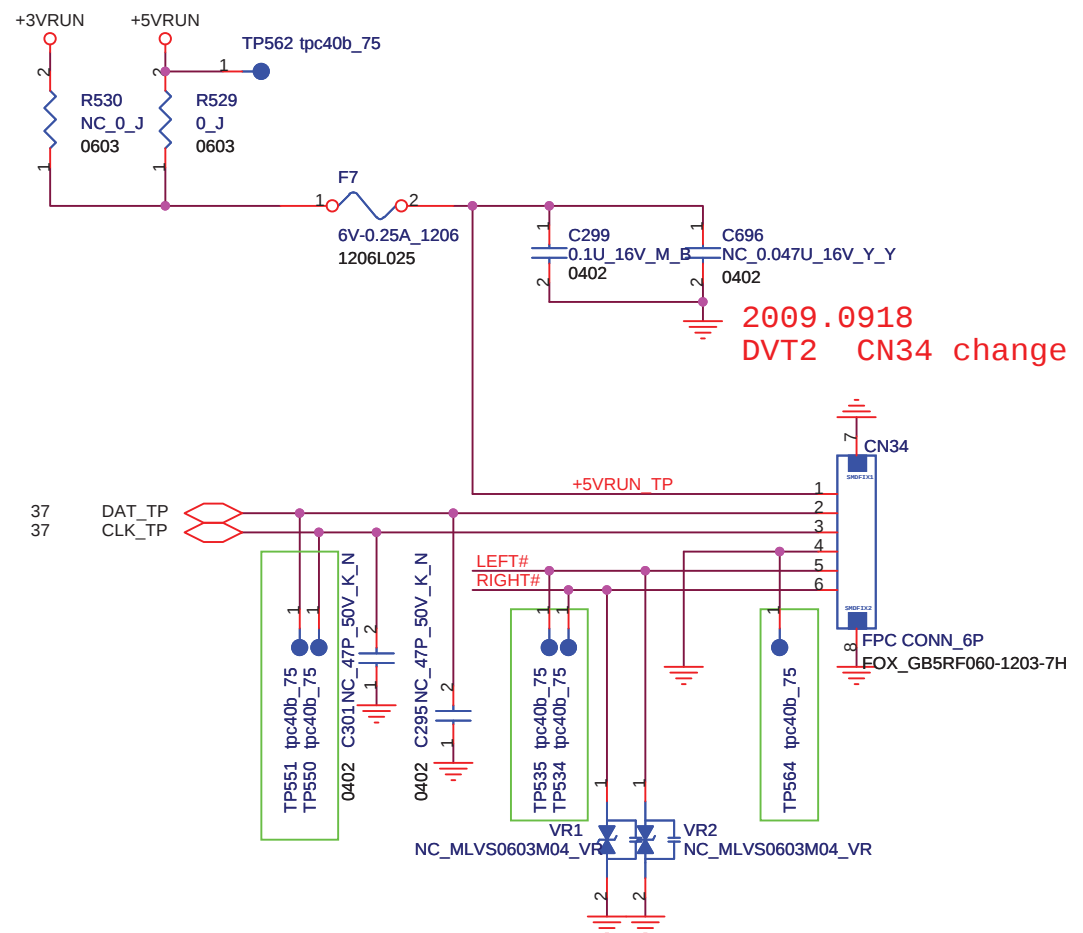
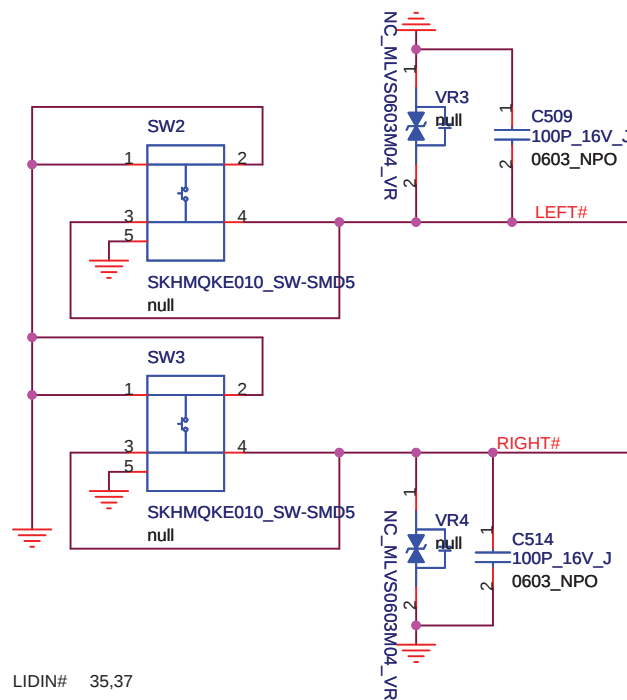
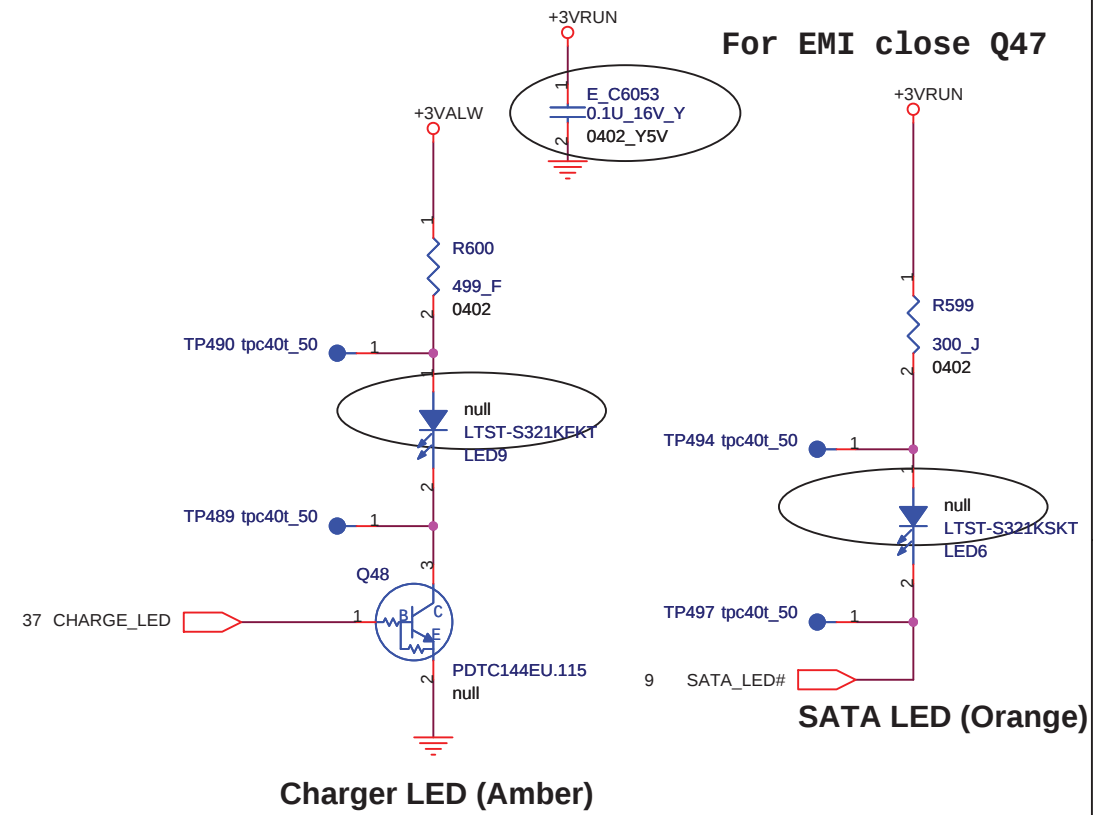
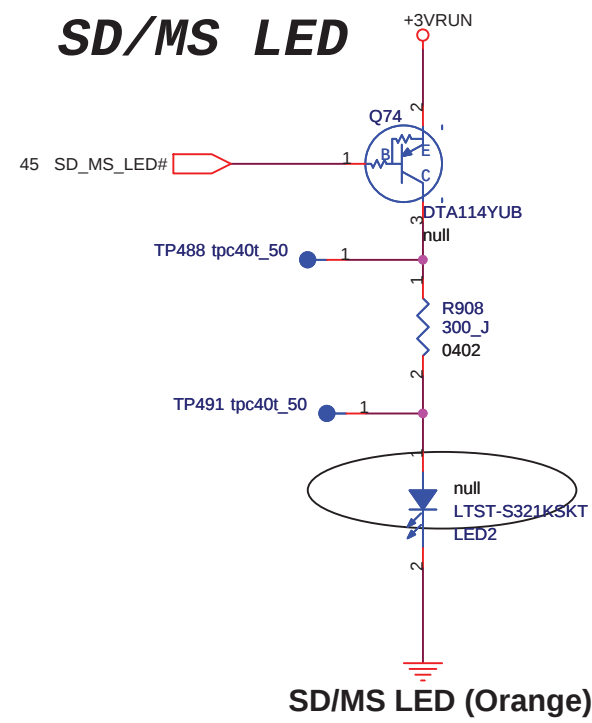
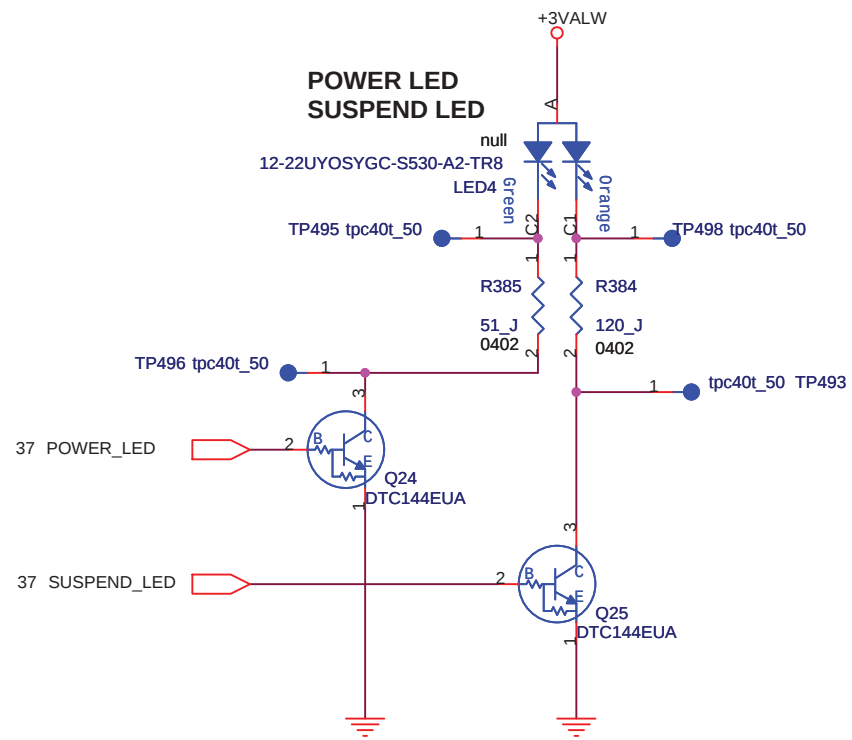
2009.0921
WIRELESS_DATA/WIRELESS_CHCLK follow M930



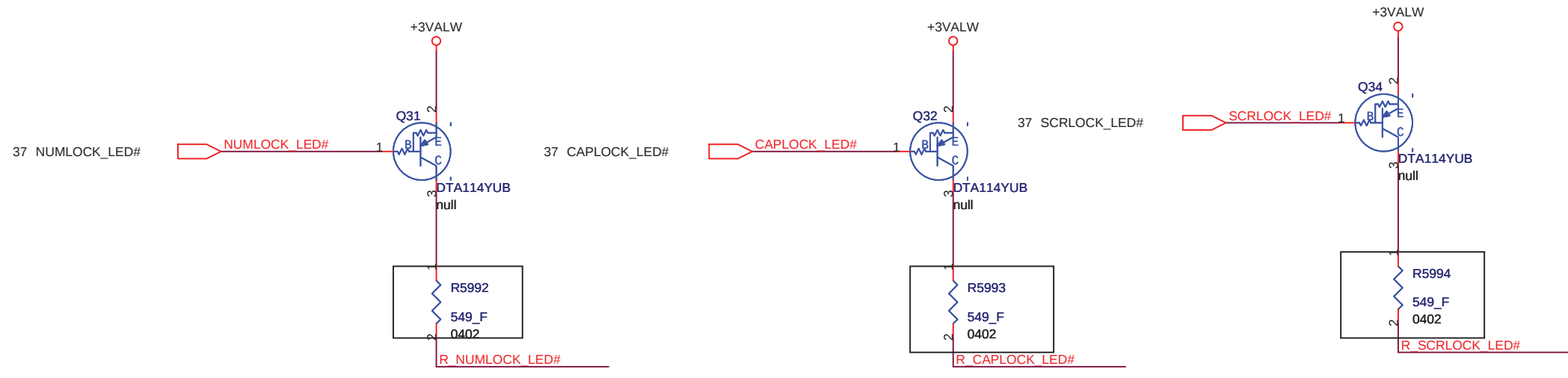
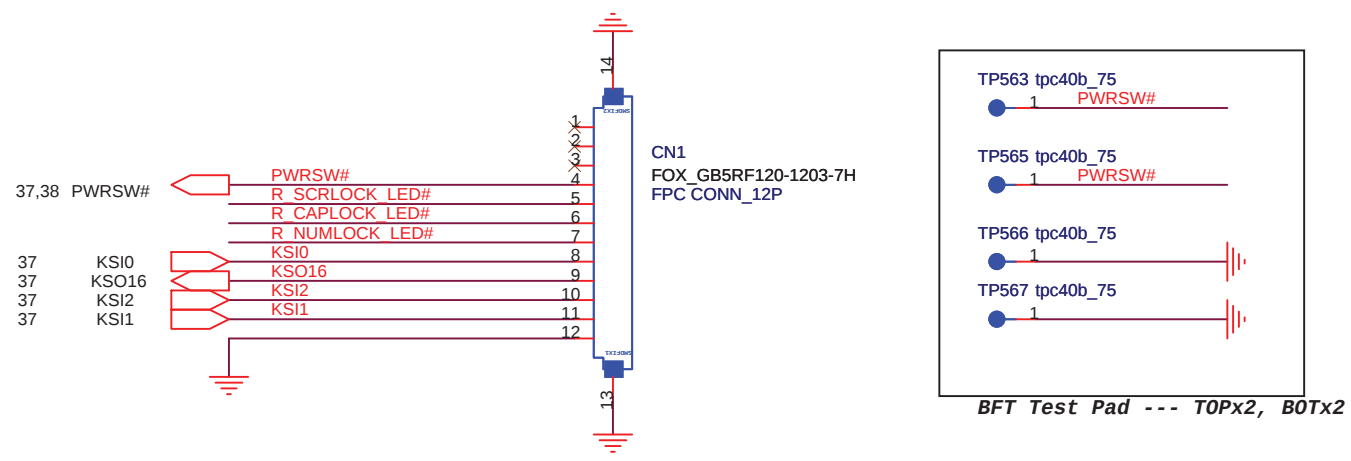
2009.11.19
Change R6009 from 1R-0000000-J200 to 1R-0000101-J200 for RF request

Bluetooth





2009/09/10
Add test point for L6 TE request



2009.10.30
change R5992,R5993,R5994 from 120ohm to 549ohm follow M870

Adaptor

19.5V / 90W

TI

bq24753A

Battery Charger

Switch Mode

PAGE 55

Battery

Li-ion

11.1V

4800mAh

DCBATOUT

ALW_ON

DCBATOUT

SUS_ON

DCBATOUT

RUN_ON1

DCBATOUT

RUN_ON1

DCBATOUT

IMVP_VR_ON

DCBATOUT

RUN_ON1

TI

SN0608098RHBR

Switch Mode

FOR System

PAGE 55

EN1

EN2

LD05

PGOOD

TI

TPS51218

Switch Mode

FOR DDR3

PAGE 59

EN

PGOOD

TI

TPS51218DSCR

Switch Mode

FOR VTT=>+1_05V_VTT

PAGE 58

EN

PGOOD

TI

TPS51218DSCR

Switch Mode

FOR VRAM

PAGE 60

EN/PSV

PGOOD

MAXIM

MAX17030

Switch Mode

FOR CPU Core

PAGE 53

VR_ON

CLK_EN#

IMVP_OK

TI

TPS51217

Switch Mode

FOR VGA

PAGE 57

EN/PSV

PGOOD

System

+5VALW/5A

System

+3VALW/5A

+5VALW_LDO

ALW_PWRGD

+12V/10mA

+1_5VSUS/11A

SUS_PWRGD

+1_05V_VTT/19A

RUN_PWRGD

+1_8VRUN/8A

VHCORE/40A

EC_CLK_EN#

IMVP_OK

NV_VDD/14A

SUS_ON

RUN_ON

SUS_ON

RUN_ON

+5VALW_LDO

RUN_ON1

RUN_ON1

RUN_ON1

N-Channel transistor

N-Channel transistor

N-Channel transistor

N-Channel transistor

AT5208-3.3KER

LDO

N-Channel transistor

G2998

LDO

OZ8033

LDO

+5VSUS/0.6A

+5VRUN/4.5A

+3VSUS/2A

+3VRUN/3A

+ECVCC/100mA

+1_5VRUN/4A

0.75VRUN/2A

PEX_VDD/700mA

HON HAI Precision Ind. Co., Ltd.
CCPBG - R&D Division

FOXCONN

Title Power Design Diagram

Size A3	Document Number M9A0_MP	Rev 1.1
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Date: Wednesday, September 23, 2009 | Sheet 52 of 73

2009.10.22
change PC112 from 68U to 47U for power request

Place these CAPS
close to FETs

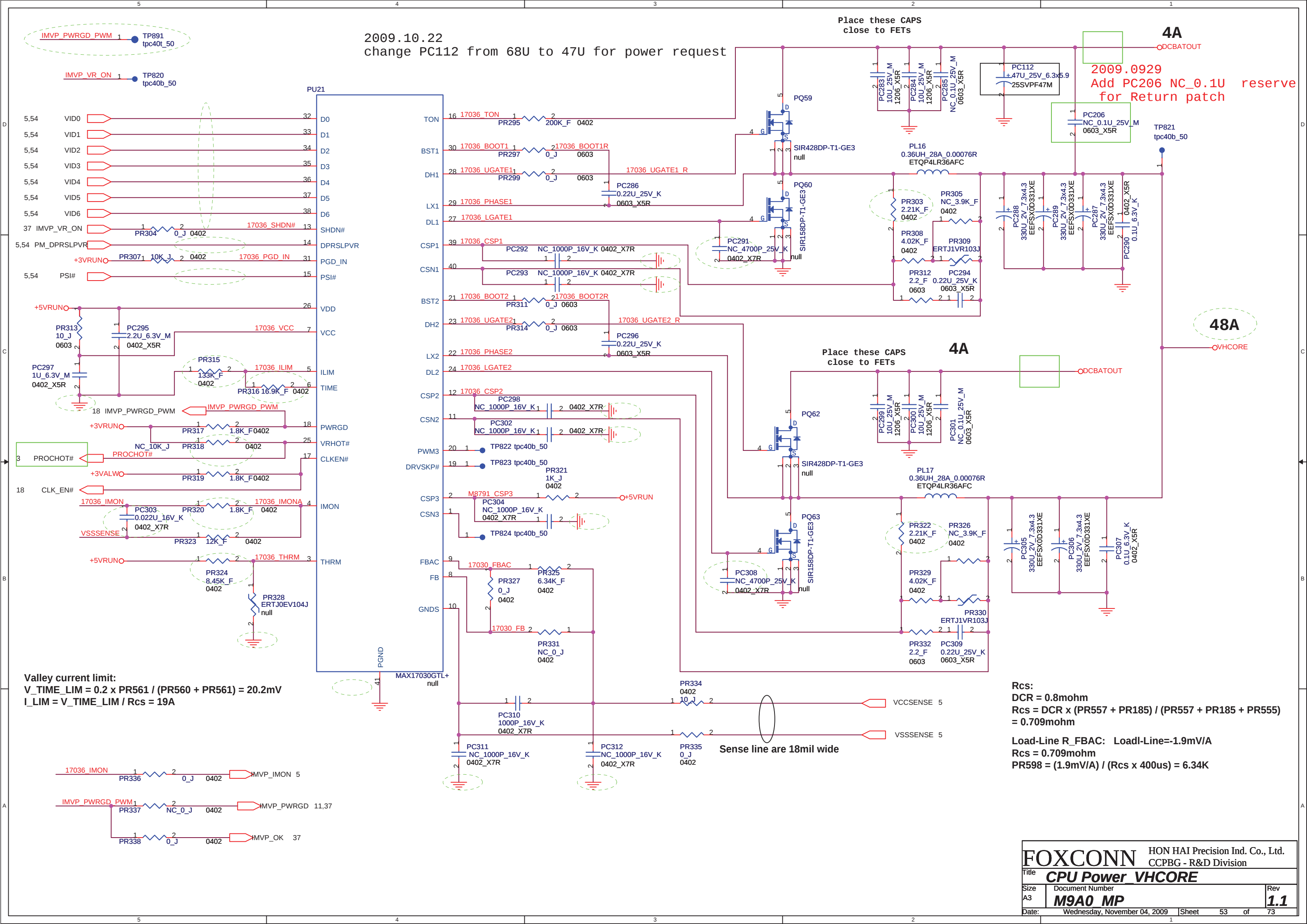
4A

2009.0929
Add PC206 NC_0.1u reserve
for Return patch

48A

4A

Rcs:
DCR = 0.8mohm
 $Rcs = DCR \times (PR557 + PR185) / (PR557 + PR185 + PR555)$
= 0.709mohm
Load-Line R_FBAC: Load-Line=-1.9mV/A
Rcs = 0.709mohm
 $PR598 = (1.9mV/A) / (Rcs \times 400us) = 6.34K$

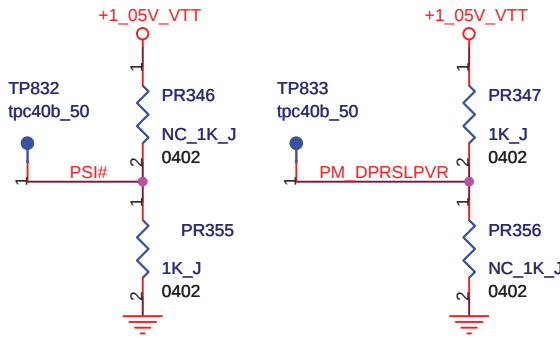
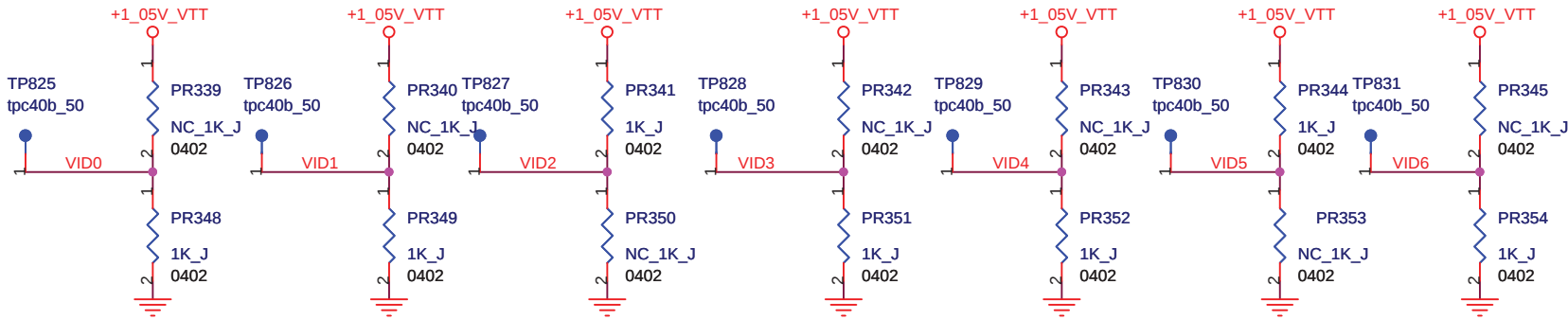
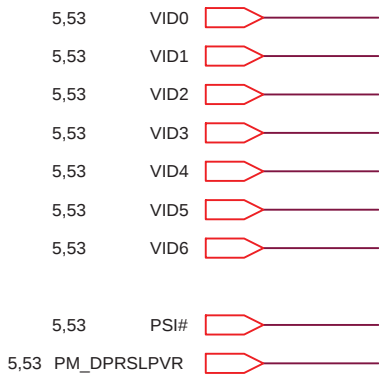


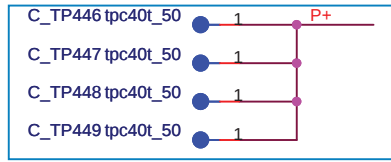
Valley current limit:
 $V_TIME_LIM = 0.2 \times PR561 / (PR560 + PR561) = 20.2mV$
 $I_LIM = V_TIME_LIM / Rcs = 19A$

Sense line are 18mil wide

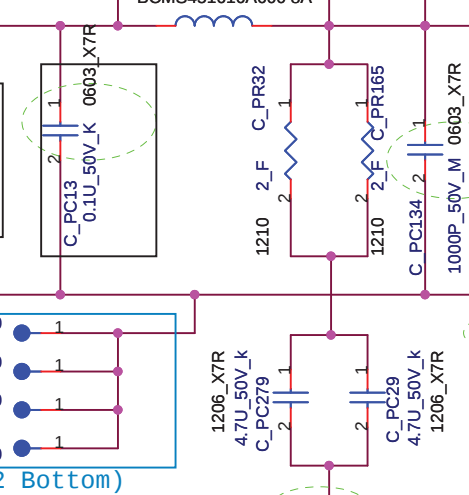
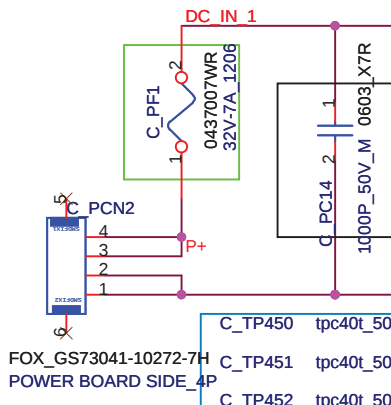
Default value of VID [6:0] = [0100100] , PSI = 0 , PROC_DPRSLPVR = 1

Market Segment Selection MSID[2:0] = [100] (SV)
- 416056_416056_Ard_EDS_Rev.1.1 - 403779_Clarksfield_MPG_Rev1.5

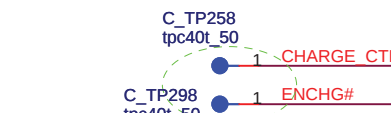




For BFT Test (2 Top, 2 Bottom)

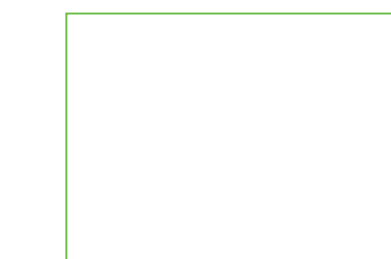


For BFT Test (2 Top, 2 Bottom)



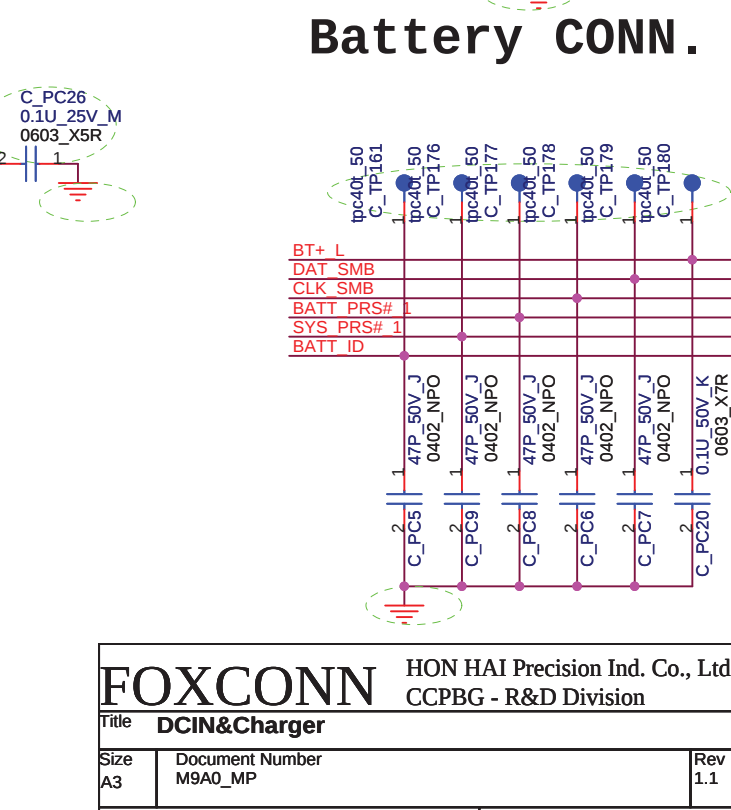
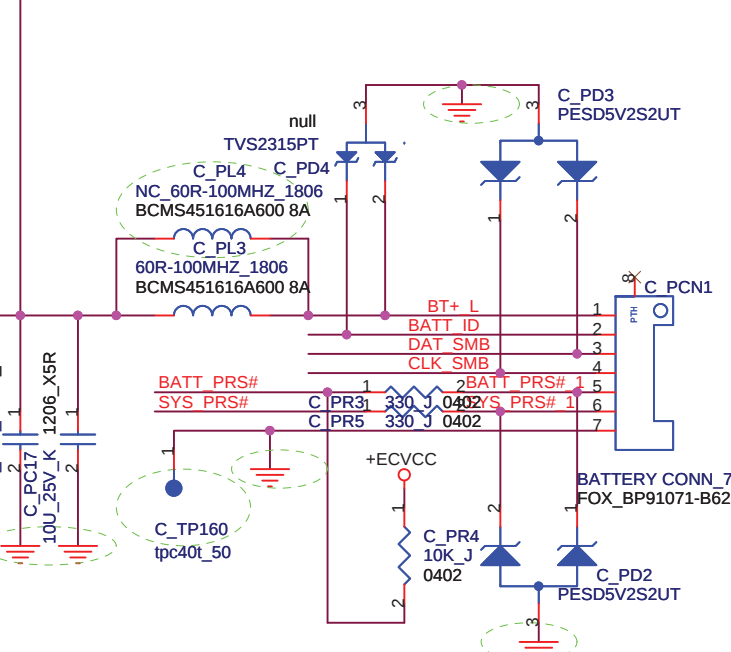
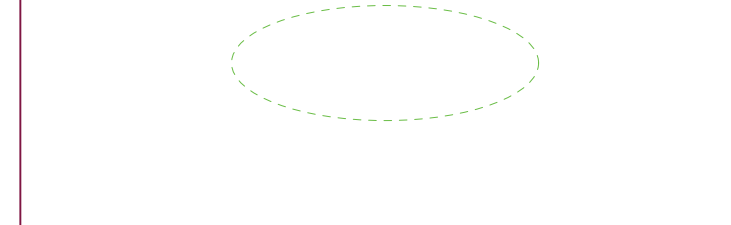
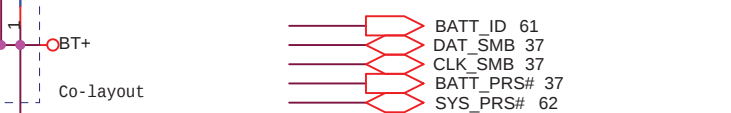
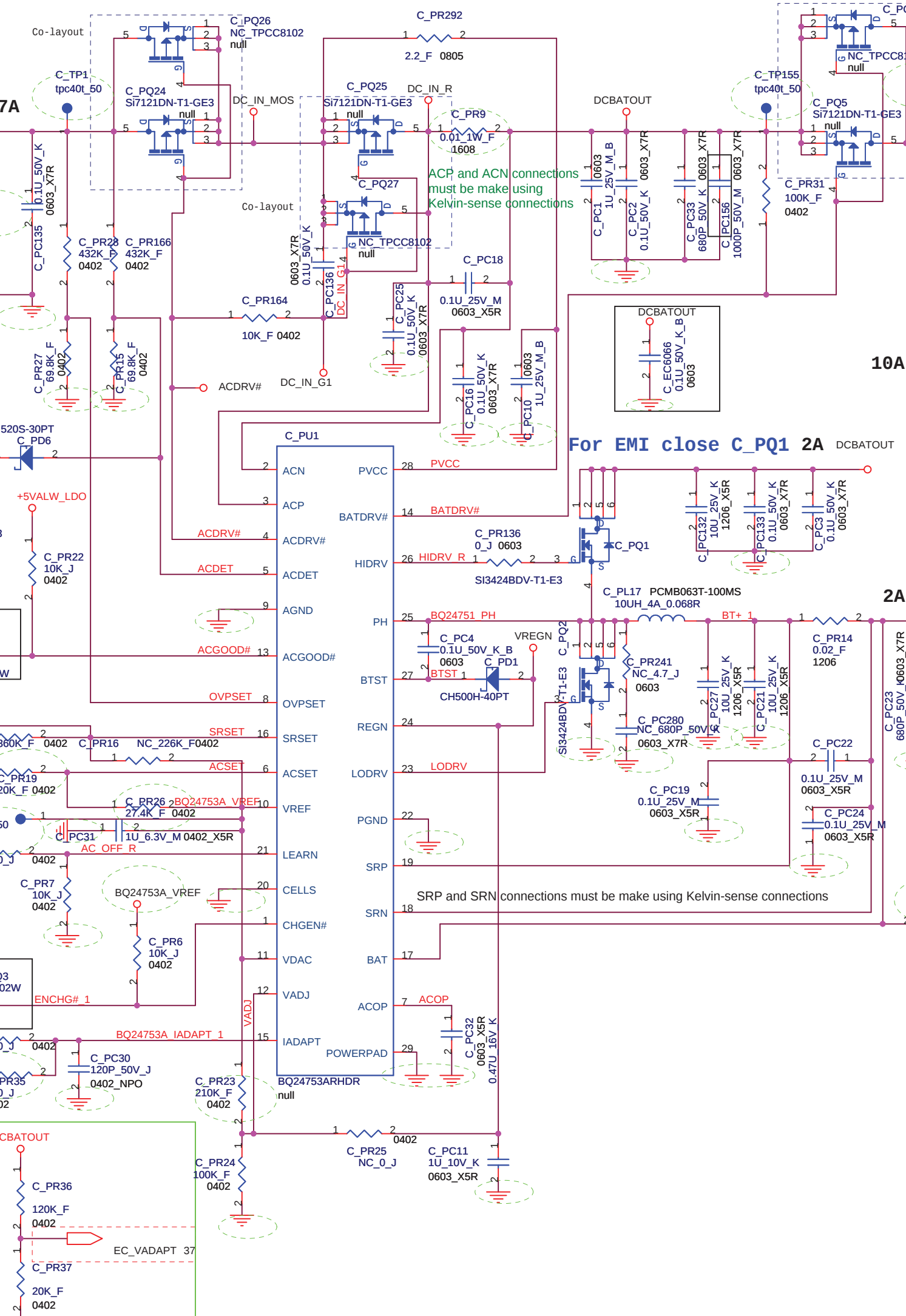
charge current set table:

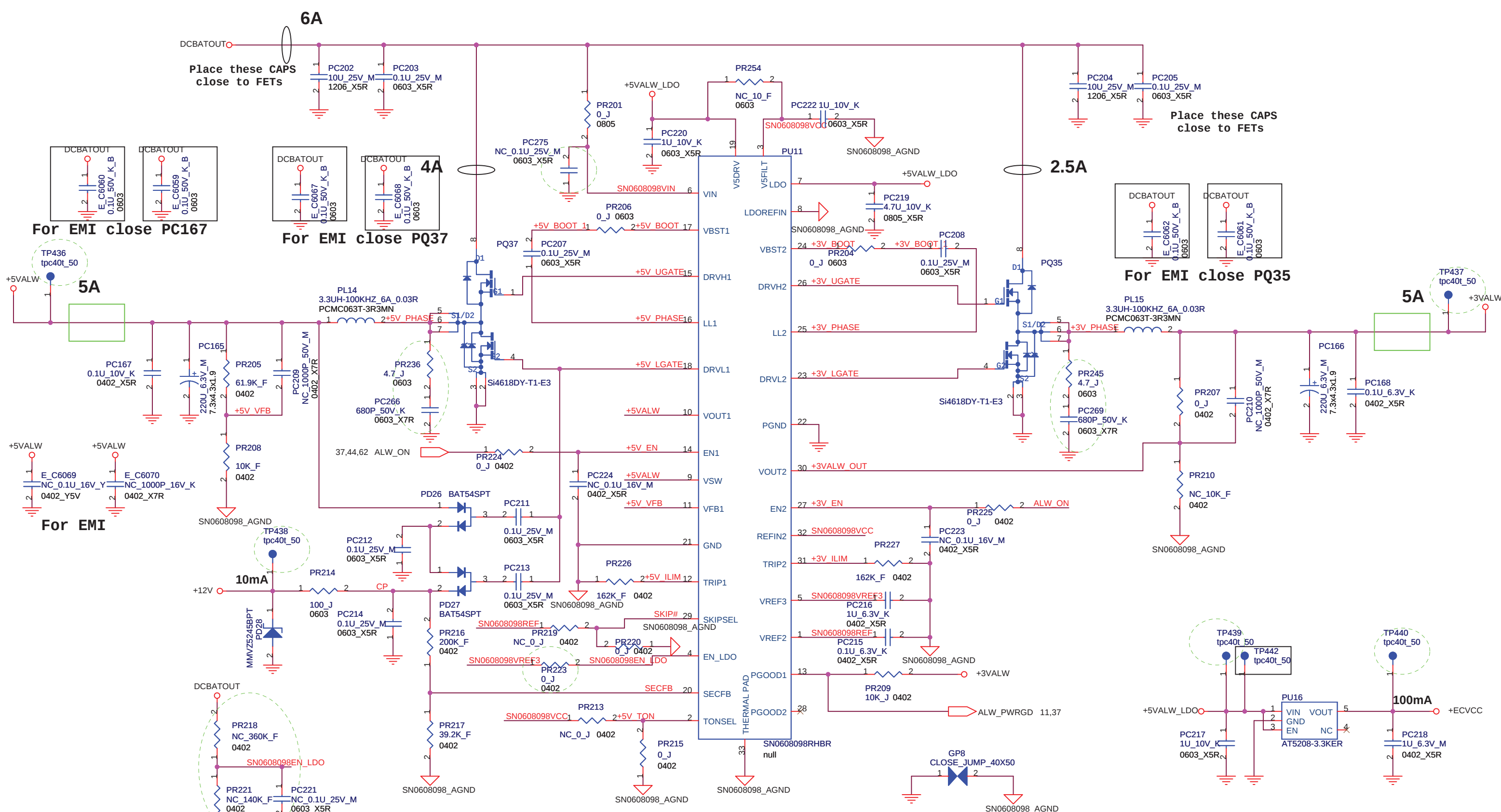
charge current	CHARGE_CTRL D/A pin voltage setting	Required charge current control
1.5A	3.06V	High current
0.8A	1.6V	Middle current
350mA	0.72V	Low current
0A	0V	charge OFF



VREF=3.3V->VDAC
 $V_{bat} = \text{cell count} * [4V + 0.512 * (V_{adj} / V_{vadc})] = 12.465V$
(Vbat=4.2V when Vadj connected to REGN)
 $I_{charge} = (V_{srset} / V_{vdac}) * (0.1 / PR15) = 1.5A$
 $I_{adapter} = (V_{vacset} / V_{vdac}) * (0.1 / PR657) = 4.22A$
 $IADAPT = (V_{acp} - V_{vacn}) * 20$
Input OCP: $(V_{ACP} - V_{ACN})_{max} / PR4 = 100mV / 10mohm = 10A$
Input OVP : 22.2V
Input UVP : 17V
Battery OCP : $I_{charge} * 145\%$
Battery OVP : $V_{bat} * 104\%$
Pre-charge : $< 2.9V / \text{cell} ==> I_{charge} / 8$
Battery OTP : Tshut=155 degree
Fsw : 300KHz
Time that input current limit :
 $t = (C_{acop} * 2) / (18uA / V * V(PVCC - ACP)) = 0.48s$

ENCHG# : Enable ==> L Disable ==> H	
ACGOOD# : Vacdet > 2.4V ==> L Vacdet < 2.4V ==> H	
CELLS	CELL COUNT
FLOAT	2
AGND	3
VREF	4



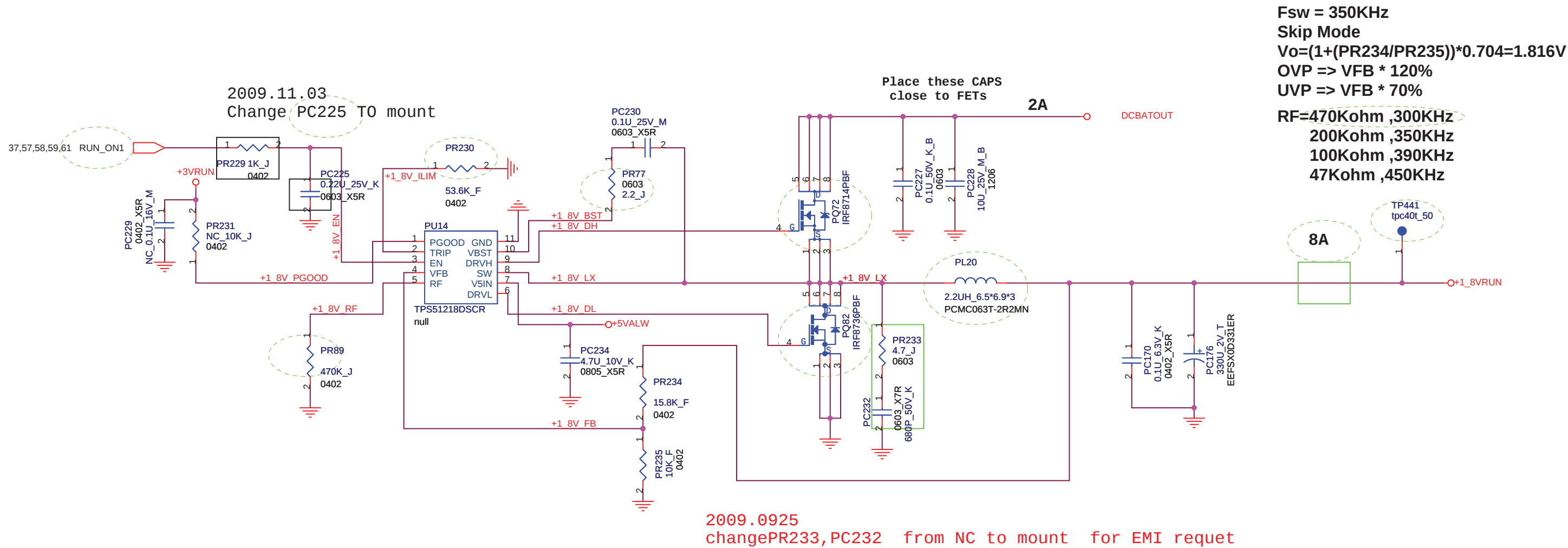


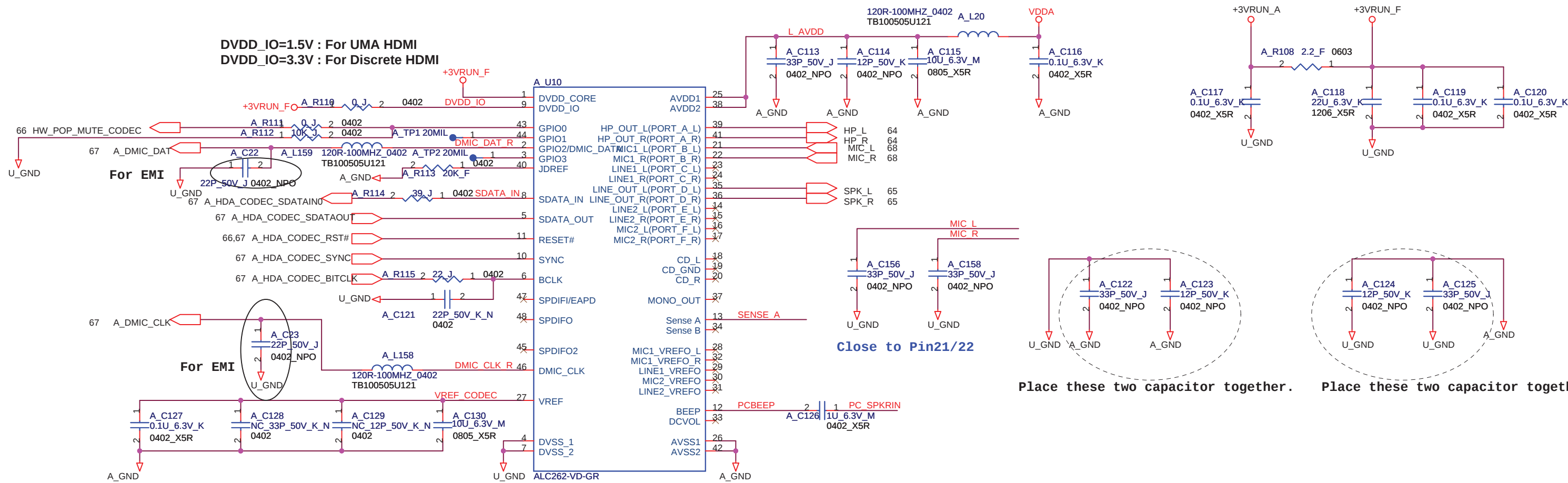
2009.0925
change PR245,PC269,PR236,PC266 from NC to mount for EMI request

TON	Operating Freqeunce (+5VALW/+3VALW)
VCC	200KHz/300KHz
REF(OPEN)	400KHz/300KHz
GND	400KHz/500KHz

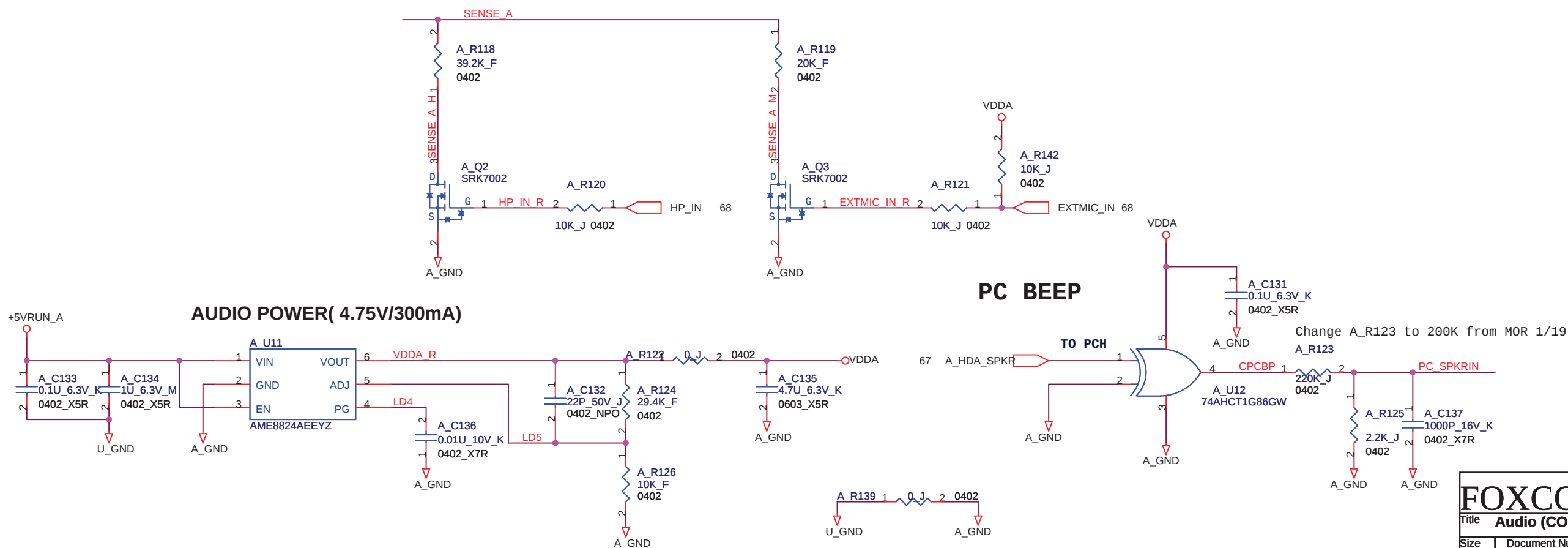
SKIP#	Operating Mode
GND	Pulse-Skipping
REF	Ultrasonic-Skip
VCC	PWM

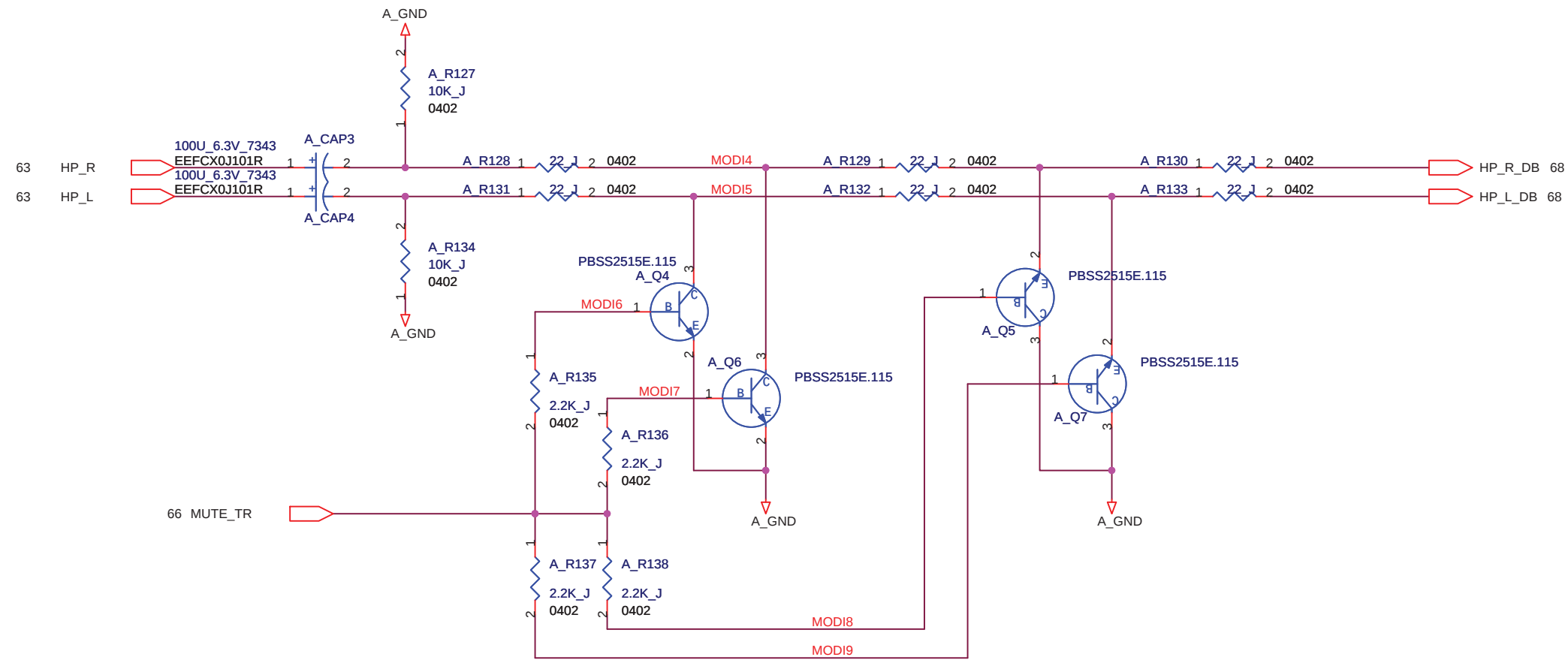
$$L=VOUT(VIN-VOUT)/(VIN*f*LIR*ILOAD(MAX))$$
$$Rocp=(Iocp-Iripple/2)*(10*Rds(on))/5u$$
$$+5VALW=((PR205/PR208)+1)*VFB1$$

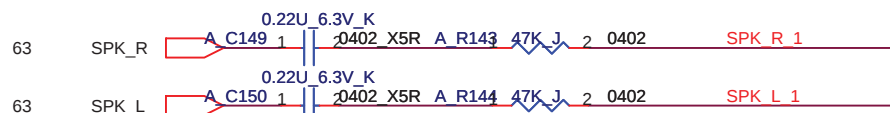
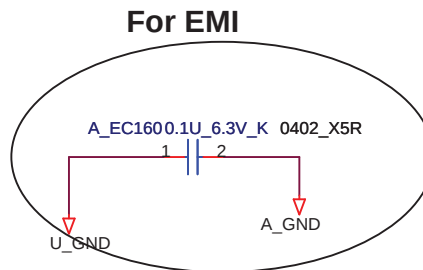
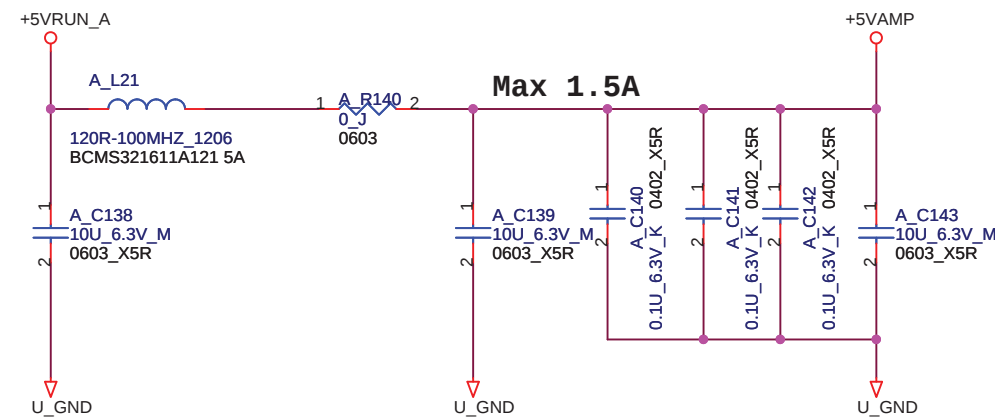




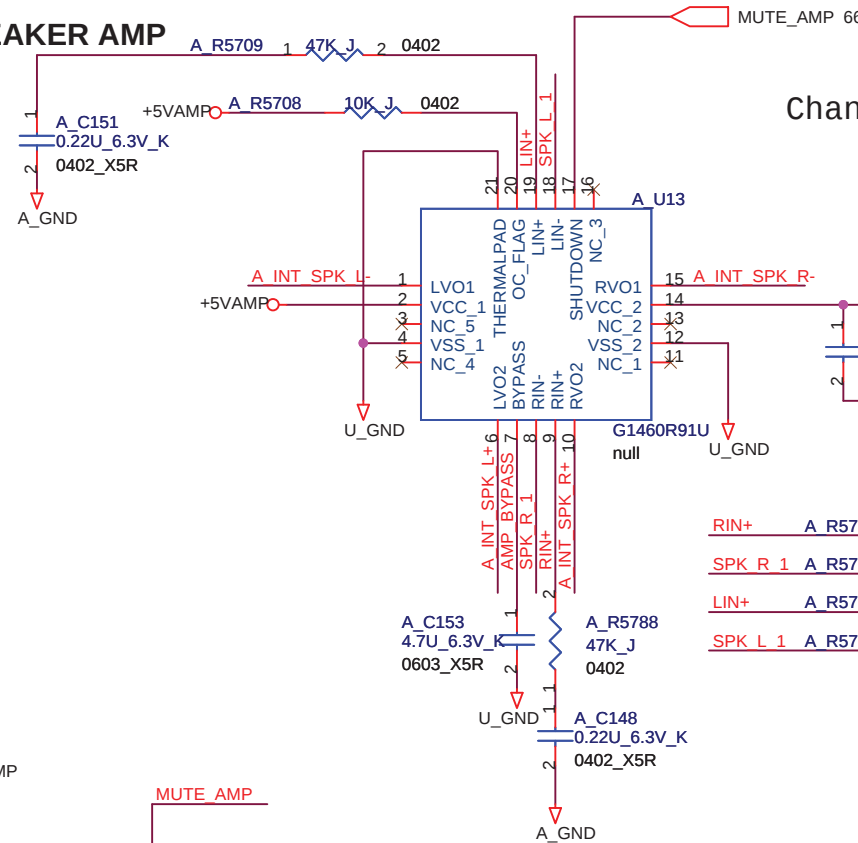
2009.11.03
 change A_C23,A_C22 from 15PF to 22PF for EMI request



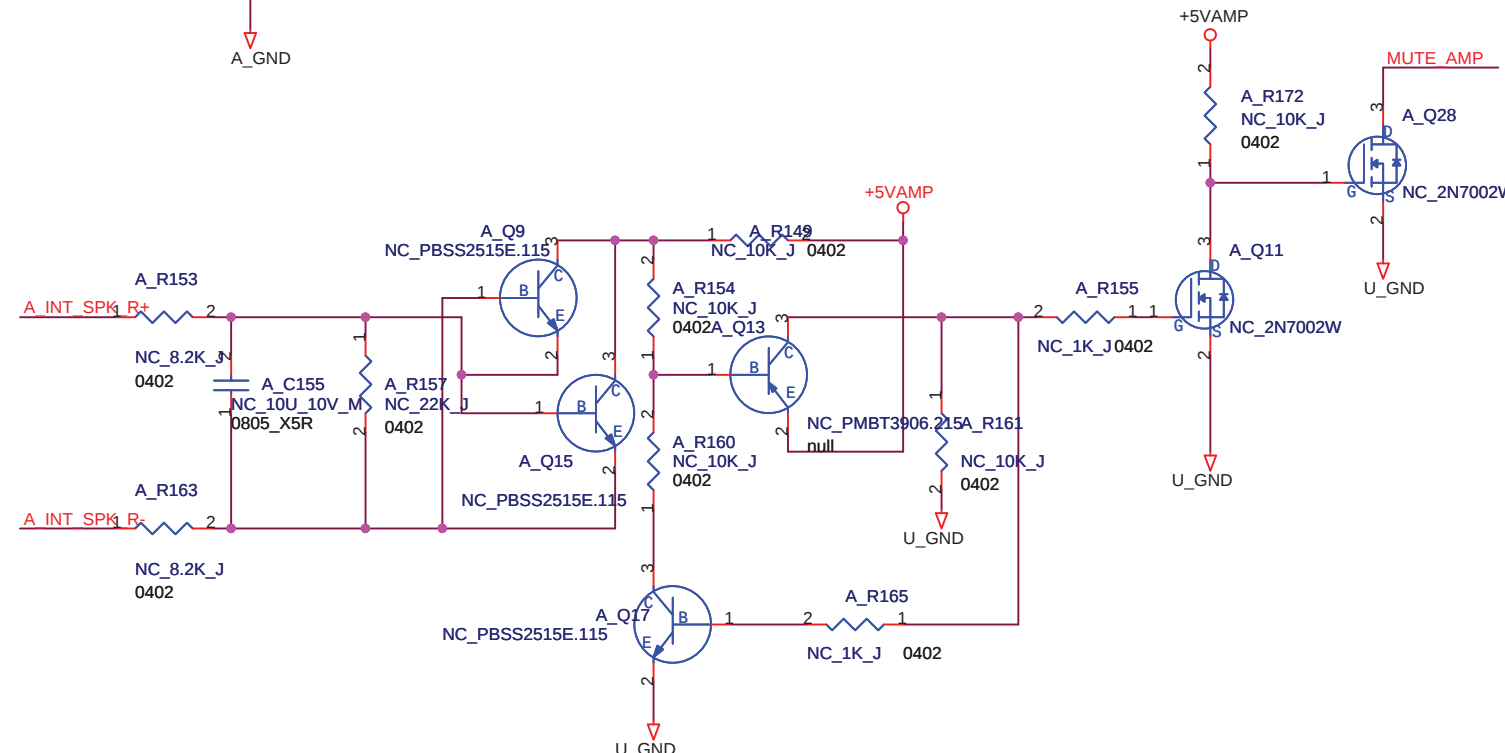
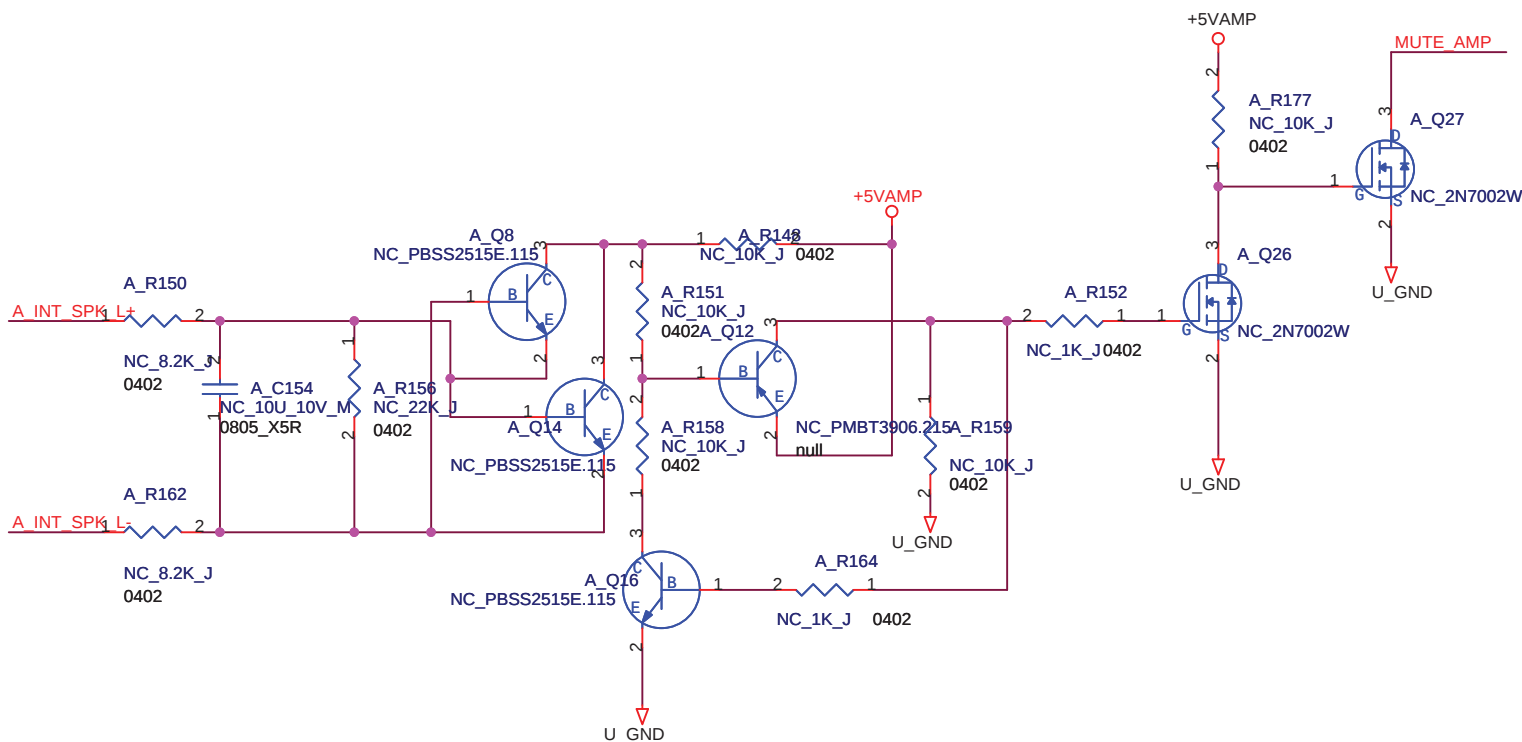
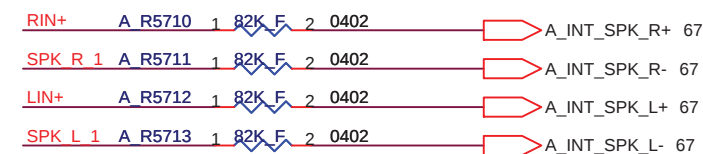




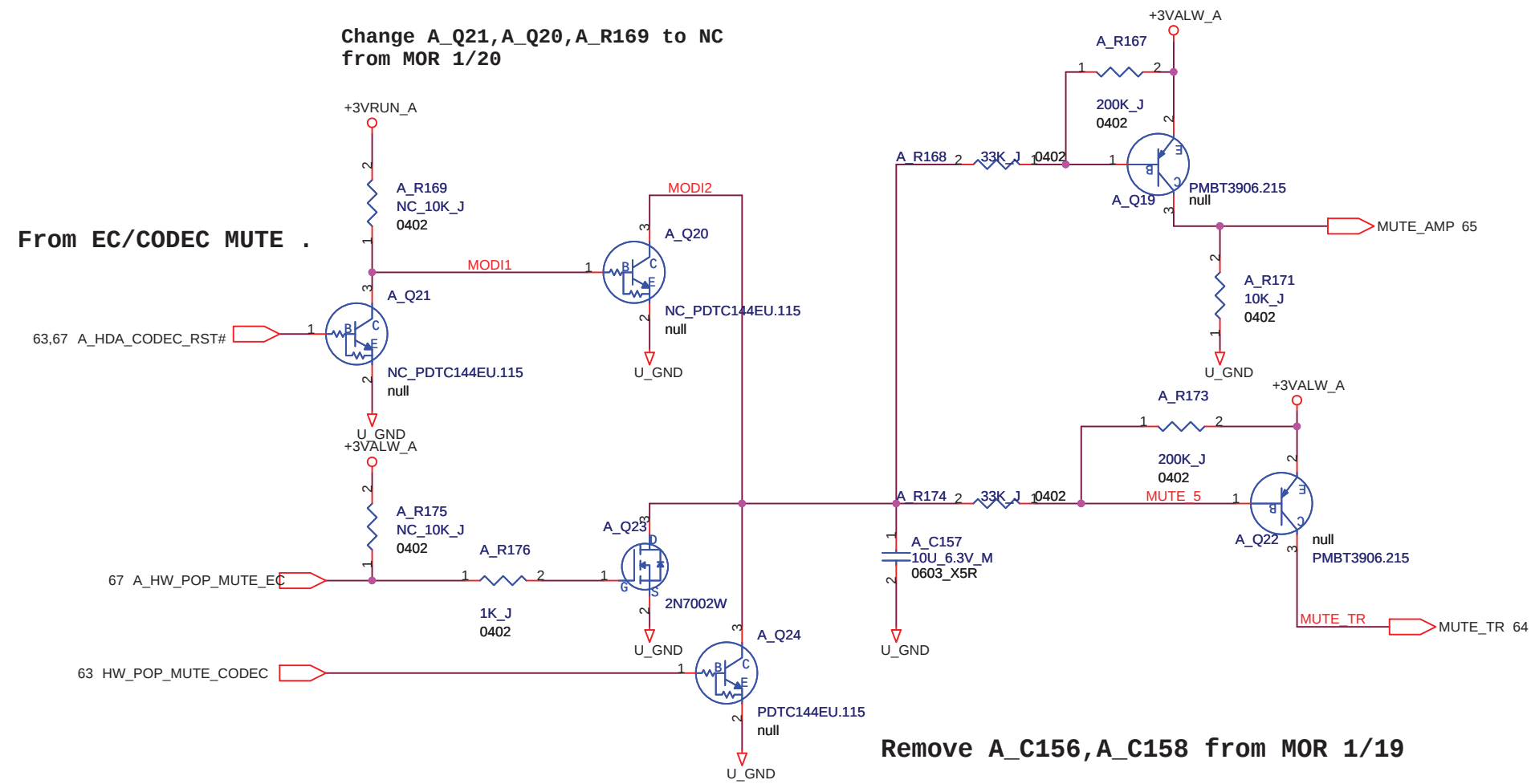
SPEAKER AMP



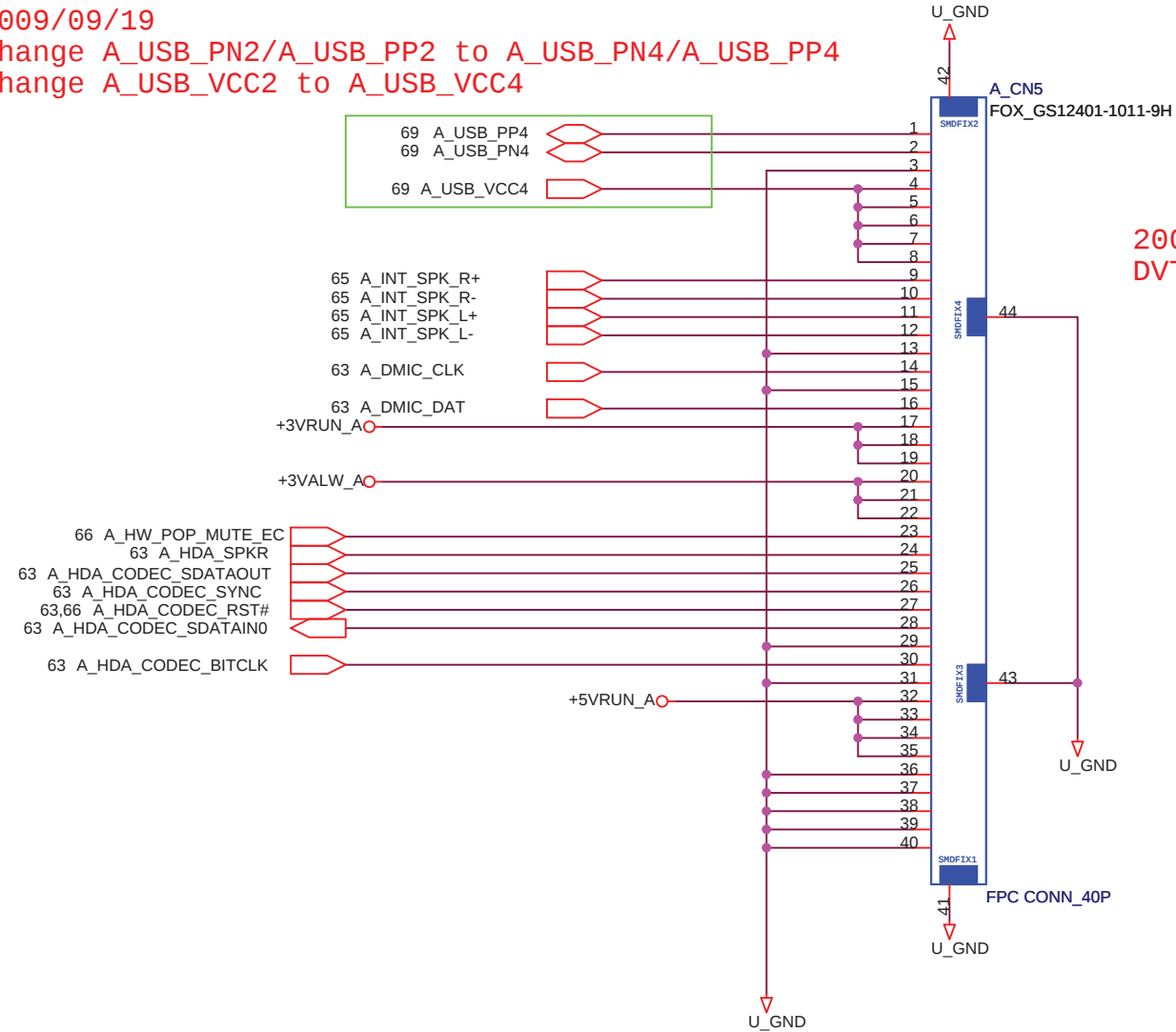
Change A_GND to U_GND from MOR 1/19



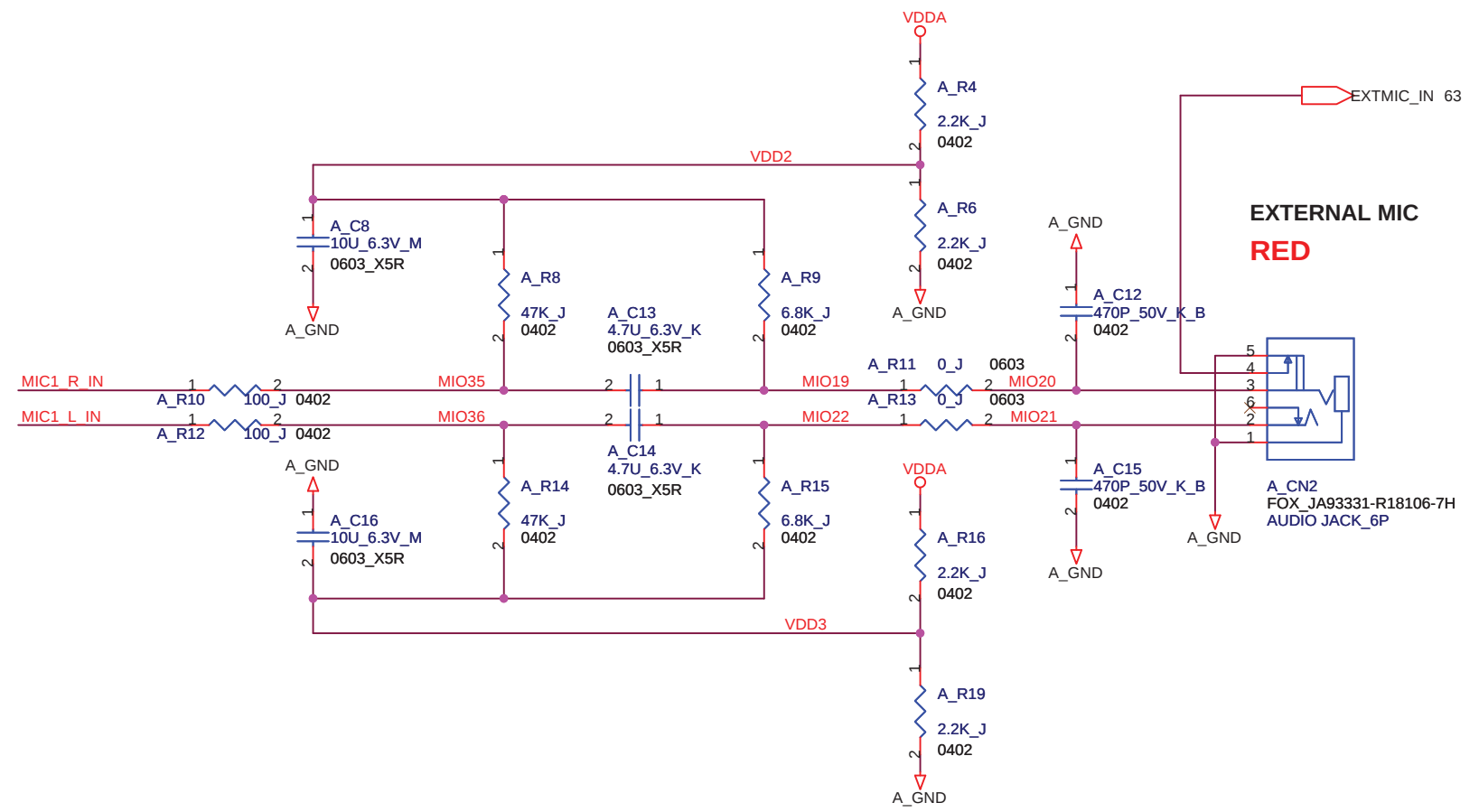
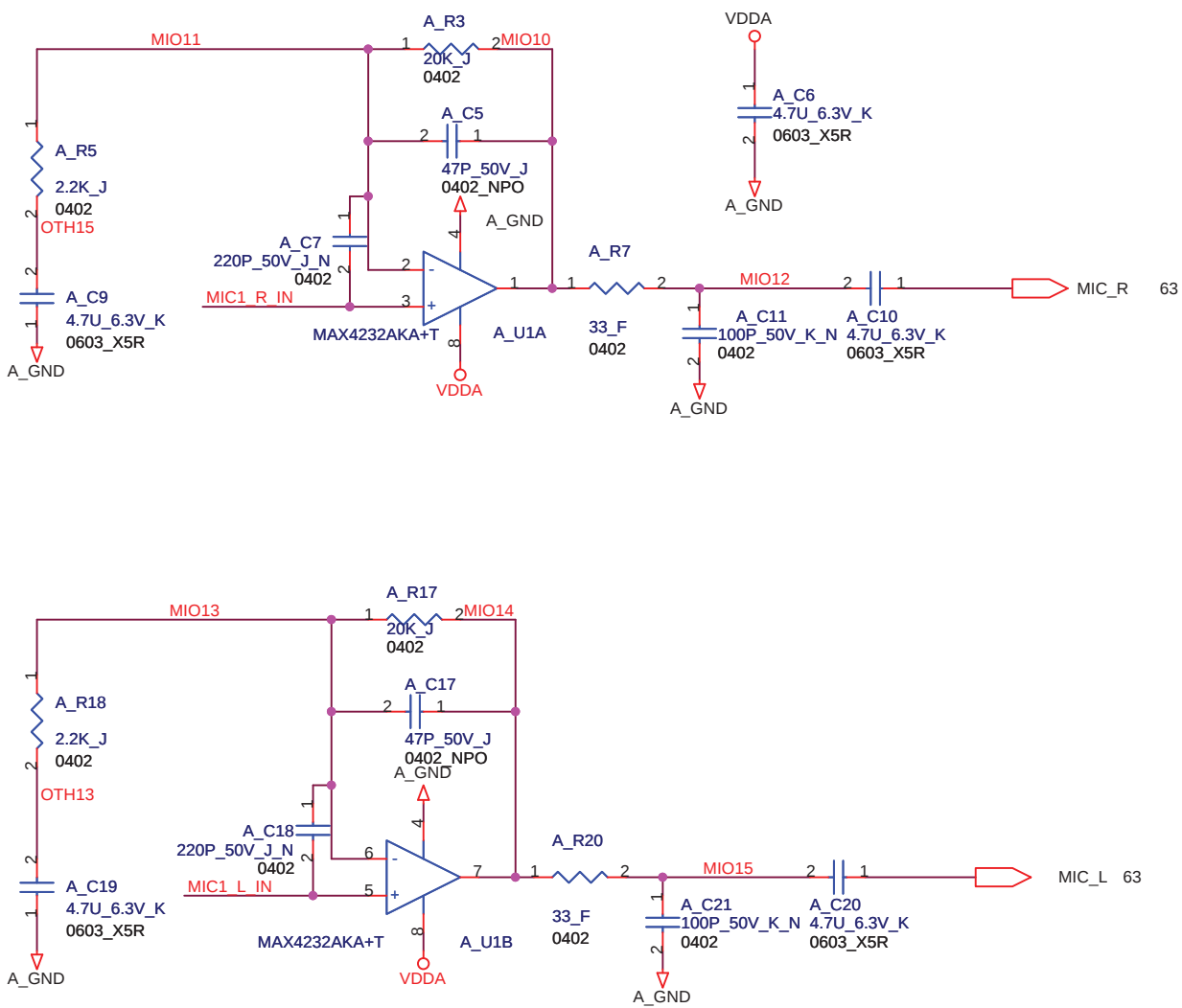
For Mor request, add the speaker cable short protection circuit



2009/09/19
Change A_USB_PN2/A_USB_PP2 to A_USB_PN4/A_USB_PP4
Change A_USB_VCC2 to A_USB_VCC4



2009.0918
DVT2 A_CN5 change to Halogen Free



VespaCP no fingerprint function, so this page reserve

5

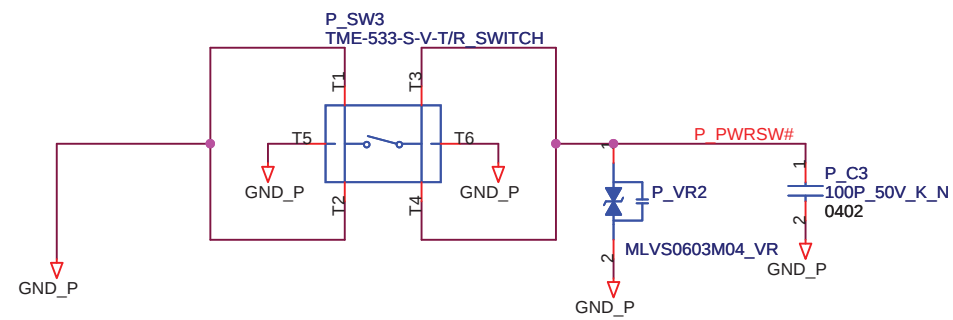
4

3

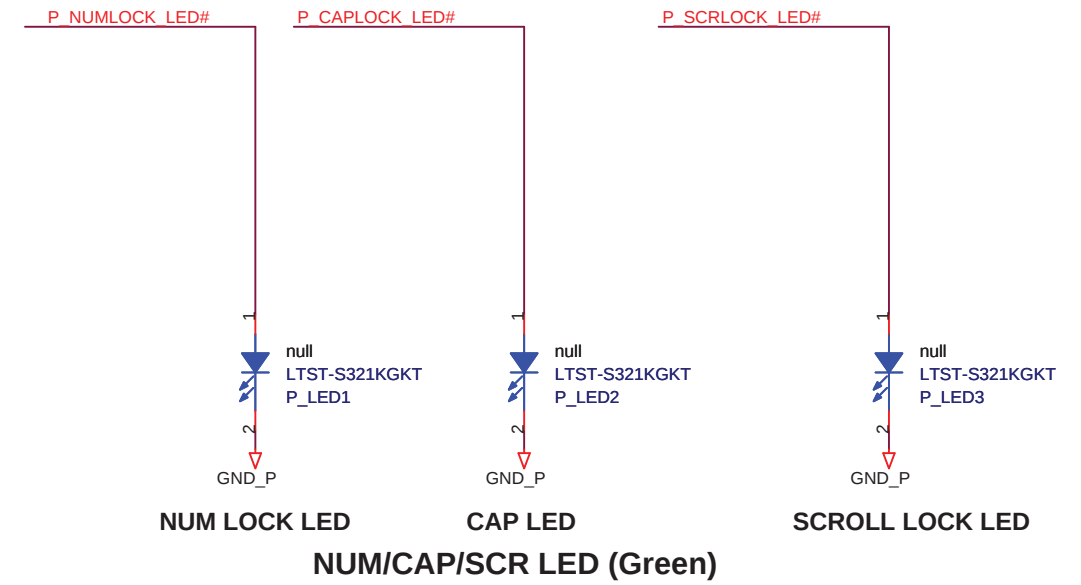
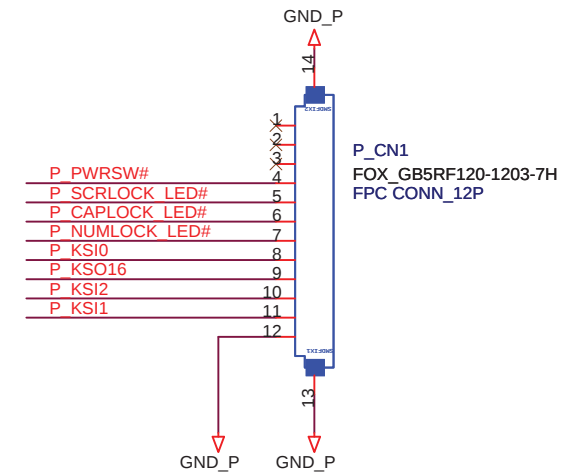
2

1

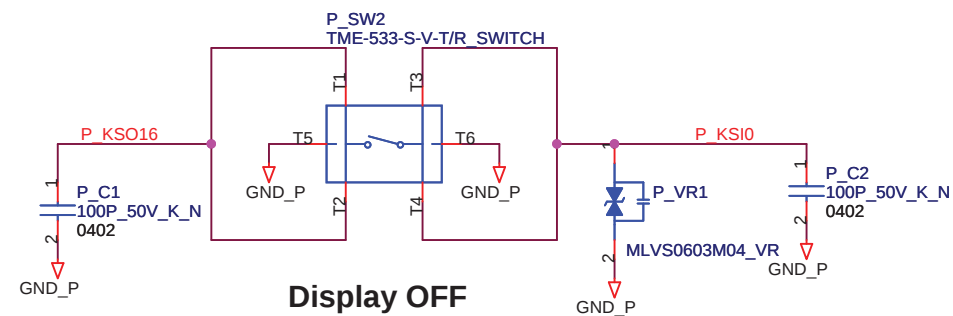
POWER BUTTON



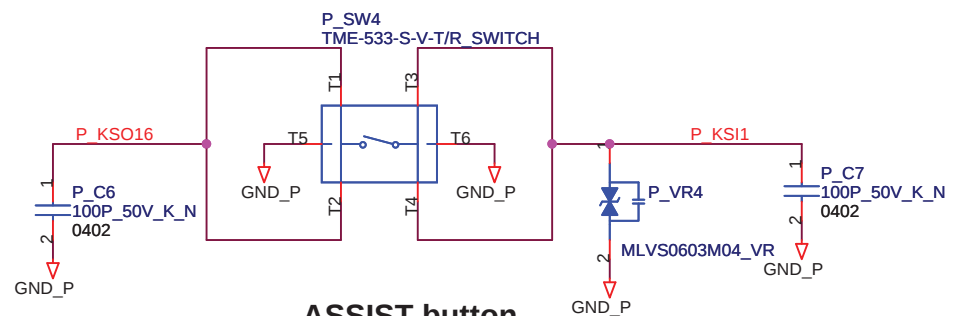
Power Button Board



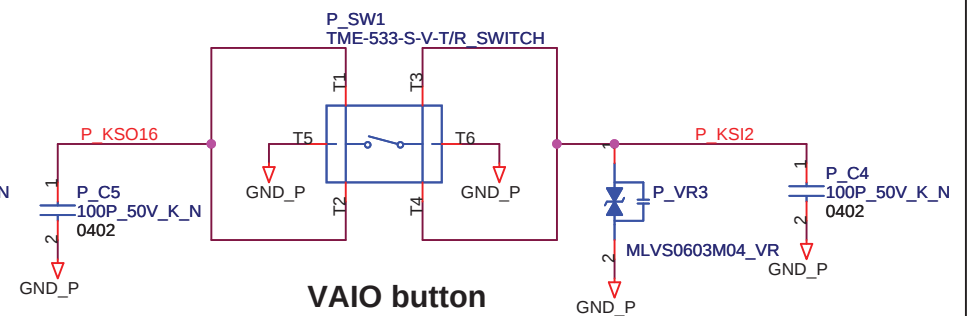
Display OFF

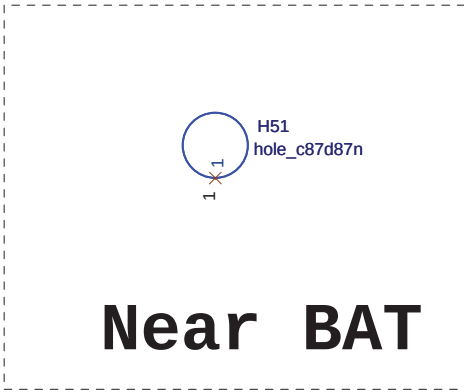


ASSIST button

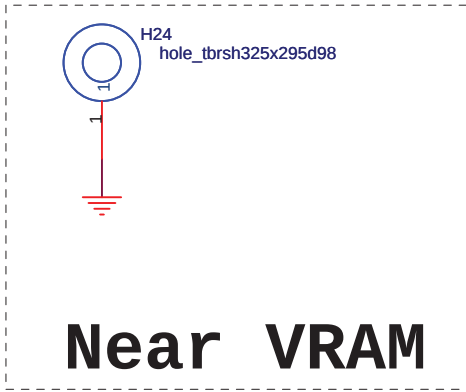


VAIO button

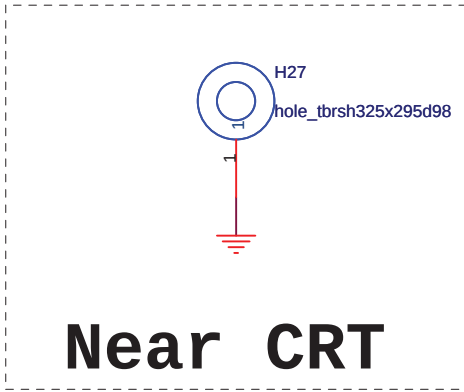




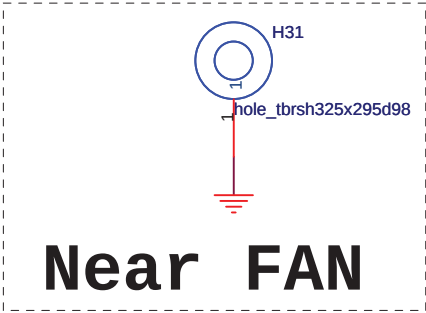
Near BAT



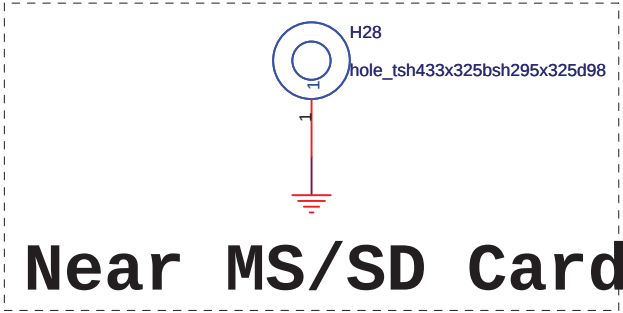
Near VRAM



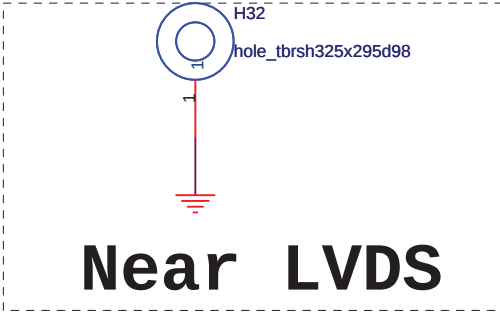
Near CRT



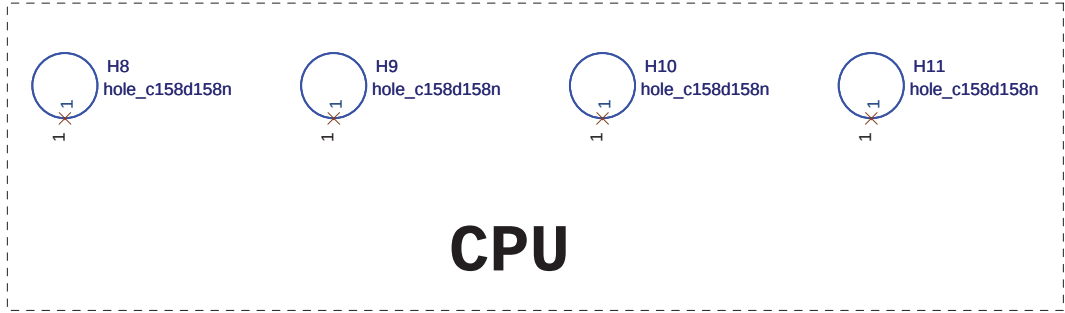
Near FAN



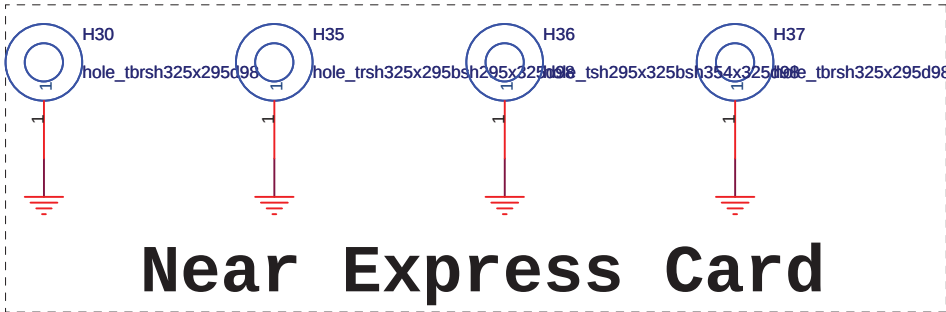
Near MS/SD Card



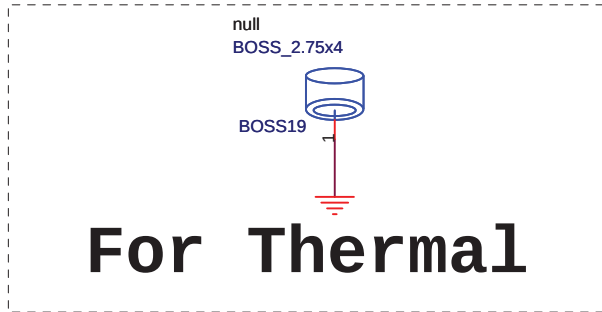
Near LVDS



CPU



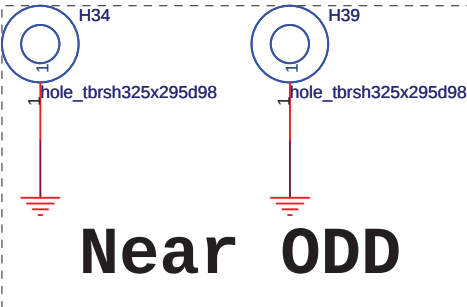
Near Express Card



For Thermal

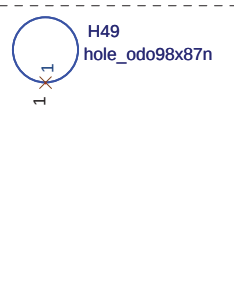


Near USB

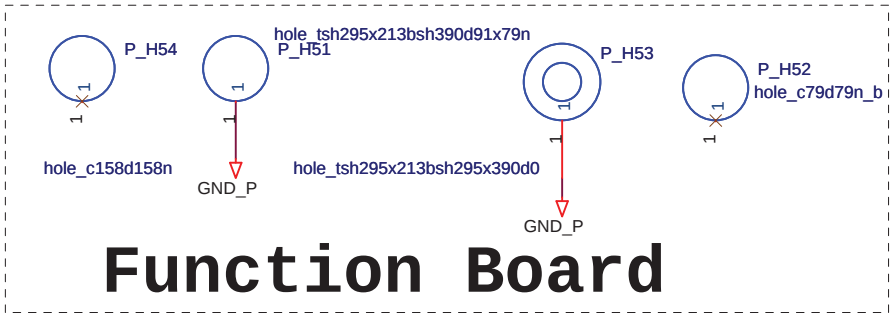
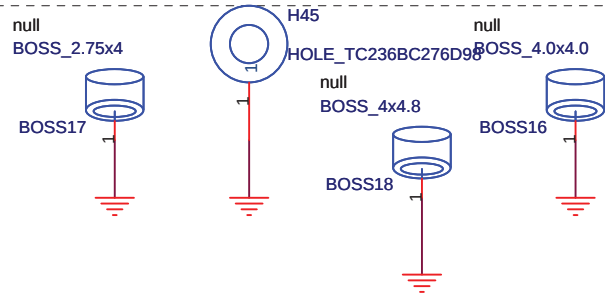


Near ODD

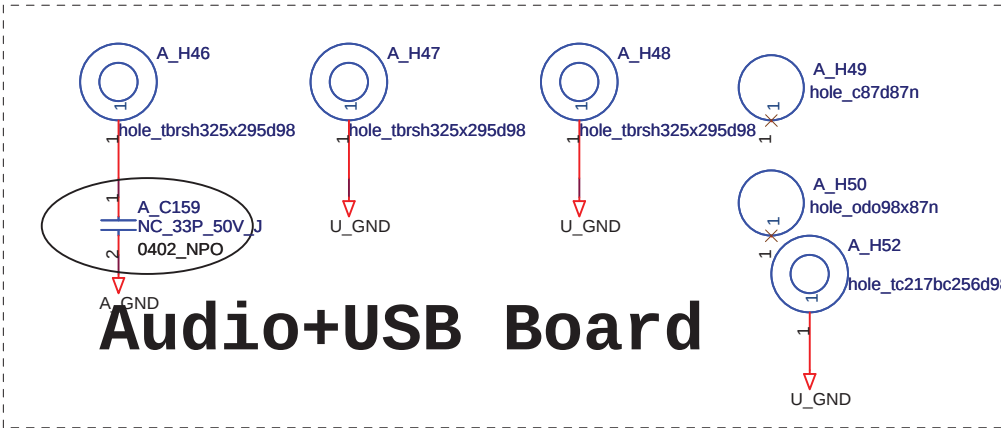
Del H42/H43, combine with CN25



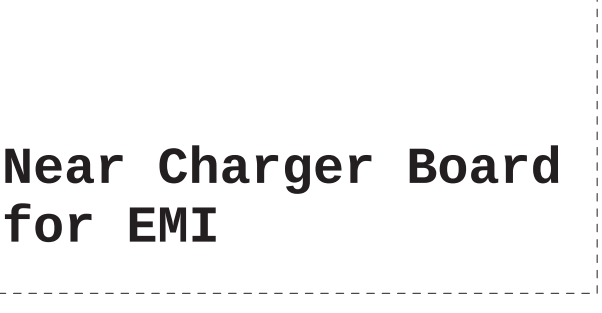
Near HDD



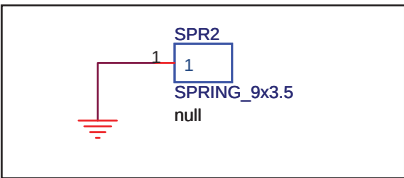
Function Board



Audio+USB Board



Near Charger Board
for EMI



2009.10.20
change SPR2 to 9 X3.5

1. Add S/D CARD test point for L6 TE request
TP736

2. Add MS CARD test point for L6 TE request
TP690, TP691, TP693, TP694, TP695, TP696, TP697
TP702, TP724, TP698, TP699, TP700, TP701, TP703

delete

3. Add I_LINK test point for L6 TE request
TP512, TP513, TP514,TP515

4. Add TOUCHPAD test point for L6 TE request
TP551, TP550, TP535, TP534 ,TP562, TP564

5.Delete R5893, R5887 and trace AC PRESENT,
add R6007 to +3VALW in page 11, delete trace AC PRESENT,
add test point TP186 in page 37. VespaCP use Ignition FW,
no ACPRESENT function.
Intel FAE suggest this pin can configure as GPIO.

6.change C6131 from NC_470P_16V_K to 0.047U_16V_K follow Intel suggest

7. Change trace (CLK-PCIE-EXPRESS#,CLK-PCIE-EXPRESS,EXPRESS-CLKREQ#) from
U134(AH42,AH41,A8) to (AJ50,AJ52,H6) for DVT1 express card can't detect issue.

8. Change page 70 from finger print to reserve, VespaCP no this function.

2009/0912

9. Delete R5785 0ohm resistor for voltage drop problem

10. Change RP82 from NC to mount for SI test
Change RP81 from mount to NC for SI test
Change RP86 from NC to mount for SI test

2009/0914

11.delete finger print

12.delete TP417,link to gnd

13.CN16 PIN 15 LINK TO GND
14.CN35: change 0ohm to 33ohm

15.PCH: GNT0# and GNT1# change from pull high to +3vsus to pull low to gnd

16.DC_IN: DELETE C_PQ9 ,C_PR34
change C_PR36,C_PR37 from NC to mount
C_PF1 change to 0437007.WR

17.+1.05V: change PC319 from Y5V to X5R

18. VHCORE: change OVT_EC# to PROCHOT#

20.other: add PD31
change PR275 from 10K to 4.7K

21.OVP: DELETE PR78 ,PQ17
change PC35, PU2, PC37, PR240, PR108,PR39,
PR36 from mount to NC

22.N11P-LP1+SANSUNG(H2) SKU and
N11M-GE1 +SANSUANG(M2 SKU)need change BOM
R5244 change from 1R-0004532-F200(45.3K) to
1R-0002492-F200(24.9K) for nVIDIA FAE suggest

2009.0918
23. CN11, CN18, CN34, CN9, CN12, A_CN7, A_CN5 change to Halogen Free

2009/09/19
1.Change A_USB_PN2/A_USB_PP2 to A_USB_PN4/A_USB_PP4
Change A_USB_VCC2 to A_USB_VCC4 in page 67

2. Change A_USB_PN2/A_USB_PP2 to A_USB_PN4/A_USB_PP4
Change A_USB_VCC2 to A_USB_VCC4
Change U_VD2+_F/U_VD2-_F to U_VD4+_F/U_VD4-_F in page 69

3.Change USB_VCC2 to USB_VCC4
Change USB_OC#0 to USB_OC#1 in page 48

4.Add USB_OC#1
Change USB_PN10/USB_PP10 to test point in page 13

5.Change USB_VCC2 to USB_VCC4 in page 43

2009.0921
Page 50
1.R531 Delete,then pull CN34 pin4 to GND.
2.Remove the Test point TP562 to +5VRUN.

2009.0922

1.change R5272,R5273 from NC to mount
2.add R5313 for 10K_J
3.change R5916 TO NC
4.change D15,D21,A_D7 TO mount and place them near connector
5.WIRELESS_DATA/WIRELESS_CHCLK change · please refere to page 49
6.ADD R5991 for 100K_J
7.change C476 TO NC_12P
8.change C1986 TO 12P
9.ADD R6010,R6011,R6012 to pull-down SPI0_CLK,SPI0_MOSI,SPI0_CS# in page 09
10.change CN25,CN29,CN30 TO Halogen Free
11.change D13,D11 TO 16-SSM22LL_PT00
12.change R5910,R5911 to NC_1K
13.DELETE TP498, TP491,TP490, TP495,TP494,TP509
14.CHANGE Q45 TO NC ,R5996 TO MOUNT
15.change CN21 TO 1N-1052000-0000 for ME request
16.change B0SS1,B0SS2 to 1M-1F40M20-1500 for ME request
17.page 57:change net PWRCNTL_0_R TO PWRCNTL_1_R
change net PWRCNTL_1_R TO PWRCNTL_0_R
change PR389,PR380 TO 110 ohm
change PC334 to 220P_16V_J 0402
change PC337 to 220P_50V_J 0402
delete PJ23,PJ24,PJ25,PJ26

18.page 53:delete PJ18,PJ19
19.page 56:delete PJ1,PJ2
20.page 58:delete PJ20,PJ21,PJ22
ADD PR367/0 ohm
21.page 59:delete PJ5
22.page 60:delete PJ3
23.page 06:delete PJ43

2009.0923
ADD test point TP490,TP491,TP494,TP495,TP498,TP509

2009.0925
ADD C6260 NC_1000P_16V_K

2009.0925
For EMI request
1.Add Cap.C36 0.1U,C999 1000PF on net +1_05V_VTT
2.Add Cap.C37,C38 0.1U on net +1_8VRUN
3.Add Cap. C39 0.1U,C1000 1000PF on net +3VRUN
4.Add Cap.C53,C54,C61 0.1U on net DCBATOUT
5.Add SPR2

2009.0925
ADD C70,C71,C72 10P for RF request

2009.0925
change C6156,C6157 from 12p to 15p for vendor request

2009.0925
change PR245,PC269,PR236,PC266,PR363,PC323,PR251,
PC252,PR233,PC232 from NC to mount for EMI request

2009.0926
For EMI request
1.Add PC62 0.1U on net +1_8V_LX ,place it near PQ72
2.change C539 from NC to 680P
3.Add C549 680P on net INV_BRADJ,place it near LVDS connector

2009.0928
For RF request
change C1264,C716,C532 to 47P

2009.0928
change R5376 to 100K follow design guide

2009.0928
change PC337 to 22P

2009.0928
Add Q7 for MOR request

2009.0929
Add PC206 NC_0.1U reserve for Return patch

2009.0929
change RP86 ,RP82 TO NC
change RP81 TO mount

2009.10.19
1.Change PC319 from 1C-2B20104-K301 To 1C-2B20104-K300.
2.change R5703 from 68ohm to 75 ohm
3 NC RP81 for 1R-1010000-JP00
4. MOUNT RP82, RP86 for 1R-1010000-JP00
5. change C5250 from 1C-2B20473-K300 to 1C-2B20102-K001
6. change C6256 from 1C-2B20102-K001 to 1C-2B20473-K300

2009.10.20
change SPR2 from 4x3 to 7x2.5

2009.10.22
PAGE37:delete C468, C513, U25, R76, R55, R41, R73, C60 (NC), TP871,
TP872,TP873,TP876,TP878,TP880,TP874.TP875,TP877,TP879,TP881,
TP882 for PVT
PAGE53:change PC112 from 68U to 47U for power request

2009.10.23
Page 35 : deleteJ2,J3
Page 38 : delete TP531,TP530,TP532,TP533,TP529,TP520,519,TP518
Page 05 : delete R5786
Page 37 : add TP690, TP690
PAGE 45,46:change net SD_WP# to SD_WP
Page 35 : Add test point TP897,TP898,TP899 for PVT

page 35 : add TP900,TP901 for +3VRUN

2009.10.28
page 57: Change PC344 to 1C-2B70226-M100.
Add PC345 1C-2B70226-M100.
Change PEX_VDD to 2.5A.

2009.10.30
page 55: Change C_PQ3,C_PQ8 to 17-2N7002W-0000.
page 59: Change PQ61 to 17-2N7002W-0000.

page 61: Change PQ58 to 17-2N7002S-PT00.

page 62: Change C_PQ7 to 17-2N7002S-PT00.
Change PQ10 to 17-2N7002W-0000.
Change PQ9 to 17-2N7002S-PT00.

Page 51:change R5992,R5993,R5994 from 120ohm to 549ohm follow M870

Page 36:change Q9 to 17-2N7002S-PT00.
Page 03:change Q179 to 17-2N7002S-PT00

Page 72 :change SPR2 to 9 X3.5

2009.10.31

page 57: Add PC350 1C-33U0337-KX00 NC_330U_2.5V_K.

Page 14 : add RP83 NC_0 to escape crosstalk

2009.11.3
Page60 : Change PC225 TO mount
page 60: Delete PC62.

page 60: Change PR229 to 1K_J.
Change PC225 to 0.22U_25V_K.

2009.11.03
Page 35:add C60,C62,C63,C64
For EMI request
1:Page 55 change C_PC14 to 4700pf
change C_PC13 to 0.1U
2: Page 55 change C_PC156 to 2200pf
3.Page 63 change A_C23,A_C22 from 15PF to 22PF

2009.11.4
Page 35:add C65,C66,C67,C73,C74 for FAN issue

page 55: Change C_EC6066 to 1C-2B30104-K000.

page 56: Add TP442.

page 56: Change E_C6060 to 1C-2B30104-K000.
Change E_C6059 to 1C-2B30104-K000.
Change E_C6067 to 1C-2B30104-K000.
Change E_C6068 to 1C-2B30104-K000.
Change E_C6062 to 1C-2B30104-K000.
Change E_C6061 to 1C-2B30104-K000.

2009.11.16
change C_PC14, C_PC156 to 1000P for EMI request

2009.11.19
Page49: Change R6009 from 1R-0000000-J200 to 1R-0000101-J200 for RF request

2009.11.19
Page 55: Add C_PQ26,C_PQ27,C_PQ9 NC_TPCC8102 for 2nd source.